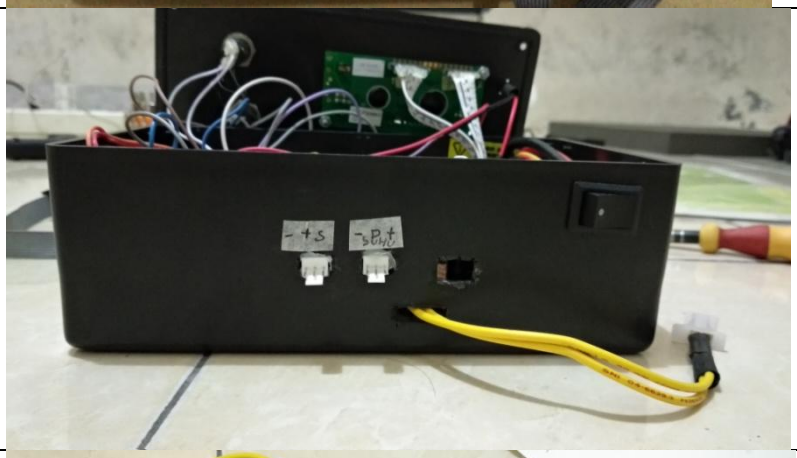
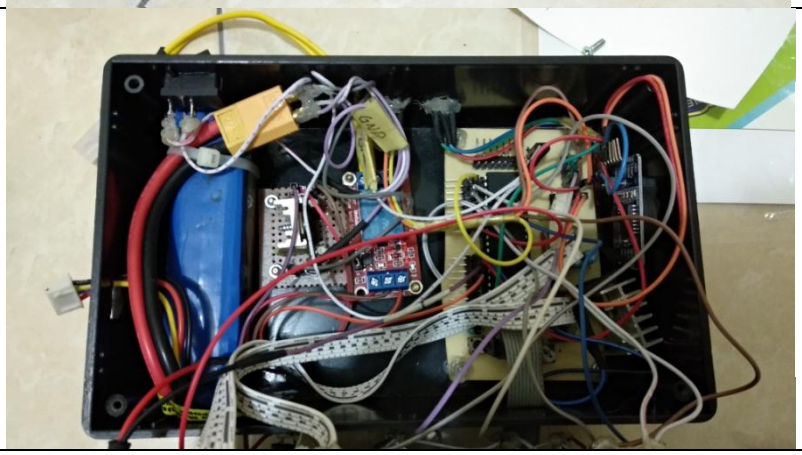
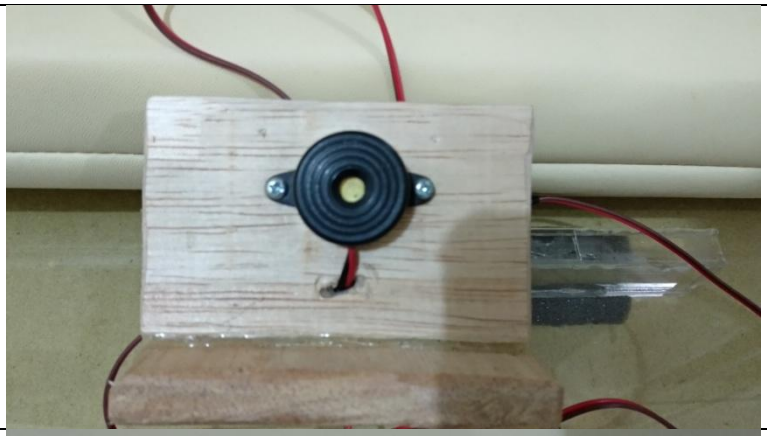
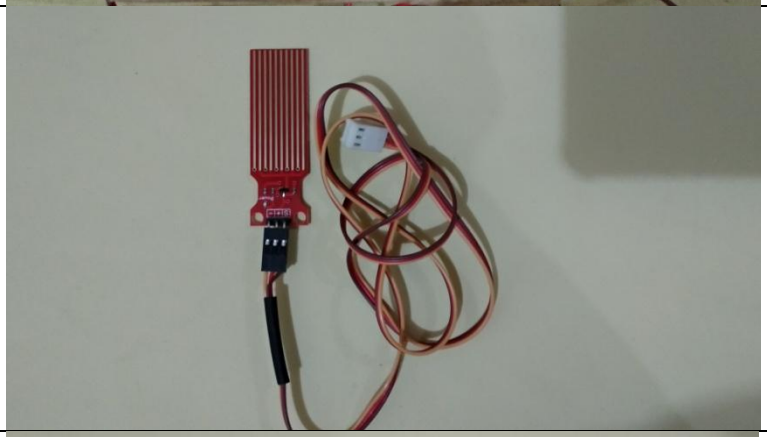
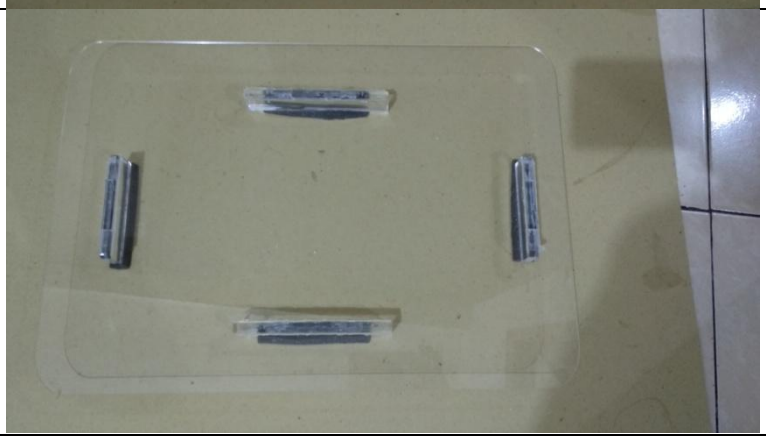
LAMPIRAN

Lampiran 1. Foto Alat

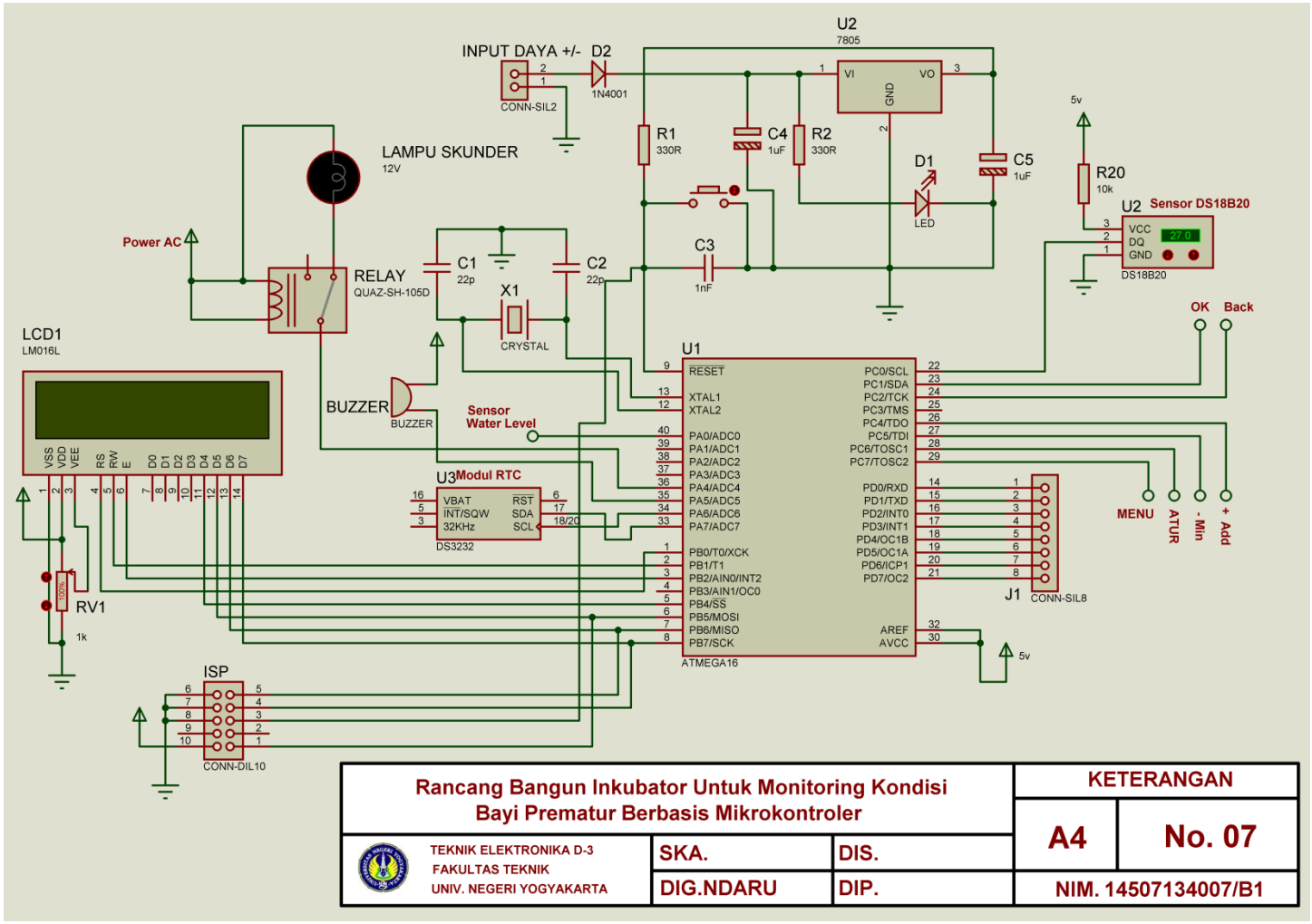
	Tampilan Depan Box Kontrol
	Tampilan Belakang Box Kontrol
	Tampilan Dalam Box Kontrol

	Buzzer
	Sensor Cairan
	Sensor Suhu DS18B20

	Tatakan Kayu dan Sekat Triplek
	Kasur Bayi
	Tatakan Kasur Bayi

	Desain Dalam Tatakan Kayu
	Lubang Udara
	Power AC, Fuse, Saklar ON/OFF

Lampiran 2. Skema Rangkaian



Lampiran 3. Progam Alat

```
/*****************************************************
This program was produced by the
CodeWizardAVR V2.05.0 Advanced
Automatic Program Generator
© Copyright 1998-2010 Pavel Haiduc, HP InfoTech s.r.l.
http://www.hpinfotech.com

Project :
Version :
Date    : 30/04/2016
Author  : www.Eca.ir *** www.Webkade.ir
Company :
Comments:


Chip type               : ATmega16
Program type            : Application
AVR Core Clock frequency: 16,000000 MHz
Memory model            : Small
External RAM size       : 0
Data Stack size         : 256
*****************************************************/

#include <mega16.h>
#include <delay.h>
#include <1wire.h>
#include <ds18b20.h>
#include <alcd.h>
#include <i2c.h>
#include <stdlib.h>
#include <string.h>
#include <ds1307.h>
#define MAX_DS1820 8
unsigned char ds18b20_devices;
unsigned char ds18b20_rom_codes[MAX_DS1820][9];
#include <stdio.h>
#define ADC_VREF_TYPE 0x20

#define s2 PINC.1 //select
#define s4 PINC.2 //back
#define s6 PINC.4 //-
#define s5 PINC.5 //+
#define s3 PINC.6 //atur
#define s1 PINC.7 //menu

unsigned char read_adc(unsigned char adc_input)
{
ADMUX=adc_input | (ADC_VREF_TYPE & 0xff);
```

```
// Delay needed for the stabilization of the ADC input
voltage
delay_us(10);
// Start the AD conversion
ADCSRA|=0x40;
// Wait for the AD conversion to complete
while ((ADCSRA & 0x10)==0);
ADCSRA|=0x10;
return ADCH;
}

float temp;
unsigned char i;   // variabel yang digunakan
float dadc,dadc1;
unsigned char jam,menit,detik;
char buff[33],buffer[33];
eeprom unsigned char ea=0,em=0;
int x,nol,satu,dua,sjam,smenit,sdetik,var,var1,var2;

int baca(char x)
{
dadc1 = read_adc(x);
dadc = (float) dadc1*5/255;        // baca adc
return dadc;
}

void baca_rtc()
{
rtc_get_time(&jam,&menit,&detik);  // baca adc
}

void ceksensor()
{
lcd_clear();
while(1){
if(!s3){x++;delay_ms(200);}       // baca sensor cairan
if(x>0)x=0;
if(x==0){

nol=read_adc(0);
lcd_gotoxy(0,0);
sprintf(buff,"0: %d ",nol);
lcd_puts(buff);
delay_ms(100);

satu=read_adc(1);
lcd_gotoxy(0,1);
sprintf(buffer,"1: %d ",satu);
lcd_puts(buffer);
delay_ms(100);
```

```
dua=read_adc(2); delay_ms(100);
lcd_gotoxy(10,0);
sprintf(buff,"2: %d ",dua);
lcd_puts(buff);
}
if(!s4){delay_ms(300);
lcd_clear();
break;
}
}
}


void set_suhu(){
lcd_clear();
while(1){
if(!s3){x++;delay_ms(300);}
if(x>60)x=0;                          // seting nilai suhu
if(x<0)x=60; {

lcd_gotoxy(0,0);
sprintf(buff, "Set Suhu : %d", var);
lcd_puts(buff);
if(!s5){var++;delay_ms(200);}
if(!s6){var--;delay_ms(200);}
if(var<0)var=0;
if(var>60)var=0;
}

if(!s4){delay_ms(300);
lcd_clear();
break;
}
}
}

void set_jam()
{
sjam=jam;
smenit=menit;
sdetik=detik;
while(1){
rtc_set_time(sjam,smenit,sdetik);
if(!s3){x++;delay_ms(300);}       // seting waktu
if(x>2)x=0;

if(x==0){
lcd_gotoxy(0,0);
lcd_putsf("Set Jam         ");
```

```
lcd_gotoxy(0,1);
sprintf(buff,"  [%02d]:%02d:%02d   ",sjam,smenit,sdetik);
lcd_puts(buff);
if(!s5){sjam++;delay_ms(200);}
if(!s6){sjam--;delay_ms(200);}
if(sjam>23)sjam=0;
if(sjam<0)sjam=23;
}
if(x==1){
lcd_gotoxy(0,0);
lcd_putsf("Set Menit       ");
lcd_gotoxy(0,1);
sprintf(buff,"  %02d:[%02d]:%02d   ",sjam,smenit,sdetik);
lcd_puts(buff);
if(!s5){smenit++;delay_ms(200);}
if(!s6){smenit--;delay_ms(200);}
if(smenit>59)smenit=0;
if(smenit<0)smenit=59;
}
if(x==2){
lcd_gotoxy(0,0);
lcd_putsf("Set Detik       ");
lcd_gotoxy(0,1);
sprintf(buff,"  %02d:%02d:[%02d]   ",sjam,smenit,sdetik);
lcd_puts(buff);
if(!s5){sdetik++;delay_ms(200);}
if(!s6){sdetik--;delay_ms(200);}
if(sdetik>59)sdetik=0;
if(sdetik<0)sdetik=59;
}
if(!s4){delay_ms(300);break;}
}
}

void set_alarm(){
lcd_clear();
while(1){
if(!s3){x++;delay_ms(300);}       // seting alarm
if(x>1)x=0;

if(x==0){
lcd_gotoxy(0,0);
sprintf(buff,"[%d]:%d  ",var1,var2);
lcd_puts(buff);              // seting input waktu alarm
if(!s5){var1++;delay_ms(200);}
if(!s6){var1--;delay_ms(200);}
if(var1>24)var1=0;
if(var1<0)var1=0;
}
```

```
if(x==1){
lcd_gotoxy(0,0);
sprintf(buff,"%d:[%d]  ",var1,var2);
lcd_puts(buff);
if(!s5){var2++;delay_ms(200);// seting input waktu alarm
if(!s6){var2--;delay_ms(200);}
if(var2>59)var2=0;
if(var2<0)var2=59;
}

if(!s4){delay_ms(300);
lcd_clear();
break;
}
}
}

/*****************************************************
*******************/
void setting()
{
while(1){
if(!s3){x++;delay_ms(300);}
if(x>3)x=0;
if(x==0){
lcd_gotoxy(0,0);
lcd_putsf("> Set Jam       ");
lcd_gotoxy(0,1);
lcd_putsf("Set Suhu        ");
if(!s2){delay_ms(300);set_jam();}
}

if(x==1){
lcd_gotoxy(0,0);
lcd_putsf("Set Jam         ");
lcd_gotoxy(0,1);            // tampilan menu pada LCD
lcd_putsf("> Set Suhu      ");
if(!s2){delay_ms(300);set_suhu();}
}
if(x==2){
lcd_gotoxy(0,0);
lcd_putsf("> Set Alarm      ");
lcd_gotoxy(0,1);
lcd_putsf("Cek Sensor      ");
if(!s2){delay_ms(300);set_alarm();}
}
if(x==3){
lcd_gotoxy(0,0);
lcd_putsf("Set Alarm        ");
lcd_gotoxy(0,1);
```

```
lcd_putsf("> Cek Sensor    ");
if(!s2){delay_ms(300);ceksensor();}
}
if(!s4){
delay_ms(300);
lcd_clear();
break;
}
}
}
/*****************************************************
*******************/

void main(void)
{
PORTA=0x00;
DDRA=0x00;
PORTB=0x00;
DDRB=0xff;
PORTC=0xff;
DDRC=0x00;
PORTD=0xF8;
DDRD=0x00;
TCCR0=0x00;
TCNT0=0x00;
OCR0=0x00;

TCCR1A=0xA1;
TCCR1B=0x03;
TCNT1H=0x00;
TCNT1L=0x00;

ICR1H=0x00;
ICR1L=0x00;
OCR1AH=0x00;
OCR1AL=0x00;
OCR1BH=0x00;
OCR1BL=0x00;
ASSR=0x00;
TCCR2=0x00;
TCNT2=0x00;
OCR2=0x00;
MCUCR=0x00;
MCUCSR=0x00;

// Timer(s)/Counter(s) Interrupt(s) initialization
TIMSK=0x00;
UCSRA=0x00;
UCSRB=0x18;
UCSRC=0x86;
```

```
UBRRH=0x00;
UBRRL=0x67;
ACSR=0x80;
SFIOR=0x00;

ADMUX=ADC_VREF_TYPE & 0xff;
ADCSRA=0xA4;
SFIOR&=0x1F;

SPCR=0x00;

TWCR=0x00;

lcd_init(16);

//rtc_set_time(14,8,00);

lcd_gotoxy(0,0);
lcd_putsf("Wait..");
delay_ms(100);
w1_init();
ds18b20_devices=w1_search(0xf0,ds18b20_rom_codes);
lcd_clear();

goto next;
exit:
setting();
next:

PORTA.5=1;         // output  buzzer
DDRA.5=1;          // output buzzer
DDRA.4=1;            //output relay
PORTA.4=1;          // output relay

while (1)
      {
      if(!s1){delay_ms(300);goto exit;}
      baca_rtc();
      delay_ms(100);
      nol=read_adc(0);         // baca nilai suhu
      delay_ms(100);
      dua=read_adc(2);
      delay_ms(50);

      if(detik%3==0){
      for(i=0;i<ds18b20_devices;i++)
        {
        temp=ds18b20_temperature(ds18b20_rom_codes[i]);
        if(temp<var)PORTA.4=0; //relay off >> lampu on
        if(temp>var)PORTA.4=1; //relay on >> lampu mati
```

```
        }
      for (i=0;i<8;i++)
        {
        baca(i);
        }
      }

      if(PINC.2==0){ea=jam;      ea=ea+var;      em=menit;
em=em+var2;
        lcd_gotoxy(0,1);
lcd_putsf("Saved");delay_ms(200); lcd_clear();}
      if(jam==ea  &&  menit==em)  PORTA.5=0;  //buzzer  on
// seting alarm
      if(PINC.6==0){ea=0; em=0; PORTA.5=1;
        lcd_gotoxy(0,1);
lcd_putsf("Clear");delay_ms(200); lcd_clear();}

      lcd_gotoxy(0,0);
      sprintf(buff,"%02d:%02d:%02d ",jam,menit,detik);
      lcd_puts(buff);

      lcd_gotoxy(10,0);
      sprintf(buff,"%0.1fc ",temp);
      lcd_puts(buff);
      if(temp<var)PORTA.4=0;     // lampu masih menyala
      if(temp>var)PORTA.4=1;         //lampu mati
      lcd_gotoxy(10,1);
      lcd_putsf("[MENU]");

      if(nol>51){nol=read_adc(0);  //  progam  baca  sensor
cairan  on
        lcd_gotoxy(0,1);
        lcd_putsf("NGOMPOL");
        PORTA.5=0;  // buzzer on
        }
        if(nol<10){nol=read_adc(0);        // progam baca
sensor cairan off
        lcd_gotoxy(0,1);
        lcd_putsf("        ");
        PORTA.5=1;  //off
        }
      if(PINC.6==0){PORTA.5=1;}  //off manual buzzer
      ////////////////////////////////////////////////
      ////////////////////////////////////////////////
      }
      }
```

Lampiran 4. *Datasheet* ATMega16

Features

- High-performance, Low-power AVR® 8-bit Microcontroller
- Advanced RISC Architecture
  - 131 Powerful Instructions – Most Single-clock Cycle Execution
  - 32 x 8 General Purpose Working Registers
  - Fully Static Operation
  - Up to 16 MIPS Throughput at 16 MHz
  - On-chip 2-cycle Multiplier
- Nonvolatile Program and Data Memories
  - 16K Bytes of In-System Self-Programmable Flash
    Endurance: 10,000 Write/Erase Cycles
  - Optional Boot Code Section with Independent Lock Bits
    In-System Programming by On-chip Boot Program
    True Read-While-Write Operation
  - 512 Bytes EEPROM
    Endurance: 100,000 Write/Erase Cycles
  - 1K Byte Internal SRAM
  - Programming Lock for Software Security
- JTAG (IEEE std. 1149.1 Compliant) Interface
  - Boundary-scan Capabilities According to the JTAG Standard
  - Extensive On-chip Debug Support
  - Programming of Flash, EEPROM, Fuses, and Lock Bits through the JTAG Interface
- Peripheral Features
  - Two 8-bit Timer/Counters with Separate Prescalers and Compare Modes
  - One 16-bit Timer/Counter with Separate Prescaler, Compare Mode, and Capture Mode
  - Real Time Counter with Separate Oscillator
  - Four PWM Channels
  - 8-channel, 10-bit ADC
    8 Single-ended Channels
    7 Differential Channels in TQFP Package Only
    2 Differential Channels with Programmable Gain at 1x, 10x, or 200x
  - Byte-oriented Two-wire Serial Interface
  - Programmable Serial USART
  - Master/Slave SPI Serial Interface
  - Programmable Watchdog Timer with Separate On-chip Oscillator
  - On-chip Analog Comparator
- Special Microcontroller Features
  - Power-on Reset and Programmable Brown-out Detection
  - Internal Calibrated RC Oscillator
  - External and Internal Interrupt Sources
  - Six Sleep Modes: Idle, ADC Noise Reduction, Power-save, Power-down, Standby and Extended Standby
- I/O and Packages
  - 32 Programmable I/O Lines
  - 40-pin PDIP, 44-lead TQFP, and 44-pad MLF
- Operating Voltages
  - 2.7 - 5.5V for ATmega16L
  - 4.5 - 5.5V for ATmega16
- Speed Grades
  - 0 - 8 MHz for ATmega16L
  - 0 - 16 MHz for ATmega16
- Power Consumption @ 1 MHz, 3V, and 25°C for ATmega16L
  - Active: 1.1 mA
  - Idle Mode: 0.35 mA
  - Power-down Mode: < 1 µA

8-bit AVR® Microcontroller with 16K Bytes In-System Programmable Flash

ATmega16
ATmega16L

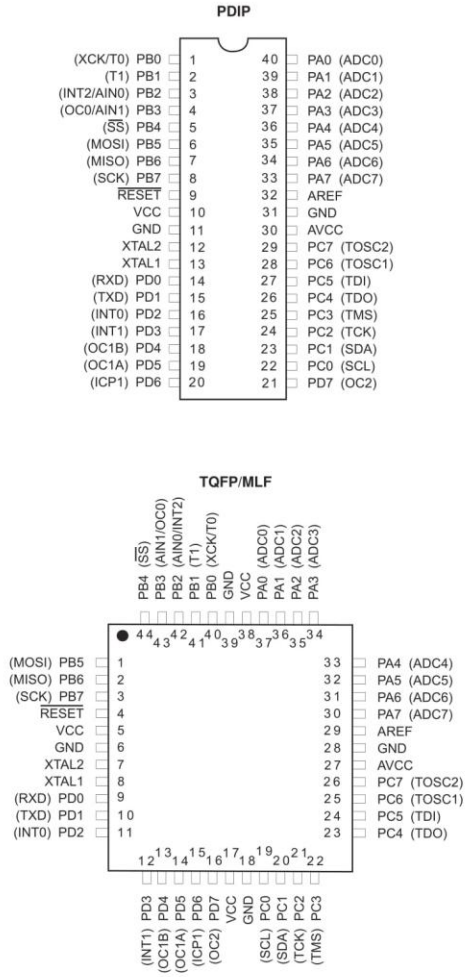
Summary

2466HS–AVR–12/03

Note: This is a summary document. A complete document is available on our Web site at www.atmel.com.

Pin Configurations

Figure 1. Pinouts ATmega16



Disclaimer

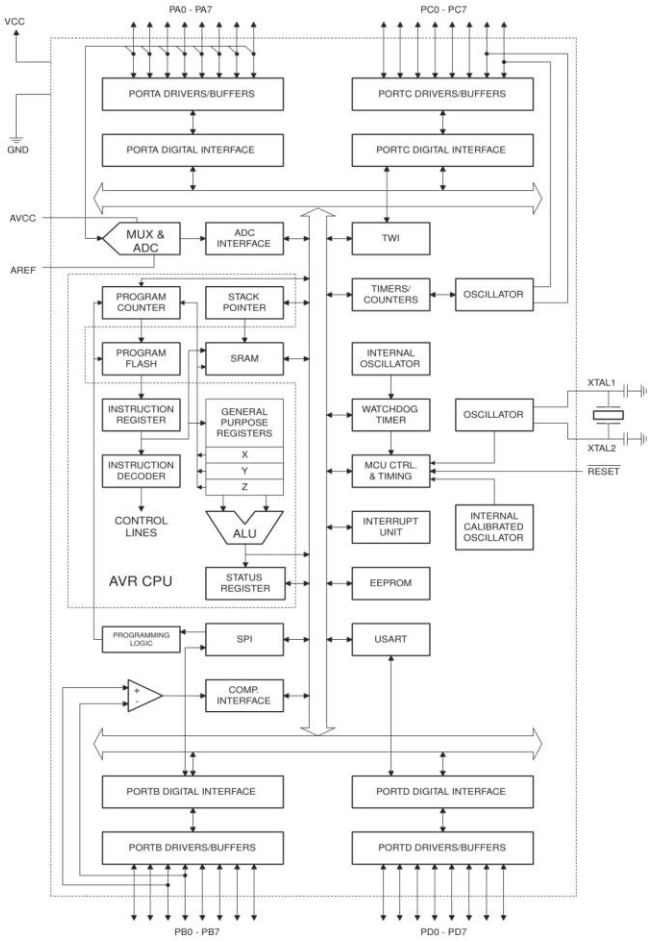
Typical values contained in this datasheet are based on simulations and characterization of other AVR microcontrollers manufactured on the same process technology. Min and Max values will be available after the device is characterized.

Overview

The ATmega16 is a low-power CMOS 8-bit microcontroller based on the AVR enhanced RISC architecture. By executing powerful instructions in a single clock cycle, the ATmega16 achieves throughputs approaching 1 MIPS per MHz allowing the system designer to optimize power consumption versus processing speed.

Block Diagram

Figure 2. Block Diagram



The AVR core combines a rich instruction set with 32 general purpose working registers. All the 32 registers are directly connected to the Arithmetic Logic Unit (ALU), allowing two independent registers to be accessed in one single instruction executed in one clock cycle. The resulting architecture is more code efficient while achieving throughputs up to ten times faster than conventional CISC microcontrollers.

The ATmega16 provides the following features: 16K bytes of In-System Programmable Flash Program memory with Read-While-Write capabilities, 512 bytes EEPROM, 1K byte SRAM, 32 general purpose I/O lines, 32 general purpose working registers, a JTAG interface for Boundary-scan, On-chip Debugging support and programming, three flexible Timer/Counters with compare modes, Internal and External Interrupts, a serial programmable USART, a byte oriented Two-wire Serial Interface, an 8-channel, 10-bit ADC with optional differential input stage with programmable gain (TQFP package only), a programmable Watchdog Timer with Internal Oscillator, an SPI serial port, and six software selectable power saving modes. The Idle mode stops the CPU while allowing the USART, Two-wire interface, A/D Converter, SRAM, Timer/Counters, SPI port, and interrupt system to continue functioning. The Power-down mode saves the register contents but freezes the Oscillator, disabling all other chip functions until the next External Interrupt or Hardware Reset. In Power-save mode, the Asynchronous Timer continues to run, allowing the user to maintain a timer base while the rest of the device is sleeping. The ADC Noise Reduction mode stops the CPU and all I/O modules except Asynchronous Timer and ADC, to minimize switching noise during ADC conversions. In Standby mode, the crystal/resonator Oscillator is running while the rest of the device is sleeping. This allows very fast start-up combined with low-power consumption. In Extended Standby mode, both the main Oscillator and the Asynchronous Timer continue to run.

The device is manufactured using Atmel's high density nonvolatile memory technology. The On-chip ISP Flash allows the program memory to be reprogrammed in-system through an SPI serial interface, by a conventional nonvolatile memory programmer, or by an On-chip Boot program running on the AVR core. The boot program can use any interface to download the application program in the Application Flash memory. Software in the Boot Flash section will continue to run while the Application Flash section is updated, providing true Read-While-Write operation. By combining an 8-bit RISC CPU with In-System Self-Programmable Flash on a monolithic chip, the Atmel ATmega16 is a powerful microcontroller that provides a highly-flexible and cost-effective solution to many embedded control applications.

The ATmega16 AVR is supported with a full suite of program and system development tools including: C compilers, macro assemblers, program debugger/simulators, in-circuit emulators, and evaluation kits.

Pin Descriptions

VCC

Digital supply voltage.

GND

Ground.

Port A (PA7..PA0)

Port A serves as the analog inputs to the A/D Converter.

Port A also serves as an 8-bit bi-directional I/O port, if the A/D Converter is not used. Port pins can provide internal pull-up resistors (selected for each bit). The Port A output buffers have symmetrical drive characteristics with both high sink and source capability. When pins PA0 to PA7 are used as inputs and are externally pulled low, they will source current if the internal pull-up resistors are activated. The Port A pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port B (PB7..PB0)

Port B is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port B output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port B pins that are externally pulled low will source current if the pull-up resistors are activated. The Port B pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port B also serves the functions of various special features of the ATmega16 as listed on page 56.

Port C (PC7..PC0)

Port C is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port C output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port C pins that are externally pulled low will source current if the pull-up resistors are activated. The Port C pins are tri-stated when a reset condition becomes active, even if the clock is not running. If the JTAG interface is enabled, the pull-up resistors on pins PC5(TDI), PC3(TMS) and PC2(TCK) will be activated even if a reset occurs.

Port C also serves the functions of the JTAG interface and other special features of the ATmega16 as listed on page 59.

Port D (PD7..PD0)

Port D is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port D output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port D pins that are externally pulled low will source current if the pull-up resistors are activated. The Port D pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port D also serves the functions of various special features of the ATmega16 as listed on page 61.

$\overline{\text{RESET}}$

Reset Input. A low level on this pin for longer than the minimum pulse length will generate a reset, even if the clock is not running. The minimum pulse length is given in Table 15 on page 36. Shorter pulses are not guaranteed to generate a reset.

XTAL1

Input to the inverting Oscillator amplifier and input to the internal clock operating circuit.

XTAL2

Output from the inverting Oscillator amplifier.

AVCC

AVCC is the supply voltage pin for Port A and the A/D Converter. It should be externally connected to V_{CC}, even if the ADC is not used. If the ADC is used, it should be connected to V_{CC} through a low-pass filter.

AREF

AREF is the analog reference pin for the A/D Converter.

Register Summary

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Page
$3F ($5F)	SREG	I	T	H	S	V	N	Z	C	7
$3E ($5E)	SPH	–	–	–	–	–	SP10	SP9	SP8	10
$3D ($5D)	SPL	SP7	SP6	SP5	SP4	SP3	SP2	SP1	SP0	10
$3C ($5C)	OCR0	Timer/Counter0 Output Compare Register								83
$3B ($5B)	GICR	INT1	INT0	INT2	–	–	–	IVSEL	IVCE	46, 67
$3A ($5A)	GIFR	INTF1	INTF0	INTF2	–	–	–	–	–	68
$39 ($59)	TIMSK	OCIE2	TOIE2	TICIE1	OCIE1A	OCIE1B	TOIE1	OCIE0	TOIE0	83, 114, 132
$38 ($58)	TIFR	OCF2	TOV2	ICF1	OCF1A	OCF1B	TOV1	OCF0	TOV0	84, 115, 132
$37 ($57)	SPMCR	SPMIE	RWWSB	–	RWWSRE	BLBSET	PGWRT	PGERS	SPMEN	249
$36 ($56)	TWCR	TWINT	TWEA	TWSTA	TWSTO	TWWC	TWEN	–	TWIE	178
$35 ($55)	MCUCR	SM2	SE	SM1	SM0	ISC11	ISC10	ISC01	ISC00	30, 66
$34 ($54)	MCUCSR	JTD	ISC2	–	JTRF	WDRF	BORF	EXTRF	PORF	39, 67, 229
$33 ($53)	TCCR0	FOC0	WGM00	COM01	COM00	WGM01	CS02	CS01	CS00	81
$32 ($52)	TCNT0	Timer/Counter0 (8 Bits)								83
$31[1] ($51)[1]	OSCCAL	Oscillator Calibration Register								28
	OCDR	On-Chip Debug Register								225
$30 ($50)	SFIOR	ADTS2	ADTS1	ADTS0	–	ACME	PUD	PSR2	PSR10	55,86,133,199,219
$2F ($4F)	TCCR1A	COM1A1	COM1A0	COM1B1	COM1B0	FOC1A	FOC1B	WGM11	WGM10	109
$2E ($4E)	TCCR1B	ICNC1	ICES1	–	WGM13	WGM12	CS12	CS11	CS10	112
$2D ($4D)	TCNT1H	Timer/Counter1 – Counter Register High Byte								113
$2C ($4C)	TCNT1L	Timer/Counter1 – Counter Register Low Byte								113
$2B ($4B)	OCR1AH	Timer/Counter1 – Output Compare Register A High Byte								113
$2A ($4A)	OCR1AL	Timer/Counter1 – Output Compare Register A Low Byte								113
$29 ($49)	OCR1BH	Timer/Counter1 – Output Compare Register B High Byte								113
$28 ($48)	OCR1BL	Timer/Counter1 – Output Compare Register B Low Byte								113
$27 ($47)	ICR1H	Timer/Counter1 – Input Capture Register High Byte								114
$26 ($46)	ICR1L	Timer/Counter1 – Input Capture Register Low Byte								114
$25 ($45)	TCCR2	FOC2	WGM20	COM21	COM20	WGM21	CS22	CS21	CS20	127
$24 ($44)	TCNT2	Timer/Counter2 (8 Bits)								129
$23 ($43)	OCR2	Timer/Counter2 Output Compare Register								129
$22 ($42)	ASSR	–	–	–	–	AS2	TCN2UB	OCR2UB	TCR2UB	130
$21 ($41)	WDTCR	–	–	–	WDTOE	WDE	WDP2	WDP1	WDP0	41
$20[2] ($40)[2]	UBRRH	URSEL	–	–	–	UBRR[11:8]				165
	UCSRC	URSEL	UMSEL	UPM1	UPM0	USBS	UCSZ1	UCSZ0	UCPOL	164
$1F ($3F)	EEARH	–	–	–	–	–	–	–	EEAR8	17
$1E ($3E)	EEARL	EEPROM Address Register Low Byte								17
$1D ($3D)	EEDR	EEPROM Data Register								17
$1C ($3C)	EECR	–	–	–	–	EERIE	EEMWE	EEWE	EERE	17
$1B ($3B)	PORTA	PORTA7	PORTA6	PORTA5	PORTA4	PORTA3	PORTA2	PORTA1	PORTA0	64
$1A ($3A)	DDRA	DDA7	DDA6	DDA5	DDA4	DDA3	DDA2	DDA1	DDA0	64
$19 ($39)	PINA	PINA7	PINA6	PINA5	PINA4	PINA3	PINA2	PINA1	PINA0	64
$18 ($38)	PORTB	PORTB7	PORTB6	PORTB5	PORTB4	PORTB3	PORTB2	PORTB1	PORTB0	64
$17 ($37)	DDRB	DDB7	DDB6	DDB5	DDB4	DDB3	DDB2	DDB1	DDB0	64
$16 ($36)	PINB	PINB7	PINB6	PINB5	PINB4	PINB3	PINB2	PINB1	PINB0	64
$15 ($35)	PORTC	PORTC7	PORTC6	PORTC5	PORTC4	PORTC3	PORTC2	PORTC1	PORTC0	65
$14 ($34)	DDRC	DDC7	DDC6	DDC5	DDC4	DDC3	DDC2	DDC1	DDC0	65
$13 ($33)	PINC	PINC7	PINC6	PINC5	PINC4	PINC3	PINC2	PINC1	PINC0	65
$12 ($32)	PORTD	PORTD7	PORTD6	PORTD5	PORTD4	PORTD3	PORTD2	PORTD1	PORTD0	65
$11 ($31)	DDRD	DDD7	DDD6	DDD5	DDD4	DDD3	DDD2	DDD1	DDD0	65
$10 ($30)	PIND	PIND7	PIND6	PIND5	PIND4	PIND3	PIND2	PIND1	PIND0	65
$0F ($2F)	SPDR	SPI Data Register								140
$0E ($2E)	SPSR	SPIF	WCOL	–	–	–	–	–	SPI2X	140
$0D ($2D)	SPCR	SPIE	SPE	DORD	MSTR	CPOL	CPHA	SPR1	SPR0	138
$0C ($2C)	UDR	USART I/O Data Register								161
$0B ($2B)	UCSRA	RXC	TXC	UDRE	FE	DOR	PE	U2X	MPCM	162
$0A ($2A)	UCSRB	RXCIE	TXCIE	UDRIE	RXEN	TXEN	UCSZ2	RXB8	TXB8	163
$09 ($29)	UBRRL	USART Baud Rate Register Low Byte								165
$08 ($28)	ACSR	ACD	ACBG	ACO	ACI	ACIE	ACIC	ACIS1	ACIS0	200
$07 ($27)	ADMUX	REFS1	REFS0	ADLAR	MUX4	MUX3	MUX2	MUX1	MUX0	215
$06 ($26)	ADCSRA	ADEN	ADSC	ADATE	ADIF	ADIE	ADPS2	ADPS1	ADPS0	217
$05 ($25)	ADCH	ADC Data Register High Byte								218
$04 ($24)	ADCL	ADC Data Register Low Byte								218
$03 ($23)	TWDR	Two-wire Serial Interface Data Register								180
$02 ($22)	TWAR	TWA6	TWA5	TWA4	TWA3	TWA2	TWA1	TWA0	TWGCE	180

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Page
$01 ($21)	TWSR	TWS7	TWS6	TWS5	TWS4	TWS3	–	TWPS1	TWPS0	179
$00 ($20)	TWBR	Two-wire Serial Interface Bit Rate Register								178

Notes:
1. When the OCDEN Fuse is unprogrammed, the OSCCAL Register is always accessed on this address. Refer to the debugger specific documentation for details on how to use the OCDR Register.
2. Refer to the USART description for details on how to access UBRRH and UCSRC.
3. For compatibility with future devices, reserved bits should be written to zero if accessed. Reserved I/O memory addresses should never be written.
4. Some of the Status Flags are cleared by writing a logical one to them. Note that the CBI and SBI instructions will operate on all bits in the I/O Register, writing a one back into any flag read as set, thus clearing the flag. The CBI and SBI instructions work with registers $00 to $1F only.

Instruction Set Summary

Mnemonics	Operands	Description	Operation	Flags	#Clocks
ARITHMETIC AND LOGIC INSTRUCTIONS					
ADD	Rd, Rr	Add two Registers	Rd ← Rd + Rr	Z,C,N,V,H	1
ADC	Rd, Rr	Add with Carry two Registers	Rd ← Rd + Rr + C	Z,C,N,V,H	1
ADIW	Rdl,K	Add Immediate to Word	Rdh:Rdl ← Rdh:Rdl + K	Z,C,N,V,S	2
SUB	Rd, Rr	Subtract two Registers	Rd ← Rd - Rr	Z,C,N,V,H	1
SUBI	Rd, K	Subtract Constant from Register	Rd ← Rd - K	Z,C,N,V,H	1
SBC	Rd, Rr	Subtract with Carry two Registers	Rd ← Rd - Rr - C	Z,C,N,V,H	1
SBCI	Rd, K	Subtract with Carry Constant from Reg.	Rd ← Rd - K - C	Z,C,N,V,H	1
SBIW	Rdl,K	Subtract Immediate from Word	Rdh:Rdl ← Rdh:Rdl - K	Z,C,N,V,S	2
AND	Rd, Rr	Logical AND Registers	Rd ← Rd • Rr	Z,N,V	1
ANDI	Rd, K	Logical AND Register and Constant	Rd ← Rd • K	Z,N,V	1
OR	Rd, Rr	Logical OR Registers	Rd ← Rd v Rr	Z,N,V	1
ORI	Rd, K	Logical OR Register and Constant	Rd ← Rd v K	Z,N,V	1
EOR	Rd, Rr	Exclusive OR Registers	Rd ← Rd ⊕ Rr	Z,N,V	1
COM	Rd	One's Complement	Rd ← $FF − Rd	Z,C,N,V	1
NEG	Rd	Two's Complement	Rd ← $00 − Rd	Z,C,N,V,H	1
SBR	Rd,K	Set Bit(s) in Register	Rd ← Rd v K	Z,N,V	1
CBR	Rd,K	Clear Bit(s) in Register	Rd ← Rd • ($FF - K)	Z,N,V	1
INC	Rd	Increment	Rd ← Rd + 1	Z,N,V	1
DEC	Rd	Decrement	Rd ← Rd − 1	Z,N,V	1
TST	Rd	Test for Zero or Minus	Rd ← Rd • Rd	Z,N,V	1
CLR	Rd	Clear Register	Rd ← Rd ⊕ Rd	Z,N,V	1
SER	Rd	Set Register	Rd ← $FF	None	1
MUL	Rd, Rr	Multiply Unsigned	R1:R0 ← Rd x Rr	Z,C	2
MULS	Rd, Rr	Multiply Signed	R1:R0 ← Rd x Rr	Z,C	2
MULSU	Rd, Rr	Multiply Signed with Unsigned	R1:R0 ← Rd x Rr	Z,C	2
FMUL	Rd, Rr	Fractional Multiply Unsigned	R1:R0 ← (Rd x Rr) << 1	Z,C	2
FMULS	Rd, Rr	Fractional Multiply Signed	R1:R0 ← (Rd x Rr) << 1	Z,C	2
FMULSU	Rd, Rr	Fractional Multiply Signed with Unsigned	R1:R0 ← (Rd x Rr) << 1	Z,C	2
BRANCH INSTRUCTIONS					
RJMP	k	Relative Jump	PC ← PC + k + 1	None	2
IJMP		Indirect Jump to (Z)	PC ← Z	None	2
JMP	k	Direct Jump	PC ← k	None	3
RCALL	k	Relative Subroutine Call	PC ← PC + k + 1	None	3
ICALL		Indirect Call to (Z)	PC ← Z	None	3
CALL	k	Direct Subroutine Call	PC ← k	None	4
RET		Subroutine Return	PC ← STACK	None	4
RETI		Interrupt Return	PC ← STACK	I	4
CPSE	Rd,Rr	Compare, Skip if Equal	if (Rd = Rr) PC ← PC + 2 or 3	None	1 / 2 / 3
CP	Rd,Rr	Compare	Rd − Rr	Z, N,V,C,H	1
CPC	Rd,Rr	Compare with Carry	Rd − Rr − C	Z, N,V,C,H	1
CPI	Rd,K	Compare Register with Immediate	Rd − K	Z, N,V,C,H	1
SBRC	Rr, b	Skip if Bit in Register Cleared	if (Rr(b)=0) PC ← PC + 2 or 3	None	1 / 2 / 3
SBRS	Rr, b	Skip if Bit in Register is Set	if (Rr(b)=1) PC ← PC + 2 or 3	None	1 / 2 / 3
SBIC	P, b	Skip if Bit in I/O Register Cleared	if (P(b)=0) PC ← PC + 2 or 3	None	1 / 2 / 3
SBIS	P, b	Skip if Bit in I/O Register is Set	if (P(b)=1) PC ← PC + 2 or 3	None	1 / 2 / 3
BRBS	s, k	Branch if Status Flag Set	if (SREG(s) = 1) then PC←PC+k + 1	None	1 / 2
BRBC	s, k	Branch if Status Flag Cleared	if (SREG(s) = 0) then PC←PC+k + 1	None	1 / 2
BREQ	k	Branch if Equal	if (Z = 1) then PC ← PC + k + 1	None	1 / 2
BRNE	k	Branch if Not Equal	if (Z = 0) then PC ← PC + k + 1	None	1 / 2
BRCS	k	Branch if Carry Set	if (C = 1) then PC ← PC + k + 1	None	1 / 2
BRCC	k	Branch if Carry Cleared	if (C = 0) then PC ← PC + k + 1	None	1 / 2
BRSH	k	Branch if Same or Higher	if (C = 0) then PC ← PC + k + 1	None	1 / 2
BRLO	k	Branch if Lower	if (C = 1) then PC ← PC + k + 1	None	1 / 2
BRMI	k	Branch if Minus	if (N = 1) then PC ← PC + k + 1	None	1 / 2
BRPL	k	Branch if Plus	if (N = 0) then PC ← PC + k + 1	None	1 / 2
BRGE	k	Branch if Greater or Equal, Signed	if (N ⊕ V= 0) then PC ← PC + k + 1	None	1 / 2
BRLT	k	Branch if Less Than Zero, Signed	if (N ⊕ V= 1) then PC ← PC + k + 1	None	1 / 2
BRHS	k	Branch if Half Carry Flag Set	if (H = 1) then PC ← PC + k + 1	None	1 / 2
BRHC	k	Branch if Half Carry Flag Cleared	if (H = 0) then PC ← PC + k + 1	None	1 / 2
BRTS	k	Branch if T Flag Set	if (T = 1) then PC ← PC + k + 1	None	1 / 2
BRTC	k	Branch if T Flag Cleared	if (T = 0) then PC ← PC + k + 1	None	1 / 2
BRVS	k	Branch if Overflow Flag is Set	if (V = 1) then PC ← PC + k + 1	None	1 / 2
BRVC	k	Branch if Overflow Flag is Cleared	if (V = 0) then PC ← PC + k + 1	None	1 / 2

Mnemonics	Operands	Description	Operation	Flags	#Clocks
BRIE	k	Branch if Interrupt Enabled	if (I = 1) then PC ← PC + k + 1	None	1 / 2
BRID	k	Branch if Interrupt Disabled	if (I = 0) then PC ← PC + k + 1	None	1 / 2
DATA TRANSFER INSTRUCTIONS					
MOV	Rd, Rr	Move Between Registers	Rd ← Rr	None	1
MOVW	Rd, Rr	Copy Register Word	Rd+1:Rd ← Rr+1:Rr	None	1
LDI	Rd, K	Load Immediate	Rd ← K	None	1
LD	Rd, X	Load Indirect	Rd ← (X)	None	2
LD	Rd, X+	Load Indirect and Post-Inc.	Rd ← (X), X ← X + 1	None	2
LD	Rd, - X	Load Indirect and Pre-Dec.	X ← X - 1, Rd ← (X)	None	2
LD	Rd, Y	Load Indirect	Rd ← (Y)	None	2
LD	Rd, Y+	Load Indirect and Post-Inc.	Rd ← (Y), Y ← Y + 1	None	2
LD	Rd, - Y	Load Indirect and Pre-Dec.	Y ← Y - 1, Rd ← (Y)	None	2
LDD	Rd,Y+q	Load Indirect with Displacement	Rd ← (Y + q)	None	2
LD	Rd, Z	Load Indirect	Rd ← (Z)	None	2
LD	Rd, Z+	Load Indirect and Post-Inc.	Rd ← (Z), Z ← Z+1	None	2
LD	Rd, -Z	Load Indirect and Pre-Dec.	Z ← Z - 1, Rd ← (Z)	None	2
LDD	Rd, Z+q	Load Indirect with Displacement	Rd ← (Z + q)	None	2
LDS	Rd, k	Load Direct from SRAM	Rd ← (k)	None	2
ST	X, Rr	Store Indirect	(X) ← Rr	None	2
ST	X+, Rr	Store Indirect and Post-Inc.	(X) ← Rr, X ← X + 1	None	2
ST	- X, Rr	Store Indirect and Pre-Dec.	X ← X - 1, (X) ← Rr	None	2
ST	Y, Rr	Store Indirect	(Y) ← Rr	None	2
ST	Y+, Rr	Store Indirect and Post-Inc.	(Y) ← Rr, Y ← Y + 1	None	2
ST	- Y, Rr	Store Indirect and Pre-Dec.	Y ← Y - 1, (Y) ← Rr	None	2
STD	Y+q,Rr	Store Indirect with Displacement	(Y + q) ← Rr	None	2
ST	Z, Rr	Store Indirect	(Z) ← Rr	None	2
ST	Z+, Rr	Store Indirect and Post-Inc.	(Z) ← Rr, Z ← Z + 1	None	2
ST	-Z, Rr	Store Indirect and Pre-Dec.	Z ← Z - 1, (Z) ← Rr	None	2
STD	Z+q,Rr	Store Indirect with Displacement	(Z + q) ← Rr	None	2
STS	k, Rr	Store Direct to SRAM	(k) ← Rr	None	2
LPM		Load Program Memory	R0 ← (Z)	None	3
LPM	Rd, Z	Load Program Memory	Rd ← (Z)	None	3
LPM	Rd, Z+	Load Program Memory and Post-Inc	Rd ← (Z), Z ← Z+1	None	3
SPM		Store Program Memory	(Z) ← R1:R0	None	-
IN	Rd, P	In Port	Rd ← P	None	1
OUT	P, Rr	Out Port	P ← Rr	None	1
PUSH	Rr	Push Register on Stack	STACK ← Rr	None	2
POP	Rd	Pop Register from Stack	Rd ← STACK	None	2
BIT AND BIT-TEST INSTRUCTIONS					
SBI	P,b	Set Bit in I/O Register	I/O(P,b) ← 1	None	2
CBI	P,b	Clear Bit in I/O Register	I/O(P,b) ← 0	None	2
LSL	Rd	Logical Shift Left	Rd(n+1) ← Rd(n), Rd(0) ← 0	Z,C,N,V	1
LSR	Rd	Logical Shift Right	Rd(n) ← Rd(n+1), Rd(7) ← 0	Z,C,N,V	1
ROL	Rd	Rotate Left Through Carry	Rd(0)←C,Rd(n+1)← Rd(n),C←Rd(7)	Z,C,N,V	1
ROR	Rd	Rotate Right Through Carry	Rd(7)←C,Rd(n)← Rd(n+1),C←Rd(0)	Z,C,N,V	1
ASR	Rd	Arithmetic Shift Right	Rd(n) ← Rd(n+1), n=0..6	Z,C,N,V	1
SWAP	Rd	Swap Nibbles	Rd(3..0)←Rd(7..4),Rd(7..4)←Rd(3..0)	None	1
BSET	s	Flag Set	SREG(s) ← 1	SREG(s)	1
BCLR	s	Flag Clear	SREG(s) ← 0	SREG(s)	1
BST	Rr, b	Bit Store from Register to T	T ← Rr(b)	T	1
BLD	Rd, b	Bit load from T to Register	Rd(b) ← T	None	1
SEC		Set Carry	C ← 1	C	1
CLC		Clear Carry	C ← 0	C	1
SEN		Set Negative Flag	N ← 1	N	1
CLN		Clear Negative Flag	N ← 0	N	1
SEZ		Set Zero Flag	Z ← 1	Z	1
CLZ		Clear Zero Flag	Z ← 0	Z	1
SEI		Global Interrupt Enable	I ← 1	I	1
CLI		Global Interrupt Disable	I ← 0	I	1
SES		Set Signed Test Flag	S ← 1	S	1
CLS		Clear Signed Test Flag	S ← 0	S	1
SEV		Set Twos Complement Overflow.	V ← 1	V	1
CLV		Clear Twos Complement Overflow	V ← 0	V	1
SET		Set T in SREG	T ← 1	T	1
CLT		Clear T in SREG	T ← 0	T	1
SEH		Set Half Carry Flag in SREG	H ← 1	H	1

Mnemonics	Operands	Description	Operation	Flags	#Clocks
CLH		Clear Half Carry Flag in SREG	H ← 0	H	1
MCU CONTROL INSTRUCTIONS					
NOP		No Operation		None	1
SLEEP		Sleep	(see specific descr. for Sleep function)	None	1
WDR		Watchdog Reset	(see specific descr. for WDR/timer)	None	1
BREAK		Break	For On-Chip Debug Only	None	N/A

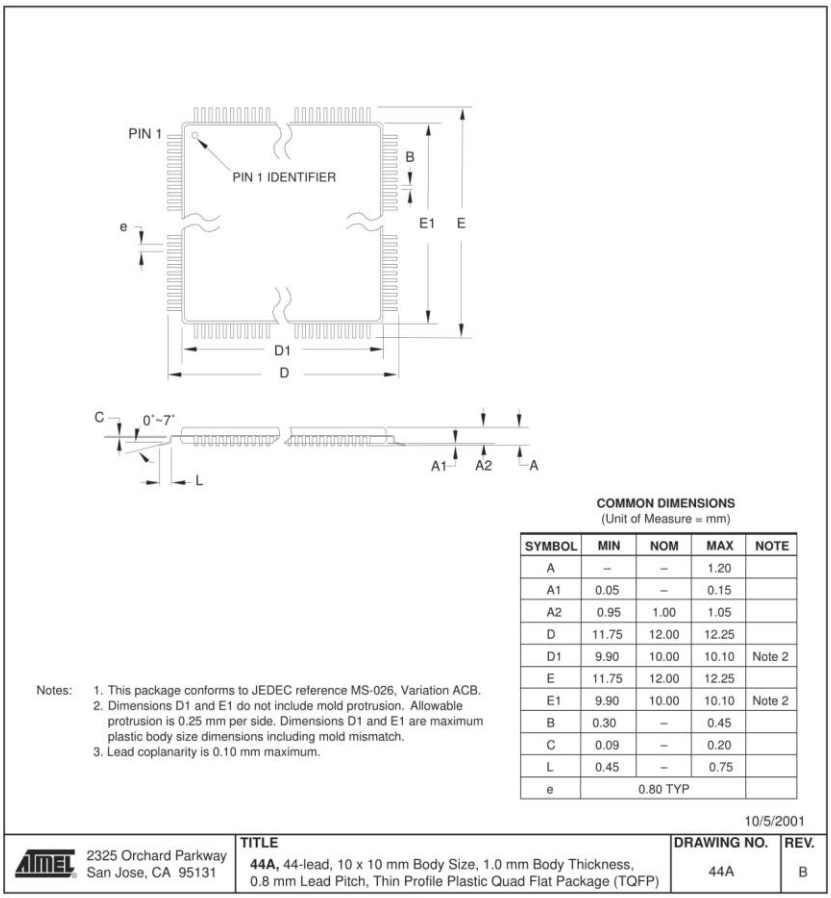
Ordering Information

Speed (MHz)	Power Supply	Ordering Code	Package	Operation Range
8	2.7 - 5.5V	ATmega16L-8AC ATmega16L-8PC ATmega16L-8MC	44A 40P6 44M1	Commercial (0°C to 70°C)
		ATmega16L-8AI ATmega16L-8PI ATmega16L-8MI	44A 40P6 44M1	Industrial (-40°C to 85°C)
16	4.5 - 5.5V	ATmega16-16AC ATmega16-16PC ATmega16-16MC	44A 40P6 44M1	Commercial (0°C to 70°C)
		ATmega16-16AI ATmega16-16PI ATmega16-16MI	44A 40P6 44M1	Industrial (-40°C to 85°C)

Package Type	
44A	44-lead, Thin (1.0 mm) Plastic Gull Wing Quad Flat Package (TQFP)
40P6	40-pin, 0.600" Wide, Plastic Dual Inline Package (PDIP)
44M1	44-pad, 7 x 7 x 1.0 mm body, lead pitch 0.50 mm, Micro Lead Frame Package (MLF)

Packaging Information

44A



COMMON DIMENSIONS
(Unit of Measure = mm)

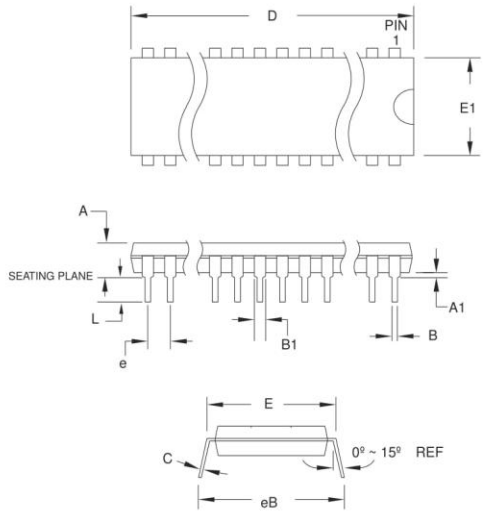
SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	1.20	
A1	0.05	–	0.15	
A2	0.95	1.00	1.05	
D	11.75	12.00	12.25	
D1	9.90	10.00	10.10	Note 2
E	11.75	12.00	12.25	
E1	9.90	10.00	10.10	Note 2
B	0.30	–	0.45	
C	0.09	–	0.20	
L	0.45	–	0.75	
e	0.80 TYP			

Notes:
1. This package conforms to JEDEC reference MS-026, Variation ACB.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25 mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10 mm maximum.

10/5/2001

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**44A,** 44-lead, 10 x 10 mm Body Size, 1.0 mm Body Thickness, 0.8 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)	44A	B

40P6



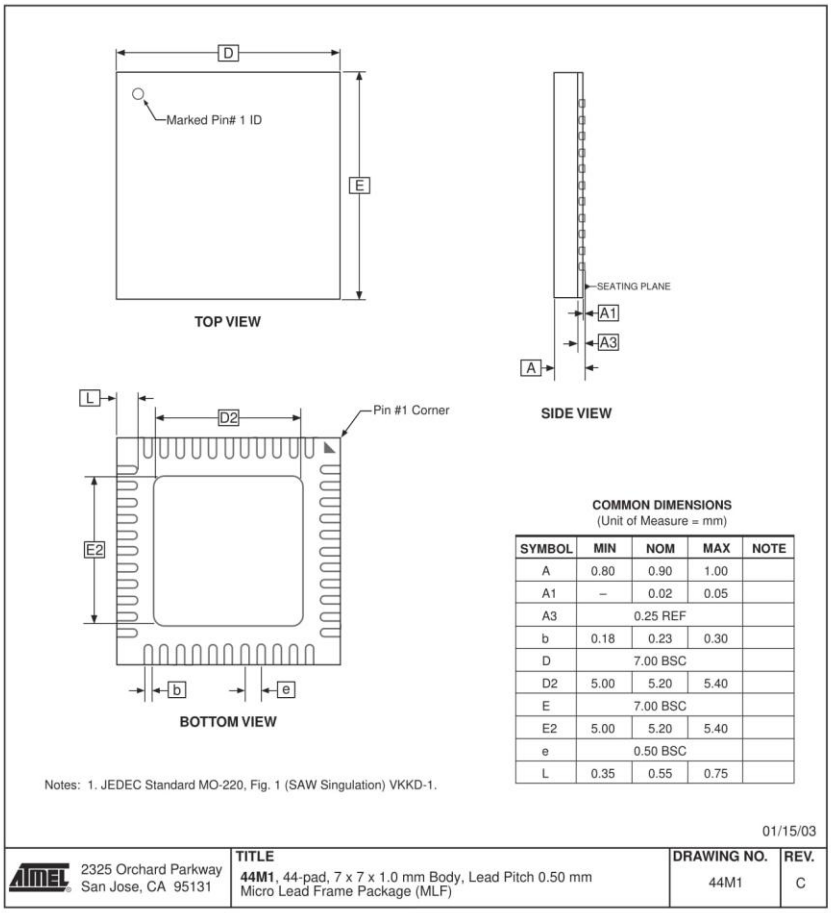
COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	4.826	
A1	0.381	–	–	
D	52.070	–	52.578	Note 2
E	15.240	–	15.875	
E1	13.462	–	13.970	Note 2
B	0.356	–	0.559	
B1	1.041	–	1.651	
L	3.048	–	3.556	
C	0.203	–	0.381	
eB	15.494	–	17.526	
e	2.540 TYP			

Notes: 1. This package conforms to JEDEC reference MS-011, Variation AC.
2. Dimensions D and E1 do not include mold Flash or Protrusion. Mold Flash or Protrusion shall not exceed 0.25 mm (0.010").

09/28/01

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**40P6**, 40-lead (0.600"/15.24 mm Wide) Plastic Dual Inline Package (PDIP)	40P6	B



COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	0.80	0.90	1.00	
A1	–	0.02	0.05	
A3		0.25 REF		
b	0.18	0.23	0.30	
D		7.00 BSC		
D2	5.00	5.20	5.40	
E		7.00 BSC		
E2	5.00	5.20	5.40	
e		0.50 BSC		
L	0.35	0.55	0.75	

Notes: 1. JEDEC Standard MO-220, Fig. 1 (SAW Singulation) VKKD-1.

01/15/03

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**44M1**, 44-pad, 7 x 7 x 1.0 mm Body, Lead Pitch 0.50 mm Micro Lead Frame Package (MLF)	44M1	C

Errata

The revision letter in this section refers to the revision of the ATmega16 device.

ATmega16(L) Rev. I

- **IDCODE masks data from TDI input**

1. IDCODE masks data from TDI input

The JTAG instruction IDCODE is not working correctly. Data to succeeding devices are replaced by all-ones during Update-DR.

Problem Fix / Workaround

– If ATmega16 is the only device in the scan chain, the problem is not visible.

– Select the Device ID Register of the ATmega16 by issuing the IDCODE instruction or by entering the Test-Logic-Reset state of the TAP controller to read out the contents of its Device ID Register and possibly data from succeeding devices of the scan chain. Issue the BYPASS instruction to the ATmega16 while reading the Device ID Registers of preceding devices of the boundary scan chain.

– If the Device IDs of all devices in the boundary scan chain must be captured simultaneously, the ATmega16 must be the fist device in the chain.

ATmega16(L) Rev. H

- **IDCODE masks data from TDI input**

1. IDCODE masks data from TDI input

The JTAG instruction IDCODE is not working correctly. Data to succeeding devices are replaced by all-ones during Update-DR.

Problem Fix / Workaround

– If ATmega16 is the only device in the scan chain, the problem is not visible.

– Select the Device ID Register of the ATmega16 by issuing the IDCODE instruction or by entering the Test-Logic-Reset state of the TAP controller to read out the contents of its Device ID Register and possibly data from succeeding devices of the scan chain. Issue the BYPASS instruction to the ATmega16 while reading the Device ID Registers of preceding devices of the boundary scan chain.

– If the Device IDs of all devices in the boundary scan chain must be captured simultaneously, the ATmega16 must be the fist device in the chain.

ATmega16(L) Rev. G

- **IDCODE masks data from TDI input**

1. IDCODE masks data from TDI input

The JTAG instruction IDCODE is not working correctly. Data to succeeding devices are replaced by all-ones during Update-DR.

Problem Fix / Workaround

– If ATmega16 is the only device in the scan chain, the problem is not visible.

– Select the Device ID Register of the ATmega16 by issuing the IDCODE instruction or by entering the Test-Logic-Reset state of the TAP controller to read out the contents of its Device ID Register and possibly data from succeeding devices of the scan chain. Issue the BYPASS instruction to the ATmega16 while reading the Device ID Registers of preceding devices of the boundary scan chain.

– If the Device IDs of all devices in the boundary scan chain must be captured simultaneously, the ATmega16 must be the fist device in the chain.

Datasheet Change Log for ATmega16

This section contains a log on the changes made to the datasheet for ATmega16.

Changes from Rev. 2466G-10/03 to Rev. 2466H-12/03

All page numbers refer to this document.

1. **Updated "Calibrated Internal RC Oscillator" on page 27.**

Changes from Rev. 2466F-02/03 to Rev. 2466G-10/03

All page numbers refer to this document.

1. **Removed "Preliminary" from the datasheet.**
2. **Changed ICP to ICP1 in the datasheet.**
3. **Updated "JTAG Interface and On-chip Debug System" on page 34.**
4. **Updated assembly and C code examples in "Watchdog Timer Control Register – WDTCR" on page 41.**
5. **Updated Figure 46 on page 101.**
6. **Updated Table 15 on page 36, Table 82 on page 215 and Table 115 on page 274.**
7. **Updated "Test Access Port – TAP" on page 220 regarding JTAGEN.**
8. **Updated description for the JTD bit on page 229.**
9. **Added note 2 to Figure 126 on page 251.**
10. **Added a note regarding JTAGEN fuse to Table 105 on page 259.**
11. **Updated Absolute Maximum Ratings* and DC Characteristics in "Electrical Characteristics" on page 289.**
12. **Updated "ATmega16 Typical Characteristics" on page 297.**
13. **Fixed typo for 16 MHz MLF package in "Ordering Information" on page 11.**
14. **Added a proposal for solving problems regarding the JTAG instruction IDCODE in "Errata" on page 15.**

Changes from Rev. 2466E-10/02 to Rev. 2466F-02/03

All page numbers refer to this document.

1. **Added note about masking out unused bits when reading the Program Counter in "Stack Pointer" on page 10.**
2. **Added Chip Erase as a first step in "Programming the Flash" on page 286 and "Programming the EEPROM" on page 287.**
3. **Added the section "Unconnected pins" on page 53.**

4. Added tips on how to disable the OCD system in “On-chip Debug System” on page 34.
5. Removed reference to the “Multi-purpose Oscillator” application note and “32 kHz Crystal Oscillator” application note, which do not exist.
6. Added information about PWM symmetry for Timer0 and Timer2.
7. Added note in “Filling the Temporary Buffer (Page Loading)” on page 252 about writing to the EEPROM during an SPM Page Load.
8. Removed ADHSM completely.
9. Added Table 73, “TWI Bit Rate Prescaler,” on page 180 to describe the TWPS bits in the “TWI Status Register – TWSR” on page 179.
10. Added section “Default Clock Source” on page 23.
11. Added note about frequency variation when using an external clock. Note added in “External Clock” on page 29. An extra row and a note added in Table 118 on page 291.
12. Various minor TWI corrections.
13. Added “Power Consumption” data in “Features” on page 1.
14. Added section “EEPROM Write During Power-down Sleep Mode” on page 20.
15. Added note about Differential Mode with Auto Triggering in “Prescaling and Conversion Timing” on page 205.
16. Added updated “Packaging Information” on page 12.

Changes from Rev. 2466D-09/02 to Rev. 2466E-10/02

All page numbers refer to this document.

1. Updated “DC Characteristics” on page 289.

Changes from Rev. 2466C-03/02 to Rev. 2466D-09/02

All page numbers refer to this document.

1. Changed all Flash write/erase cycles from 1,000 to 10,000.
2. Updated the following tables: Table 4 on page 24, Table 15 on page 36, Table 42 on page 83, Table 45 on page 110, Table 46 on page 110, Table 59 on page 141, Table 67 on page 165, Table 90 on page 233, Table 102 on page 257, “DC Characteristics” on page 289, Table 119 on page 291, Table 121 on page 293, and Table 122 on page 295.
3. Updated “Errata” on page 15.

Changes from Rev. 2466B-09/01 to Rev. 2466C-03/02

All page numbers refer to this document.

1. Updated typical EEPROM programming time, Table 1 on page 18.

2. **Updated typical start-up time in the following tables:**
   Table 3 on page 23, Table 5 on page 25, Table 6 on page 26, Table 8 on page 27, Table 9 on page 27, and Table 10 on page 28.

3. **Updated Table 17 on page 41 with typical WDT Time-out.**

4. **Added Some Preliminary Test Limits and Characterization Data.**
   Removed some of the TBD's in the following tables and pages:
   Table 15 on page 36, Table 16 on page 40, Table 116 on page 272 (table removed in document review #D), "Electrical Characteristics" on page 289, Table 119 on page 291, Table 121 on page 293, and Table 122 on page 295.

5. **Updated TWI Chapter.**
   Added the note at the end of the "Bit Rate Generator Unit" on page 176.

6. **Corrected description of ADSC bit in "ADC Control and Status Register A – ADCSRA" on page 217.**

7. **Improved description on how to do a polarity check of the ADC doff results in "ADC Conversion Result" on page 214.**

8. **Added JTAG version number for rev. H in Table 87 on page 227.**

9. **Added not regarding OCDEN Fuse below Table 105 on page 259.**

10. **Updated Programming Figures:**
    Figure 127 on page 261 and Figure 136 on page 272 are updated to also reflect that AVCC must be connected during Programming mode. Figure 131 on page 268 added to illustrate how to program the fuses.

11. **Added a note regarding usage of the "PROG_PAGELOAD ($6)" on page 278 and "PROG_PAGEREAD ($7)" on page 278.**

12. **Removed alternative algortihm for leaving JTAG Programming mode.**
    See "Leaving Programming Mode" on page 286.

13. **Added Calibrated RC Oscillator characterization curves in section "ATmega16 Typical Characteristics" on page 297.**

14. **Corrected ordering code for MLF package (16MHz) in "Ordering Information" on page 11.**

15. **Corrected Table 90, "Scan Signals for the Oscillators(1)(2)(3)," on page 233.**

Atmel Corporation

2325 Orchard Parkway
San Jose, CA 95131, USA
Tel: 1(408) 441-0311
Fax: 1(408) 487-2600

Regional Headquarters

Europe
Atmel Sarl
Route des Arsenaux 41
Case Postale 80
CH-1705 Fribourg
Switzerland
Tel: (41) 26-426-5555
Fax: (41) 26-426-5500

Asia
Room 1219
Chinachem Golden Plaza
77 Mody Road Tsimshatsui
East Kowloon
Hong Kong
Tel: (852) 2721-9778
Fax: (852) 2722-1369

Japan
9F, Tonetsu Shinkawa Bldg.
1-24-8 Shinkawa
Chuo-ku, Tokyo 104-0033
Japan
Tel: (81) 3-3523-3551
Fax: (81) 3-3523-7581

Atmel Operations

Memory
2325 Orchard Parkway
San Jose, CA 95131, USA
Tel: 1(408) 441-0311
Fax: 1(408) 436-4314

Microcontrollers
2325 Orchard Parkway
San Jose, CA 95131, USA
Tel: 1(408) 441-0311
Fax: 1(408) 436-4314

La Chantrerie
BP 70602
44306 Nantes Cedex 3, France
Tel: (33) 2-40-18-18-18
Fax: (33) 2-40-18-19-60

ASIC/ASSP/Smart Cards
Zone Industrielle
13106 Rousset Cedex, France
Tel: (33) 4-42-53-60-00
Fax: (33) 4-42-53-60-01

1150 East Cheyenne Mtn. Blvd.
Colorado Springs, CO 80906, USA
Tel: 1(719) 576-3300
Fax: 1(719) 540-1759

Scottish Enterprise Technology Park
Maxwell Building
East Kilbride G75 0QR, Scotland
Tel: (44) 1355-803-000
Fax: (44) 1355-242-743

RF/Automotive
Theresienstrasse 2
Postfach 3535
74025 Heilbronn, Germany
Tel: (49) 71-31-67-0
Fax: (49) 71-31-67-2340

1150 East Cheyenne Mtn. Blvd.
Colorado Springs, CO 80906, USA
Tel: 1(719) 576-3300
Fax: 1(719) 540-1759

Biometrics/Imaging/Hi-Rel MPU/
High Speed Converters/RF Datacom
Avenue de Rochepleine
BP 123
38521 Saint-Egreve Cedex, France
Tel: (33) 4-76-58-30-00
Fax: (33) 4-76-58-34-80

Literature Requests
www.atmel.com/literature

2466HS–AVR–12/03

Lampiran 5. *Datasheet* IC 7805

National Semiconductor

February 1995

LM78XX Series Voltage Regulators

General Description

The LM78XX series of three terminal regulators is available with several fixed output voltages making them useful in a wide range of applications. One of these is local on card regulation, eliminating the distribution problems associated with single point regulation. The voltages available allow these regulators to be used in logic systems, instrumentation, HiFi, and other solid state electronic equipment. Although designed primarily as fixed voltage regulators these devices can be used with external components to obtain adjustable voltages and currents.

The LM78XX series is available in an aluminum TO-3 package which will allow over 1.0A load current if adequate heat sinking is provided. Current limiting is included to limit the peak output current to a safe value. Safe area protection for the output transistor is provided to limit internal power dissipation. If internal power dissipation becomes too high for the heat sinking provided, the thermal shutdown circuit takes over preventing the IC from overheating.

Considerable effort was expanded to make the LM78XX series of regulators easy to use and mininize the number of external components. It is not necessary to bypass the output, although this does improve transient response. Input bypassing is needed only if the regulator is located far from the filter capacitor of the power supply.

For output voltage other than 5V, 12V and 15V the LM117 series provides an output voltage range from 1.2V to 57V.

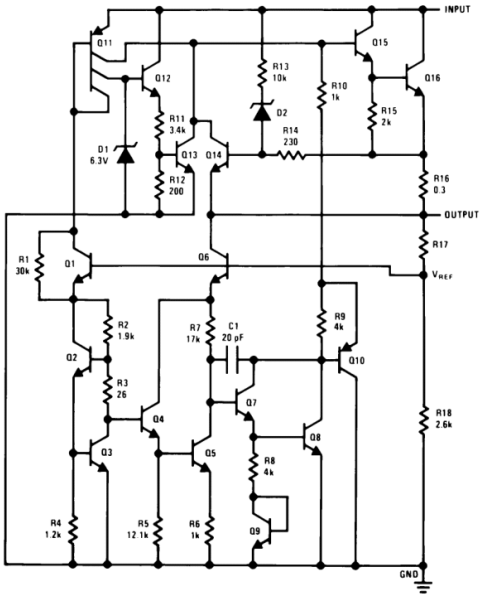
Features

- Output current in excess of 1A
- Internal thermal overload protection
- No external components required
- Output transistor safe area protection
- Internal short circuit current limit
- Available in the aluminum TO-3 package

Voltage Range

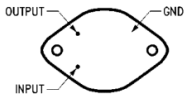
LM7805C	5V
LM7812C	12V
LM7815C	15V

Schematic and Connection Diagrams



TL/H/7746–1

Metal Can Package
TO-3 (K)
Aluminum

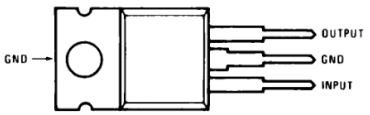


TL/H/7746–2

Bottom View

Order Number LM7805CK,
LM7812CK or LM7815CK
See NS Package Number KC02A

Plastic Package
TO-220 (T)



TL/H/7746–3

Top View

Order Number LM7805CT,
LM7812CT or LM7815CT
See NS Package Number T03B

RRD-B30M115/Printed in U. S. A.

Absolute Maximum Ratings

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Input Voltage (V_O = 5V, 12V and 15V)	35V
Internal Power Dissipation (Note 1)	Internally Limited
Operating Temperature Range (T_A)	0°C to +70°C
Maximum Junction Temperature	
(K Package)	150°C
(T Package)	150°C
Storage Temperature Range	−65°C to +150°C
Lead Temperature (Soldering, 10 sec.)	
TO-3 Package K	300°C
TO-220 Package T	230°C

Electrical Characteristics LM78XXC (Note 2) 0°C ≤ Tj ≤ 125°C unless otherwise noted.

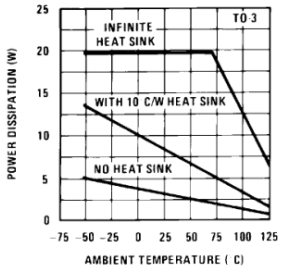
Output Voltage				5V			12V			15V			Units
Input Voltage (unless otherwise noted)				10V			19V			23V			
Symbol	Parameter	Conditions		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V_O	Output Voltage	Tj = 25°C, 5 mA ≤ I_O ≤ 1A		4.8	5	5.2	11.5	12	12.5	14.4	15	15.6	V
		P_D ≤ 15W, 5 mA ≤ I_O ≤ 1A		4.75		5.25	11.4		12.6	14.25		15.75	V
		V_{MIN} ≤ V_{IN} ≤ V_{MAX}		(7.5 ≤ V_{IN} ≤ 20)			(14.5 ≤ V_{IN} ≤ 27)			(17.5 ≤ V_{IN} ≤ 30)			V
ΔV_O	Line Regulation	I_O = 500 mA	Tj = 25°C		3	50		4	120		4	150	mV
			ΔV_{IN}	(7 ≤ V_{IN} ≤ 25)			14.5 ≤ V_{IN} ≤ 30)			(17.5 ≤ V_{IN} ≤ 30)			V
			0°C ≤ Tj ≤ +125°C			50			120			150	mV
			ΔV_{IN}	(8 ≤ V_{IN} ≤ 20)			(15 ≤ V_{IN} ≤ 27)			(18.5 ≤ V_{IN} ≤ 30)			V
		I_O ≤ 1A	Tj = 25°C			50			120			150	mV
			ΔV_{IN}	(7.5 ≤ V_{IN} ≤ 20)			(14.6 ≤ V_{IN} ≤ 27)			(17.7 ≤ V_{IN} ≤ 30)			V
			0°C ≤ Tj ≤ +125°C			25			60			75	mV
			ΔV_{IN}	(8 ≤ V_{IN} ≤ 12)			(16 ≤ V_{IN} ≤ 22)			(20 ≤ V_{IN} ≤ 26)			V
ΔV_O	Load Regulation	Tj = 25°C	5 mA ≤ I_O ≤ 1.5A		10	50		12	120		12	150	mV
			250 mA ≤ I_O ≤ 750 mA			25			60			75	mV
		5 mA ≤ I_O ≤ 1A, 0°C ≤ Tj ≤ +125°C				50			120			150	mV
I_Q	Quiescent Current	I_O ≤ 1A	Tj = 25°C			8			8			8	mA
			0°C ≤ Tj ≤ +125°C			8.5			8.5			8.5	mA
ΔI_Q	Quiescent Current Change	5 mA ≤ I_O ≤ 1A				0.5			0.5			0.5	mA
		Tj = 25°C, I_O ≤ 1A				1.0			1.0			1.0	mA
		V_{MIN} ≤ V_{IN} ≤ V_{MAX}		(7.5 ≤ V_{IN} ≤ 20)			(14.8 ≤ V_{IN}≤ 27)			(17.9 ≤ V_{IN} ≤ 30)			V
		I_O ≤ 500 mA, 0°C ≤ Tj ≤ +125°C				1.0			1.0			1.0	mA
		V_{MIN} ≤ V_{IN} ≤ V_{MAX}		(7 ≤ V_{IN} ≤ 25)			(14.5 ≤ V_{IN}≤ 30)			(17.5 ≤ V_{IN} ≤ 30)			V
V_N	Output Noise Voltage	T_A = 25°C, 10 Hz ≤ f ≤ 100 kHz			40			75			90		μV
$\frac{\Delta V_{IN}}{\Delta V_{OUT}}$	Ripple Rejection	f = 120 Hz	I_O ≤ 1A, Tj = 25°C or	62	80		55	72		54	70		dB
			I_O ≤ 500 mA	62			55			54			dB
			0°C ≤ Tj ≤ +125°C										
		V_{MIN} ≤ V_{IN} ≤ V_{MAX}		(8 ≤ V_{IN} ≤ 18)			(15 ≤ V_{IN} ≤ 25)			(18.5 ≤ V_{IN} ≤ 28.5)			V
R_O	Dropout Voltage	Tj = 25°C, I_{OUT} = 1A			2.0			2.0			2.0		V
	Output Resistance	f = 1 kHz			8			18			19		mΩ
	Short-Circuit Current	Tj = 25°C			2.1			1.5			1.2		A
	Peak Output Current	Tj = 25°C			2.4			2.4			2.4		A
	Average TC of V_{OUT}	0°C ≤ Tj ≤ +125°C, I_O = 5 mA			0.6			1.5			1.8		mV/°C
V_{IN}	Input Voltage Required to Maintain Line Regulation	Tj = 25°C, I_O ≤ 1A			7.5		14.6			17.7			V

Note 1: Thermal resistance of the TO-3 package (K, KC) is typically 4°C/W junction to case and 35°C/W case to ambient. Thermal resistance of the TO-220 package (T) is typically 4°C/W junction to case and 50°C/W case to ambient.

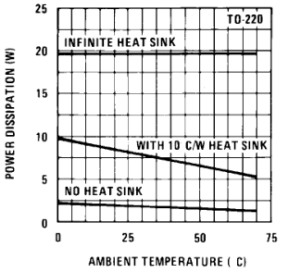
Note 2: All characteristics are measured with capacitor across the input of 0.22 μF, and a capacitor across the output of 0.1μF. All characteristics except noise voltage and ripple rejection ratio are measured using pulse techniques (t_w ≤ 10 ms, duty cycle ≤ 5%). Output voltage changes due to changes in internal temperature must be taken into account separately.

Typical Performance Characteristics

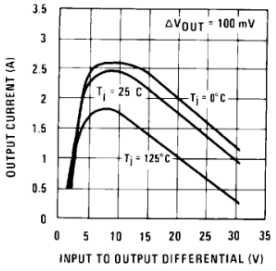
Maximum Average Power Dissipation



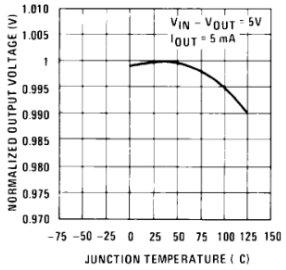
Maximum Average Power Dissipation



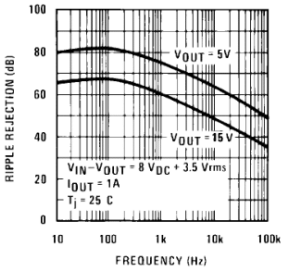
Peak Output Current



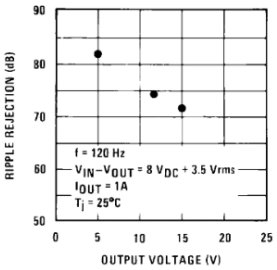
Output Voltage (Normalized to 1V at Tj = 25°C)



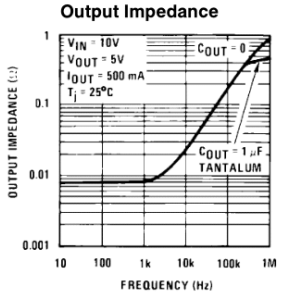
Ripple Rejection



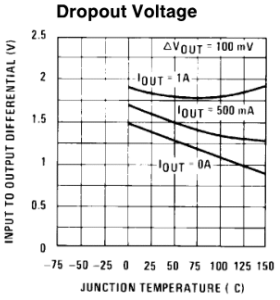
Ripple Rejection



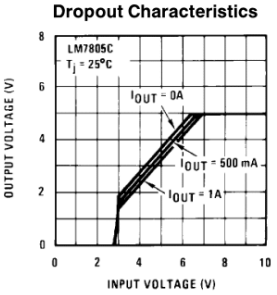
Output Impedance



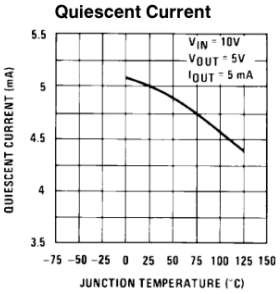
Dropout Voltage



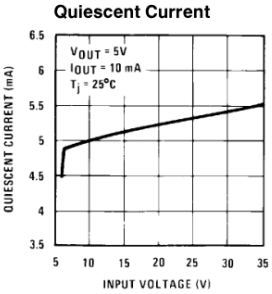
Dropout Characteristics



Quiescent Current

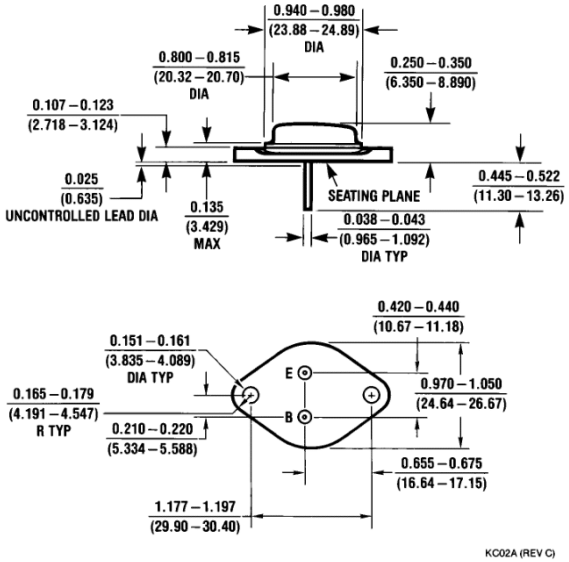


Quiescent Current



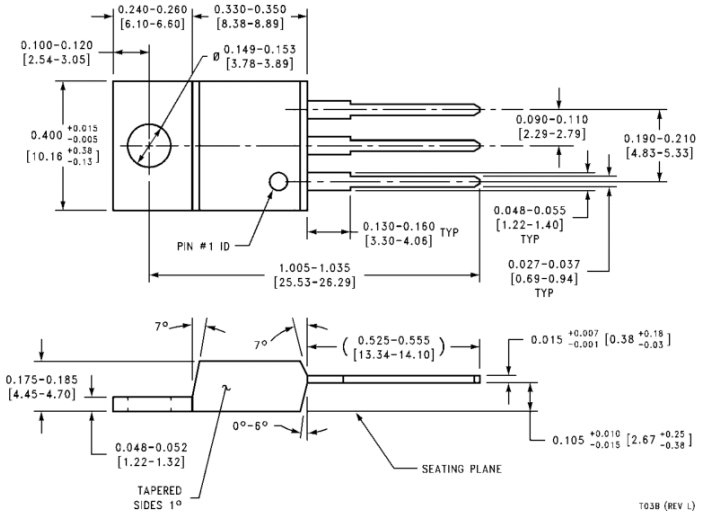
TL/H/7746–4

Physical Dimensions inches (millimeters)



Aluminum Metal Can Package (KC)
Order Number LM7805CK, LM7812CK or LM7815CK
NS Package Number KC02A

Physical Dimensions inches (millimeters) (Continued)



TO-220 Package (T)
Order Number LM7805CT, LM7812CT or LM7815CT
NS Package Number T03B

LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

National Semiconductor Corporation
1111 West Bardin Road
Arlington, TX 76017
Tel: 1(800) 272-9959
Fax: 1(800) 737-7018

National Semiconductor Europe
Fax: (+49) 0-180-530 85 86
Email: cnjwge@tevm2.nsc.com
Deutsch Tel: (+49) 0-180-530 85 85
English Tel: (+49) 0-180-532 78 32
Français Tel: (+49) 0-180-532 93 58
Italiano Tel: (+49) 0-180-534 16 80

National Semiconductor Hong Kong Ltd.
13th Floor, Straight Block,
Ocean Centre, 5 Canton Rd.
Tsimshatsui, Kowloon
Hong Kong
Tel: (852) 2737-1600
Fax: (852) 2736-9960

National Semiconductor Japan Ltd.
Tel: 81-043-299-2309
Fax: 81-043-299-2408

Lampiran 6. *Datasheet* Sensor Suhu DS18B20

DS18B20

Programmable Resolution 1-Wire Digital Thermometer

General Description

The DS18B20 digital thermometer provides 9-bit to 12-bit Celsius temperature measurements and has an alarm function with nonvolatile user-programmable upper and lower trigger points. The DS18B20 communicates over a 1-Wire bus that by definition requires only one data line (and ground) for communication with a central microprocessor. In addition, the DS18B20 can derive power directly from the data line ("parasite power"), eliminating the need for an external power supply.

Each DS18B20 has a unique 64-bit serial code, which allows multiple DS18B20s to function on the same 1-Wire bus. Thus, it is simple to use one microprocessor to control many DS18B20s distributed over a large area. Applications that can benefit from this feature include HVAC environmental controls, temperature monitoring systems inside buildings, equipment, or machinery, and process monitoring and control systems.

Applications

- Thermostatic Controls
- Industrial Systems
- Consumer Products
- Thermometers
- Thermally Sensitive Systems

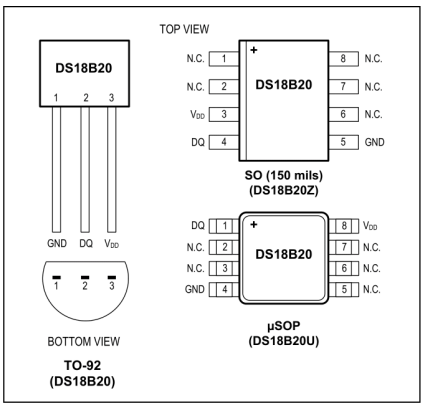
Ordering Information ***appears at end of data sheet.***

1-Wire is a registered trademark of Maxim Integrated Products, Inc.

Benefits and Features

- Unique 1-Wire® Interface Requires Only One Port Pin for Communication
- Reduce Component Count with Integrated Temperature Sensor and EEPROM
  - Measures Temperatures from -55°C to +125°C (-67°F to +257°F)
  - ±0.5°C Accuracy from -10°C to +85°C
  - Programmable Resolution from 9 Bits to 12 Bits
  - No External Components Required
- Parasitic Power Mode Requires Only 2 Pins for Operation (DQ and GND)
- Simplifies Distributed Temperature-Sensing Applications with Multidrop Capability
  - Each Device Has a Unique 64-Bit Serial Code Stored in On-Board ROM
- Flexible User-Definable Nonvolatile (NV) Alarm Settings with Alarm Search Command Identifies Devices with Temperatures Outside Programmed Limits
- Available in 8-Pin SO (150 mils), 8-Pin µSOP, and 3-Pin TO-92 Packages

Pin Configurations



19-7487; Rev 4; 1/15

maxim integrated™

Absolute Maximum Ratings

Voltage Range on Any Pin Relative to Ground....-0.5V to +6.0V
Operating Temperature Range..... -55°C to +125°C
Storage Temperature Range..... -55°C to +125°C
Solder Temperature.....Refer to the IPC/JEDEC J-STD-020 Specification.

These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect reliability.

DC Electrical Characteristics

(-55°C to +125°C; V_{DD} = 3.0V to 5.5V)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Supply Voltage	V_{DD}	Local power (Note 1)		+3.0		+5.5	V
Pullup Supply Voltage	V_{PU}	Parasite power	(Notes 1, 2)	+3.0		+5.5	V
		Local power		+3.0		V_{DD}	
Thermometer Error	t_{ERR}	-10°C to +85°C	(Note 3)			±0.5	°C
		-55°C to +125°C				±2	
Input Logic-Low	V_{IL}	(Notes 1, 4, 5)		-0.3		+0.8	V
Input Logic-High	V_{IH}	Local power	(Notes 1,6)	+2.2		The lower of 5.5 or V_{DD} + 0.3	V
		Parasite power		+3.0			
Sink Current	I_L	$V_{I/O}$ = 0.4V		4.0			mA
Standby Current	I_{DDS}	(Notes 7, 8)			750	1000	nA
Active Current	I_{DD}	V_{DD} = 5V (Note 9)			1	1.5	mA
DQ Input Current	I_{DQ}	(Note 10)			5		µA
Drift		(Note 11)			±0.2		°C

Note 1: All voltages are referenced to ground.
Note 2: The Pullup Supply Voltage specification assumes that the pullup device is ideal, and therefore the high level of the pullup is equal to V_{PU}. In order to meet the V_{IH} spec of the DS18B20, the actual supply rail for the strong pullup transistor must include margin for the voltage drop across the transistor when it is turned on; thus: $V_{PU\_ACTUAL} = V_{PU\_IDEAL} + V_{TRANSISTOR}$.
Note 3: See typical performance curve in Figure 1.
Note 4: Logic-low voltages are specified at a sink current of 4mA.
Note 5: To guarantee a presence pulse under low voltage parasite power conditions, V_{ILMAX} may have to be reduced to as low as 0.5V.
Note 6: Logic-high voltages are specified at a source current of 1mA.
Note 7: Standby current specified up to +70°C. Standby current typically is 3µA at +125°C.
Note 8: To minimize I_{DDS}, DQ should be within the following ranges: GND ≤ DQ ≤ GND + 0.3V or V_{DD} – 0.3V ≤ DQ ≤ V_{DD}.
Note 9: Active current refers to supply current during active temperature conversions or EEPROM writes.
Note 10: DQ line is high (“high-Z” state).
Note 11: Drift data is based on a 1000-hour stress test at +125°C with V_{DD} = 5.5V.

AC Electrical Characteristics–NV Memory

(-55°C to +125°C; V_{DD} = 3.0V to 5.5V)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
NV Write Cycle Time	t_{WR}			2	10	ms
EEPROM Writes	N_{EEWR}	-55°C to +55°C	50k			writes
EEPROM Data Retention	t_{EEDR}	-55°C to +55°C	10			years

AC Electrical Characteristics

(-55°C to +125°C; V_{DD} = 3.0V to 5.5V)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Temperature Conversion Time	t_{CONV}	9-bit resolution	(Note 12)			93.75	ms
		10-bit resolution				187.5	
		11-bit resolution				375	
		12-bit resolution				750	
Time to Strong Pullup On	t_{SPON}	Start convert T command issued				10	µs
Time Slot	t_{SLOT}	(Note 12)		60		120	µs
Recovery Time	t_{REC}	(Note 12)		1			µs
Write 0 Low Time	t_{LOW0}	(Note 12)		60		120	µs
Write 1 Low Time	t_{LOW1}	(Note 12)		1		15	µs
Read Data Valid	t_{RDV}	(Note 12)				15	µs
Reset Time High	t_{RSTH}	(Note 12)		480			µs
Reset Time Low	t_{RSTL}	(Notes 12, 13)		480			µs
Presence-Detect High	t_{PDHIGH}	(Note 12)		15		60	µs
Presence-Detect Low	t_{PDLOW}	(Note 12)		60		240	µs
Capacitance	$C_{IN/OUT}$					25	pF

Note 12: See the timing diagrams in Figure 2.
Note 13: Under parasite power, if t_{RSTL} > 960µs, a power-on reset can occur.

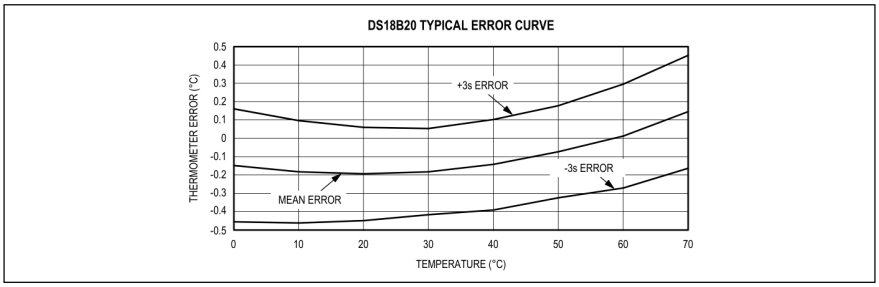


Figure 1. Typical Performance Curve

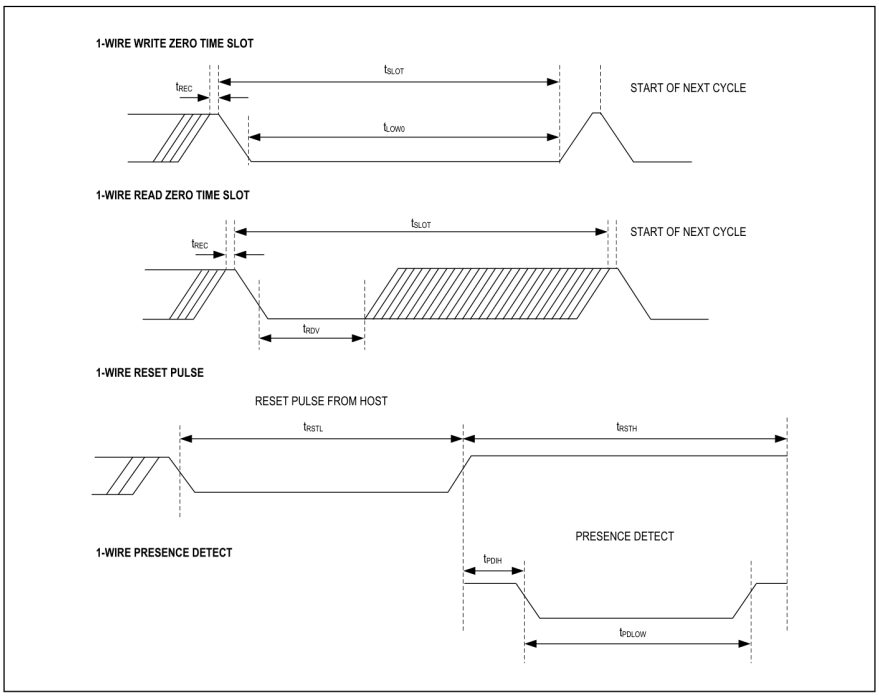


Figure 2. Timing Diagrams

Pin Description

PIN			NAME	FUNCTION
SO	µSOP	TO-92		
1, 2, 6, 7, 8	2, 3, 5, 6, 7	—	N.C.	No Connection
3	8	3	V_{DD}	Optional V_{DD}. V_{DD} must be grounded for operation in parasite power mode.
4	1	2	DQ	Data Input/Output. Open-drain 1-Wire interface pin. Also provides power to the device when used in parasite power mode (see the *Powering the DS18B20* section.)
5	4	1	GND	Ground

Overview

Figure 3 shows a block diagram of the DS18B20, and pin descriptions are given in the *Pin Description* table. The 64-bit ROM stores the device's unique serial code. The scratchpad memory contains the 2-byte temperature register that stores the digital output from the temperature sensor. In addition, the scratchpad provides access to the 1-byte upper and lower alarm trigger registers (T_H and T_L) and the 1-byte configuration register. The configuration register allows the user to set the resolution of the temperature-to-digital conversion to 9, 10, 11, or 12 bits. The T_H, T_L, and configuration registers are nonvolatile (EEPROM), so they will retain data when the device is powered down.

The DS18B20 uses Maxim's exclusive 1-Wire bus protocol that implements bus communication using one control signal. The control line requires a weak pullup resistor since all devices are linked to the bus via a 3-state or open-drain port (the DQ pin in the case of the DS18B20). In this bus system, the microprocessor (the master device) identifies and addresses devices on the bus using each device's unique 64-bit code. Because each device has a unique code, the number of devices that can be addressed on one bus is virtually unlimited. The 1-Wire bus protocol, including detailed explanations of the commands and "time slots," is covered in the *1-Wire Bus System* section.

Another feature of the DS18B20 is the ability to operate without an external power supply. Power is instead supplied through the 1-Wire pullup resistor through the DQ pin when the bus is high. The high bus signal also charges an internal capacitor (C_{PP}), which then supplies power to the device when the bus is low. This method of deriving power from the 1-Wire bus is referred to as "parasite power." As an alternative, the DS18B20 may also be powered by an external supply on V_{DD}.

Operation—Measuring Temperature

The core functionality of the DS18B20 is its direct-to-digital temperature sensor. The resolution of the temperature sensor is user-configurable to 9, 10, 11, or 12 bits, corresponding to increments of 0.5°C, 0.25°C, 0.125°C, and 0.0625°C, respectively. The default resolution at power-up is 12-bit. The DS18B20 powers up in a low-power idle state. To initiate a temperature measurement and A-to-D conversion, the master must issue a Convert T [44h] command. Following the conversion, the resulting thermal data is stored in the 2-byte temperature register in the scratchpad memory and the DS18B20 returns to its idle state. If the DS18B20 is powered by an external supply, the master can issue "read time slots" (see the *1-Wire Bus System* section) after the Convert T command and the DS18B20 will respond by transmitting 0 while the temperature conversion is in progress and 1 when the conversion is done. If the DS18B20 is powered with parasite power, this notification technique cannot be used since the bus must be pulled high by a strong pullup during the entire temperature conversion. The bus requirements for parasite power are explained in detail in the *Powering the DS18B20* section.

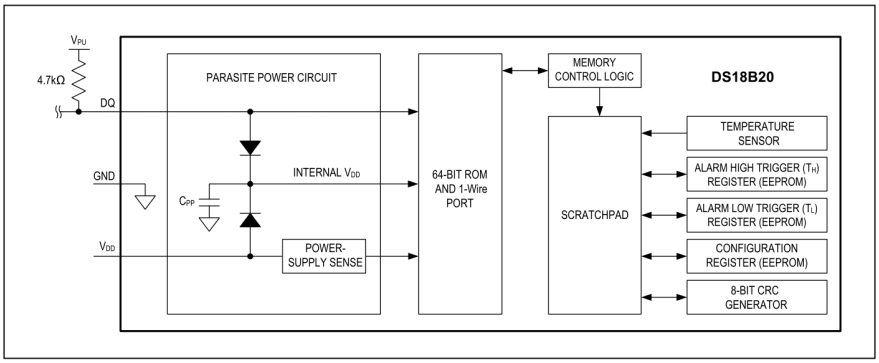


Figure 3. DS18B20 Block Diagram

The DS18B20 output temperature data is calibrated in degrees Celsius; for Fahrenheit applications, a lookup table or conversion routine must be used. The temperature data is stored as a 16-bit sign-extended two's complement number in the temperature register (see Figure 4). The sign bits (S) indicate if the temperature is positive or negative: for positive numbers S = 0 and for negative numbers S = 1. If the DS18B20 is configured for 12-bit resolution, all bits in the temperature register will contain valid data. For 11-bit resolution, bit 0 is undefined. For 10-bit resolution, bits 1 and 0 are undefined, and for 9-bit resolution bits 2, 1, and 0 are undefined. Table 1 gives examples of digital output data and the corresponding temperature reading for 12-bit resolution conversions.

Operation—Alarm Signaling

After the DS18B20 performs a temperature conversion, the temperature value is compared to the user-defined two's complement alarm trigger values stored in the 1-byte T_H and T_L registers (see Figure 5). The sign bit (S) indicates if the value is positive or negative: for positive numbers S = 0 and for negative numbers S = 1. The T_H and T_L registers are nonvolatile (EEPROM) so they will retain data when the device is powered down. T_H and T_L can be accessed through bytes 2 and 3 of the scratchpad as explained in the *Memory* section.

Only bits 11 through 4 of the temperature register are used in the T_H and T_L comparison since T_H and T_L are 8-bit registers. If the measured temperature is lower than

	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
LS BYTE	2^3	2^2	2^1	2^0	2^{-1}	2^{-2}	2^{-3}	2^{-4}
	BIT 15	**BIT 14**	**BIT 13**	**BIT 12**	**BIT 11**	**BIT 10**	**BIT 9**	**BIT 8**
MS BYTE	S	S	S	S	S	2^6	2^5	2^4

S = SIGN

Figure 4. Temperature Register Format

Table 1. Temperature/Data Relationship

TEMPERATURE (°C)	DIGITAL OUTPUT (BINARY)	DIGITAL OUTPUT (HEX)
+125	0000 0111 1101 0000	07D0h
+85*	0000 0101 0101 0000	0550h
+25.0625	0000 0001 1001 0001	0191h
+10.125	0000 0000 1010 0010	00A2h
+0.5	0000 0000 0000 1000	0008h
0	0000 0000 0000 0000	0000h
-0.5	1111 1111 1111 1000	FFF8h
-10.125	1111 1111 0101 1110	FF5Eh
-25.0625	1111 1110 0110 1111	FE6Fh
-55	1111 1100 1001 0000	FC90h

**The power-on reset value of the temperature register is +85°C.*

BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
S	2^6	2^5	2^4	2^3	2^2	2^1	2^0

Figure 5. T_H and T_L Register Format

or equal to T_L or higher than or equal to T_H, an alarm condition exists and an alarm flag is set inside the DS18B20. This flag is updated after every temperature measurement; therefore, if the alarm condition goes away, the flag will be turned off after the next temperature conversion.

The master device can check the alarm flag status of all DS18B20s on the bus by issuing an Alarm Search [ECh] command. Any DS18B20s with a set alarm flag will respond to the command, so the master can determine exactly which DS18B20s have experienced an alarm condition. If an alarm condition exists and the T_H or T_L settings have changed, another temperature conversion should be done to validate the alarm condition.

Powering the DS18B20

The DS18B20 can be powered by an external supply on the V_{DD} pin, or it can operate in "parasite power" mode, which allows the DS18B20 to function without a local external supply. Parasite power is very useful for applications that require remote temperature sensing or that are very space constrained. Figure 3 shows the DS18B20's parasite-power control circuitry, which "steals" power from the 1-Wire bus via the DQ pin when the bus is high. The stolen charge powers the DS18B20 while the bus is high, and some of the charge is stored on the parasite power capacitor (C_{PP}) to provide power when the bus is low. When the DS18B20 is used in parasite power mode, the V_{DD} pin must be connected to ground.

In parasite power mode, the 1-Wire bus and CPP can provide sufficient current to the DS18B20 for most operations as long as the specified timing and voltage requirements are met (see the *DC Electrical Characteristics* and *AC Electrical Characteristics*). However, when the DS18B20 is performing temperature conversions or copying data from the scratchpad memory to EEPROM, the operating current can be as high as 1.5mA. This current can cause an unacceptable voltage drop across the weak 1-Wire pullup resistor and is more current than can be supplied by C_{PP}. To assure that the DS18B20 has sufficient supply current, it is necessary to provide a strong pullup on the 1-Wire bus whenever temperature conversions are taking place or data is being copied from the scratchpad to EEPROM. This can be accomplished by using a MOSFET to pull the bus directly to the rail as shown in Figure 6. The 1-Wire bus must be switched to the strong pullup within 10µs (max) after a Convert T [44h] or Copy Scratchpad [48h] command is issued, and the bus must be held high by the pullup for the duration of the conversion (t_{CONV}) or data transfer (t_{WR} = 10ms). No other activity can take place on the 1-Wire bus while the pullup is enabled.

The DS18B20 can also be powered by the conventional method of connecting an external power supply to the V_{DD} pin, as shown in Figure 7. The advantage of this method is that the MOSFET pullup is not required, and the 1-Wire bus is free to carry other traffic during the temperature conversion time.

The use of parasite power is not recommended for temperatures above +100°C since the DS18B20 may not be able to sustain communications due to the higher leakage currents that can exist at these temperatures. For applications in which such temperatures are likely, it is strongly recommended that the DS18B20 be powered by an external power supply.

In some situations the bus master may not know whether the DS18B20s on the bus are parasite powered or powered by external supplies. The master needs this information to determine if the strong bus pullup should be used during temperature conversions. To get this information, the master can issue a Skip ROM [CCh] command followed by a Read Power Supply [B4h] command followed by a "read time slot". During the read time slot, parasite powered DS18B20s will pull the bus low, and externally powered DS18B20s will let the bus remain high. If the bus is pulled low, the master knows that it must supply the strong pullup on the 1-Wire bus during temperature conversions.

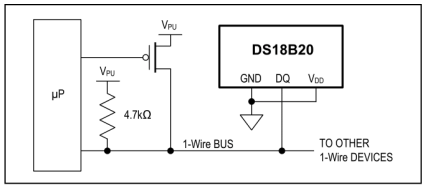


Figure 6. Supplying the Parasite-Powered DS18B20 During Temperature Conversions

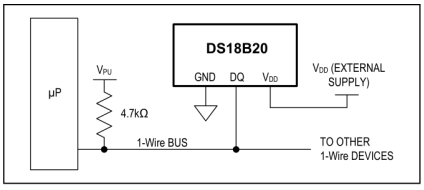


Figure 7. Powering the DS18B20 with an External Supply

64-BIT Lasered ROM code

Each DS18B20 contains a unique 64–bit code (see Figure 8) stored in ROM. The least significant 8 bits of the ROM code contain the DS18B20's 1-Wire family code: 28h. The next 48 bits contain a unique serial number. The most significant 8 bits contain a cyclic redundancy check (CRC) byte that is calculated from the first 56 bits of the ROM code. A detailed explanation of the CRC bits is provided in the *CRC Generation* section. The 64-bit ROM code and associated ROM function control logic allow the DS18B20 to operate as a 1-Wire device using the protocol detailed in the *1-Wire Bus System* section.

Memory

The DS18B20's memory is organized as shown in Figure 9. The memory consists of an SRAM scratchpad with nonvolatile EEPROM storage for the high and low alarm trigger registers (T_H and T_L) and configuration register. Note that if the DS18B20 alarm function is not used, the TH and TL registers can serve as general-purpose memory. All memory commands are described in detail in the *DS18B20 Function Commands* section.

Byte 0 and byte 1 of the scratchpad contain the LSB and the MSB of the temperature register, respectively. These bytes are read-only. Bytes 2 and 3 provide access to TH and TL registers. Byte 4 contains the configuration register data, which is explained in detail in the *Configuration Register* section. Bytes 5, 6, and 7 are reserved for internal use by the device and cannot be overwritten.

Byte 8 of the scratchpad is read-only and contains the CRC code for bytes 0 through 7 of the scratchpad. The DS18B20 generates this CRC using the method described in the *CRC Generation* section.

Data is written to bytes 2, 3, and 4 of the scratchpad using the Write Scratchpad [4Eh] command; the data must be transmitted to the DS18B20 starting with the least significant bit of byte 2. To verify data integrity, the scratchpad can be read (using the Read Scratchpad [BEh] command) after the data is written. When reading the scratchpad, data is transferred over the 1-Wire bus starting with the least significant bit of byte 0. To transfer the T_H, T_L and configuration data from the scratchpad to EEPROM, the master must issue the Copy Scratchpad [48h] command.

Data in the EEPROM registers is retained when the device is powered down; at power-up the EEPROM data is reloaded into the corresponding scratchpad locations. Data can also be reloaded from EEPROM to the scratchpad at any time using the Recall E^2 [B8h] command. The master can issue read time slots following the Recall E^2 command and the DS18B20 will indicate the status of the recall by transmitting 0 while the recall is in progress and 1 when the recall is done.

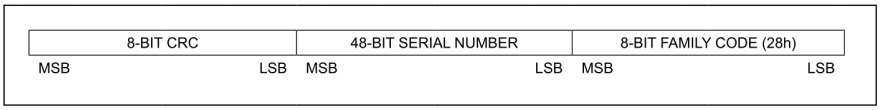


Figure 8. 64-Bit Lasered ROM Code

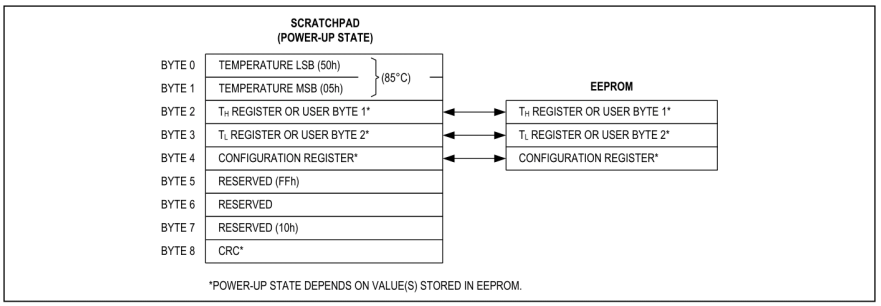


Figure 9. DS18B20 Memory Map

Configuration Register

Byte 4 of the scratchpad memory contains the configuration register, which is organized as illustrated in Figure 10. The user can set the conversion resolution of the DS18B20 using the R0 and R1 bits in this register as shown in Table 2. The power-up default of these bits is R0 = 1 and R1 = 1 (12-bit resolution). Note that there is a direct tradeoff between resolution and conversion time. Bit 7 and bits 0 to 4 in the configuration register are reserved for internal use by the device and cannot be overwritten.

CRC Generation

CRC bytes are provided as part of the DS18B20's 64-bit ROM code and in the 9th byte of the scratchpad memory. The ROM code CRC is calculated from the first 56 bits of the ROM code and is contained in the most significant byte of the ROM. The scratchpad CRC is calculated from the data stored in the scratchpad, and therefore it changes when the data in the scratchpad changes. The CRCs provide the bus master with a method of data validation when data is read from the DS18B20. To verify that data has been read correctly, the bus master must re-calculate the CRC from the received data and then compare this value to either the ROM code CRC (for ROM reads) or to the scratchpad CRC (for scratchpad reads). If the calculated CRC matches the read CRC, the data has been received error free. The comparison of CRC values and the decision to continue with an operation are determined entirely by the bus master. There is no circuitry inside the DS18B20 that prevents a command sequence from proceeding if the DS18B20 CRC (ROM or scratchpad) does not match the value generated by the bus master.

The equivalent polynomial function of the CRC (ROM or scratchpad) is:

$$CRC = X^8 + X^5 + X^4 + 1$$

The bus master can re-calculate the CRC and compare it to the CRC values from the DS18B20 using the polynomial generator shown in Figure 11. This circuit consists of a shift register and XOR gates, and the shift register bits are initialized to 0. Starting with the least significant bit of the ROM code or the least significant bit of byte 0 in the scratchpad, one bit at a time should shifted into the shift register. After shifting in the 56th bit from the ROM or the most significant bit of byte 7 from the scratchpad, the polynomial generator will contain the recalculated CRC. Next, the 8-bit ROM code or scratchpad CRC from the DS18B20 must be shifted into the circuit. At this point, if the re-calculated CRC was correct, the shift register will contain all 0s. Additional information about the Maxim 1-Wire cyclic redundancy check is available in *Application Note 27: Understanding and Using Cyclic Redundancy Checks with Maxim iButton Products*.

BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
0	R1	R0	1	1	1	1	1

Figure 10. Configuration Register

Table 2. Thermometer Resolution Configuration

R1	R0	RESOLUTION (BITS)	MAX CONVERSION TIME	
0	0	9	93.75ms	($t_{CONV}/8$)
0	1	10	187.5ms	($t_{CONV}/4$)
1	0	11	375ms	($t_{CONV}/2$)
1	1	12	750ms	(t_{CONV})

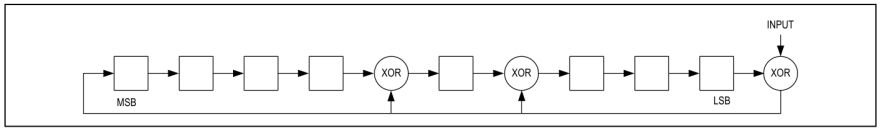


Figure 11. CRC Generator

1-Wire Bus System

The 1-Wire bus system uses a single bus master to control one or more slave devices. The DS18B20 is always a slave. When there is only one slave on the bus, the system is referred to as a “single-drop” system; the system is “multidrop” if there are multiple slaves on the bus.

All data and commands are transmitted least significant bit first over the 1-Wire bus.

The following discussion of the 1-Wire bus system is broken down into three topics: hardware configuration, transaction sequence, and 1-Wire signaling (signal types and timing).

Hardware Configuration

The 1-Wire bus has by definition only a single data line. Each device (master or slave) interfaces to the data line via an open-drain or 3-state port. This allows each device to “release” the data line when the device is not transmitting data so the bus is available for use by another device. The 1-Wire port of the DS18B20 (the DQ pin) is open drain with an internal circuit equivalent to that shown in Figure 12.

The 1-Wire bus requires an external pullup resistor of approximately 5kΩ; thus, the idle state for the 1-Wire bus is high. If for any reason a transaction needs to be suspended, the bus MUST be left in the idle state if the transaction is to resume. Infinite recovery time can occur between bits so long as the 1-Wire bus is in the inactive (high) state during the recovery period. If the bus is held low for more than 480µs, all components on the bus will be reset.

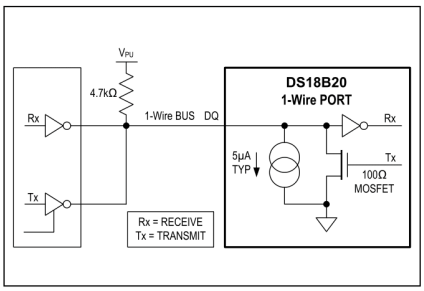


Figure 12. Hardware Configuration

Transaction Sequence

The transaction sequence for accessing the DS18B20 is as follows:

Step 1. Initialization

Step 2. ROM Command (followed by any required data exchange)

Step 3. DS18B20 Function Command (followed by any required data exchange)

It is very important to follow this sequence every time the DS18B20 is accessed, as the DS18B20 will not respond if any steps in the sequence are missing or out of order. Exceptions to this rule are the Search ROM [F0h] and Alarm Search [ECh] commands. After issuing either of these ROM commands, the master must return to Step 1 in the sequence.

Initialization

All transactions on the 1-Wire bus begin with an initialization sequence. The initialization sequence consists of a reset pulse transmitted by the bus master followed by presence pulse(s) transmitted by the slave(s). The presence pulse lets the bus master know that slave devices (such as the DS18B20) are on the bus and are ready to operate. Timing for the reset and presence pulses is detailed in the *1-Wire Signaling* section.

ROM Commands

After the bus master has detected a presence pulse, it can issue a ROM command. These commands operate on the unique 64-bit ROM codes of each slave device and allow the master to single out a specific device if many are present on the 1-Wire bus. These commands also allow the master to determine how many and what types of devices are present on the bus or if any device has experienced an alarm condition. There are five ROM commands, and each command is 8 bits long. The master device must issue an appropriate ROM command before issuing a DS18B20 function command. A flowchart for operation of the ROM commands is shown in Figure 13.

Search Rom [F0h]

When a system is initially powered up, the master must identify the ROM codes of all slave devices on the bus, which allows the master to determine the number of slaves and their device types. The master learns the ROM codes through a process of elimination that requires the master to perform a Search ROM cycle (i.e., Search ROM command followed by data exchange) as many times as necessary to identify all of the slave devices.

If there is only one slave on the bus, the simpler Read ROM [33h] command can be used in place of the Search ROM process. For a detailed explanation of the Search ROM procedure, refer to *Application Note 937: Book of iButton® Standards*. After every Search ROM cycle, the bus master must return to Step 1 (Initialization) in the transaction sequence.

Read Rom [33h]

This command can only be used when there is one slave on the bus. It allows the bus master to read the slave's 64-bit ROM code without using the Search ROM procedure. If this command is used when there is more than one slave present on the bus, a data collision will occur when all the slaves attempt to respond at the same time.

Match Rom [55H]

The match ROM command followed by a 64-bit ROM code sequence allows the bus master to address a specific slave device on a multidrop or single-drop bus. Only the slave that exactly matches the 64-bit ROM code sequence will respond to the function command issued by the master; all other slaves on the bus will wait for a reset pulse.

Skip Rom [CCh]

The master can use this command to address all devices on the bus simultaneously without sending out any ROM code information. For example, the master can make all DS18B20s on the bus perform simultaneous temperature conversions by issuing a Skip ROM command followed by a Convert T [44h] command.

Note that the Read Scratchpad [BEh] command can follow the Skip ROM command only if there is a single slave device on the bus. In this case, time is saved by allowing the master to read from the slave without sending the device's 64-bit ROM code. A Skip ROM command followed by a Read Scratchpad command will cause a data collision on the bus if there is more than one slave since multiple devices will attempt to transmit data simultaneously.

Alarm Search [ECh]

The operation of this command is identical to the operation of the Search ROM command except that only slaves with a set alarm flag will respond. This command allows the master device to determine if any DS18B20s experienced an alarm condition during the most recent temperature conversion. After every Alarm Search cycle (i.e., Alarm Search command followed by data exchange), the bus master must return to Step 1 (Initialization) in the transaction sequence. See the *Operation—Alarm Signaling* section for an explanation of alarm flag operation.

DS18B20 Function Commands

After the bus master has used a ROM command to address the DS18B20 with which it wishes to communicate, the master can issue one of the DS18B20 function commands. These commands allow the master to write to and read from the DS18B20's scratchpad memory, initiate temperature conversions and determine the power supply mode. The DS18B20 function commands, which are described below, are summarized in Table 3 and illustrated by the flowchart in Figure 14.

Convert T [44h]

This command initiates a single temperature conversion. Following the conversion, the resulting thermal data is stored in the 2-byte temperature register in the scratchpad memory and the DS18B20 returns to its low-power idle state. If the device is being used in parasite power mode, within 10µs (max) after this command is issued the master must enable a strong pullup on the 1-Wire bus for the duration of the conversion (t_{CONV}) as described in the *Powering the DS18B20* section. If the DS18B20 is powered by an external supply, the master can issue read time slots after the Convert T command and the DS18B20 will respond by transmitting a 0 while the temperature conversion is in progress and a 1 when the conversion is done. In parasite power mode this notification technique cannot be used since the bus is pulled high by the strong pullup during the conversion.

Write Scratchpad [4Eh]

This command allows the master to write 3 bytes of data to the DS18B20's scratchpad. The first data byte is written into the T_H register (byte 2 of the scratchpad), the second byte is written into the T_L register (byte 3), and the third byte is written into the configuration register (byte 4). Data must be transmitted least significant bit first. All three bytes MUST be written before the master issues a reset, or the data may be corrupted.

Read Scratchpad [BEh]

This command allows the master to read the contents of the scratchpad. The data transfer starts with the least significant bit of byte 0 and continues through the scratchpad until the 9th byte (byte 8 – CRC) is read. The master may issue a reset to terminate reading at any time if only part of the scratchpad data is needed.

¡Button is a registered trademark of Maxim Integrated Products, Inc.

Copy Scratchpad [48h]

This command copies the contents of the scratchpad T_H, T_L and configuration registers (bytes 2, 3 and 4) to EEPROM. If the device is being used in parasite power mode, within 10µs (max) after this command is issued the master must enable a strong pullup on the 1-Wire bus for at least 10ms as described in the *Powering the DS18B20* section.

Recall E^2 [B8h]

This command recalls the alarm trigger values (T_H and T_L) and configuration data from EEPROM and places the data in bytes 2, 3, and 4, respectively, in the scratchpad memory. The master device can issue read time slots following the Recall E^2 command and the DS18B20 will indicate the status of the recall by transmitting 0 while the recall is in progress and 1 when the recall is done. The recall operation happens automatically at power-up, so valid data is available in the scratchpad as soon as power is applied to the device.

Read Power Supply [B4h]

The master device issues this command followed by a read time slot to determine if any DS18B20s on the bus are using parasite power. During the read time slot, parasite powered DS18B20s will pull the bus low, and externally powered DS18B20s will let the bus remain high. See the *Powering the DS18B20* section for usage information for this command.

Table 3. DS18B20 Function Command Set

COMMAND	DESCRIPTION	PROTOCOL	1-Wire BUS ACTIVITY AFTER COMMAND IS ISSUED	NOTES
TEMPERATURE CONVERSION COMMANDS				
Convert T	Initiates temperature conversion.	44h	DS18B20 transmits conversion status to master (not applicable for parasite-powered DS18B20s).	1
MEMORY COMMANDS				
Read Scratchpad	Reads the entire scratchpad including the CRC byte.	BEh	DS18B20 transmits up to 9 data bytes to master.	2
Write Scratchpad	Writes data into scratchpad bytes 2, 3, and 4 (T_H, T_L, and configuration registers).	4Eh	Master transmits 3 data bytes to DS18B20.	3
Copy Scratchpad	Copies T_H, T_L, and configuration register data from the scratchpad to EEPROM.	48h	None	1
Recall E^2	Recalls T_H, T_L, and configuration register data from EEPROM to the scratchpad.	B8h	DS18B20 transmits recall status to master.	
Read Power Supply	Signals DS18B20 power supply mode to the master.	B4h	DS18B20 transmits supply status to master.	

Note 1: For parasite-powered DS18B20s, the master must enable a strong pullup on the 1-Wire bus during temperature conversions and copies from the scratchpad to EEPROM. No other bus activity may take place during this time.
Note 2: The master can interrupt the transmission of data at any time by issuing a reset.
Note 3: All three bytes must be written before a reset is issued.

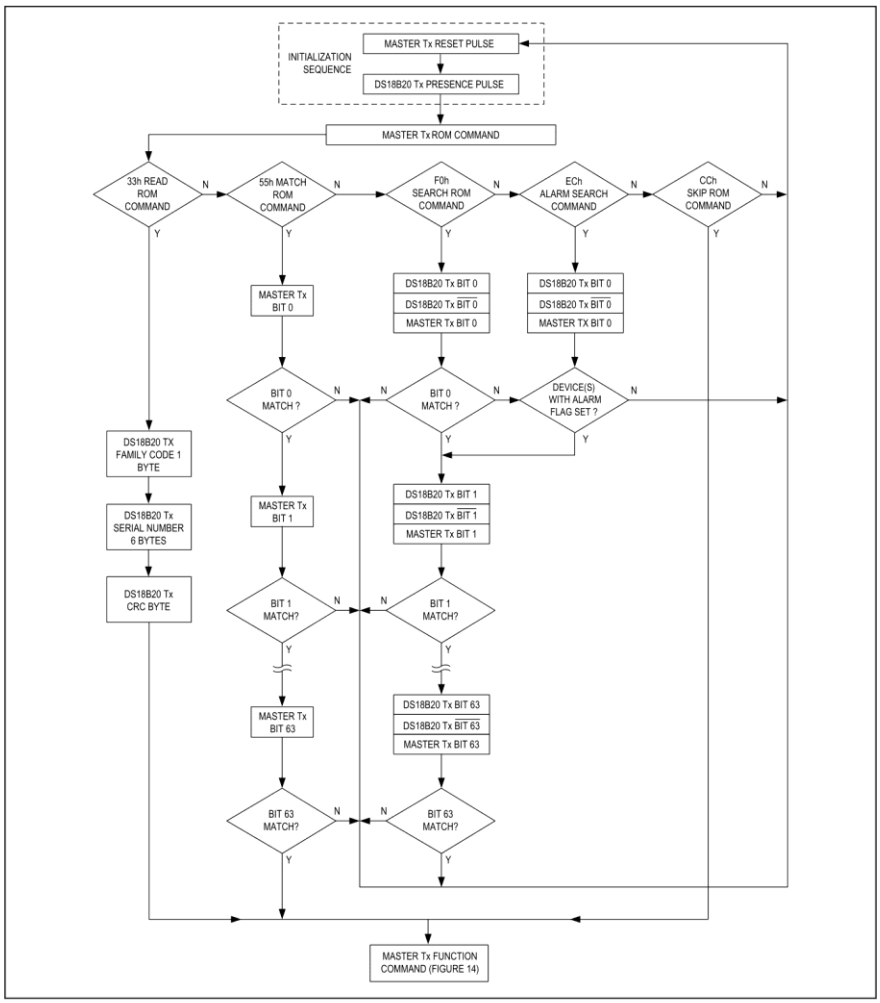


Figure 13. ROM Commands Flowchart

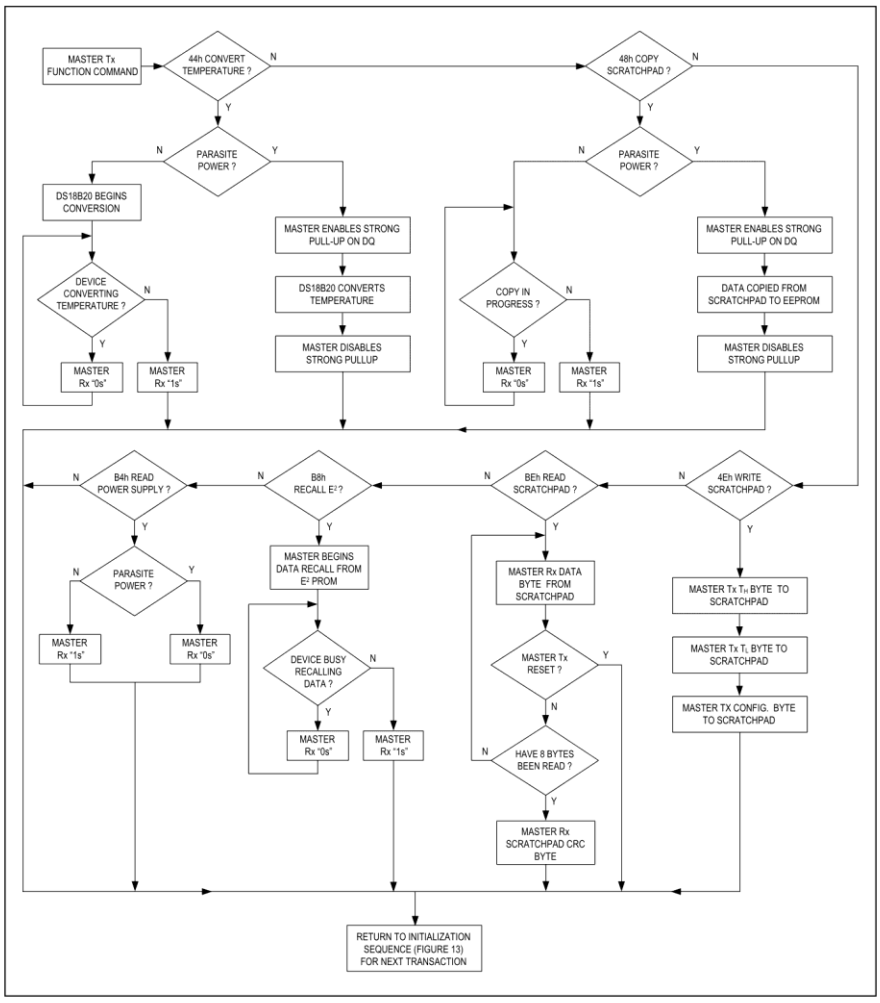


Figure 14. DS18B20 Function Commands Flowchart

1-Wire Signaling

The DS18B20 uses a strict 1-Wire communication protocol to ensure data integrity. Several signal types are defined by this protocol: reset pulse, presence pulse, write 0, write 1, read 0, and read 1. The bus master initiates all these signals, with the exception of the presence pulse.

Initialization Procedure—Reset And Presence Pulses

All communication with the DS18B20 begins with an initialization sequence that consists of a reset pulse from the master followed by a presence pulse from the DS18B20. This is illustrated in Figure 15. When the DS18B20 sends the presence pulse in response to the reset, it is indicating to the master that it is on the bus and ready to operate.

During the initialization sequence the bus master transmits (T_X) the reset pulse by pulling the 1-Wire bus low for a minimum of 480µs. The bus master then releases the bus and goes into receive mode (R_X). When the bus is released, the 5kΩ pullup resistor pulls the 1-Wire bus high. When the DS18B20 detects this rising edge, it waits 15µs to 60µs and then transmits a presence pulse by pulling the 1-Wire bus low for 60µs to 240µs.

Read/Write Time Slots

The bus master writes data to the DS18B20 during write time slots and reads data from the DS18B20 during read time slots. One bit of data is transmitted over the 1-Wire bus per time slot.

Write Time Slots

There are two types of write time slots: “Write 1” time slots and “Write 0” time slots. The bus master uses a Write 1 time slot to write a logic 1 to the DS18B20 and a Write 0 time slot to write a logic 0 to the DS18B20. All write time slots must be a minimum of 60µs in duration with a minimum of a 1µs recovery time between individual write slots. Both types of write time slots are initiated by the master pulling the 1-Wire bus low (see Figure 14).

To generate a Write 1 time slot, after pulling the 1-Wire bus low, the bus master must release the 1-Wire bus within 15µs. When the bus is released, the 5kΩ pullup resistor will pull the bus high. To generate a Write 0 time slot, after pulling the 1-Wire bus low, the bus master must continue to hold the bus low for the duration of the time slot (at least 60µs).

The DS18B20 samples the 1-Wire bus during a window that lasts from 15µs to 60µs after the master initiates the write time slot. If the bus is high during the sampling window, a 1 is written to the DS18B20. If the line is low, a 0 is written to the DS18B20.

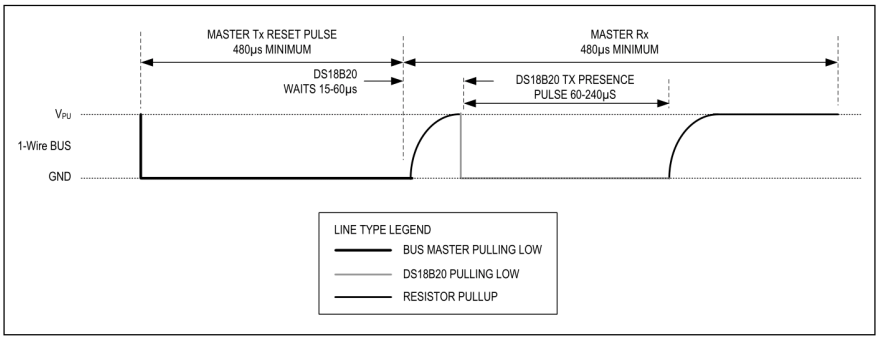


Figure 15. Initialization Timing

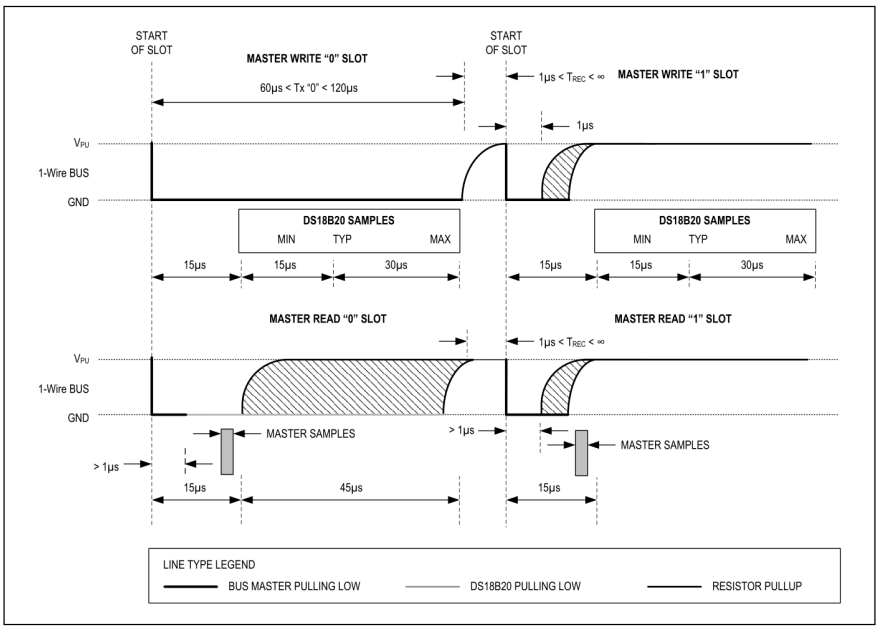


Figure 16. Read/Write Time Slot Timing Diagram

Read Time Slots

The DS18B20 can only transmit data to the master when the master issues read time slots. Therefore, the master must generate read time slots immediately after issuing a Read Scratchpad [BEh] or Read Power Supply [B4h] command, so that the DS18B20 can provide the requested data. In addition, the master can generate read time slots after issuing Convert T [44h] or Recall E^2 [B8h] commands to find out the status of the operation as explained in the *DS18B20 Function Commands* section.

All read time slots must be a minimum of 60µs in duration with a minimum of a 1µs recovery time between slots. A read time slot is initiated by the master device pulling the 1-Wire bus low for a minimum of 1µs and then releasing the bus (see Figure 16). After the master initiates the read time slot, the DS18B20 will begin transmitting a 1 or 0 on bus. The DS18B20 transmits a 1 by leaving the bus high and transmits a 0 by pulling the bus low. When transmitting a 0, the DS18B20 will release the bus by the end of the time slot, and the bus will be pulled back to its high idle state by the pullup resister. Output data from the DS18B20 is valid for 15µs after the falling edge that initiated the read time slot. Therefore, the master must release the bus and then sample the bus state within 15µs from the start of the slot.

Figure 17 illustrates that the sum of T_{INIT}, T_{RC}, and T_{SAMPLE} must be less than 15µs for a read time slot. Figure 18 shows that system timing margin is maximized by keeping T_{INIT} and T_{RC} as short as possible and by locating the master sample time during read time slots towards the end of the 15µs period.

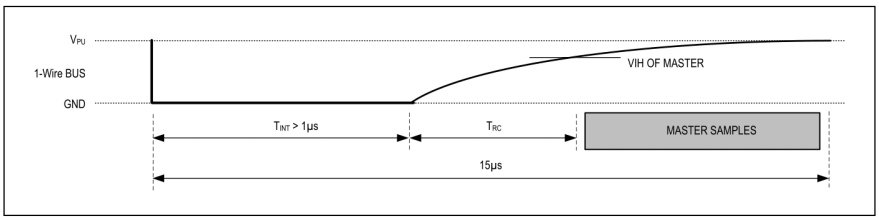


Figure 17. Detailed Master Read 1 Timing

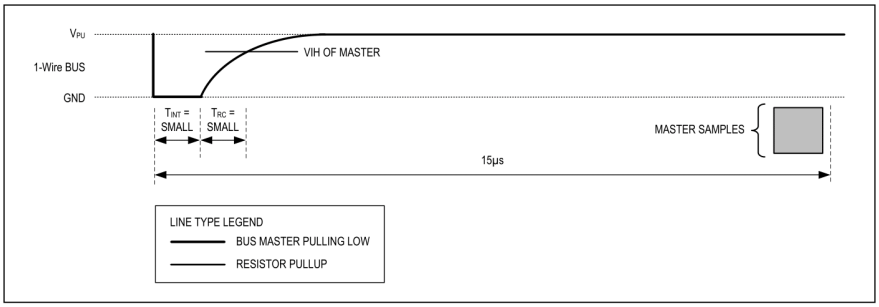


Figure 18. Recommended Master Read 1 Timing

Related Application Notes

The following application notes can be applied to the DS18B20 and are available at www.maximintegrated.com.

Application Note 27: Understanding and Using Cyclic Redundancy Checks with Maxim iButton Products

Application Note 122: Using Dallas' 1-Wire ICs in 1-Cell Li-Ion Battery Packs with Low-Side N-Channel Safety FETs Master

Application Note 126: 1-Wire Communication Through Software

Application Note 162: Interfacing the DS18x20/DS1822 1-Wire Temperature Sensor in a Microcontroller Environment

Application Note 208: Curve Fitting the Error of a Bandgap-Based Digital Temperature Sensor

Application Note 2420: 1-Wire Communication with a Microchip PICmicro Microcontroller

Application Note 3754: Single-Wire Serial Bus Carries Isolated Power and Data

Sample 1-Wire subroutines that can be used in conjunction with A*pplication Note 74: Reading and Writing iButtons via Serial Interfaces* can be downloaded from the Maxim website.

DS18B20 Operation Example 1

In this example there are multiple DS18B20s on the bus and they are using parasite power. The bus master initiates a temperature conversion in a specific DS18B20 and then reads its scratchpad and recalculates the CRC to verify the data.

MASTER MODE	DATA (LSB FIRST)	COMMENTS
Tx	Reset	Master issues reset pulse.
Rx	Presence	DS18B20s respond with presence pulse.
Tx	55h	Master issues Match ROM command.
Tx	64-bit ROM code	Master sends DS18B20 ROM code.
Tx	44h	Master issues Convert T command.
Tx	DQ line held high by strong pullup	Master applies strong pullup to DQ for the duration of the conversion (t_{CONV}).
Tx	Reset	Master issues reset pulse.
Rx	Presence	DS18B20s respond with presence pulse.
Tx	55h	Master issues Match ROM command.
Tx	64-bit ROM code	Master sends DS18B20 ROM code.
Tx	BEh	Master issues Read Scratchpad command.
Rx	9 data bytes	Master reads entire scratchpad including CRC. The master then recalculates the CRC of the first eight data bytes from the scratchpad and compares the calculated CRC with the read CRC (byte 9). If they match, the master continues; if not, the read operation is repeated.

DS18B20 Operation Example 2

In this example there is only one DS18B20 on the bus and it is using parasite power. The master writes to the TH, TL, and configuration registers in the DS18B20 scratchpad and then reads the scratchpad and recalculates the CRC to verify the data. The master then copies the scratchpad contents to EEPROM.

MASTER MODE	DATA (LSB FIRST)	COMMENTS
Tx	Reset	Master issues reset pulse.
Rx	Presence	DS18B20 responds with presence pulse.
Tx	CCh	Master issues Skip ROM command.
Tx	4Eh	Master issues Write Scratchpad command.
Tx	3 data bytes	Master sends three data bytes to scratchpad (T_H, T_L, and config).
Tx	Reset	Master issues reset pulse.
Rx	Presence	DS18B20 responds with presence pulse.
Tx	CCh	Master issues Skip ROM command.
Tx	BEh	Master issues Read Scratchpad command.
Rx	9 data bytes	Master reads entire scratchpad including CRC. The master then recalculates the CRC of the first eight data bytes from the scratchpad and compares the calculated CRC with the read CRC (byte 9). If they match, the master continues; if not, the read operation is repeated.
Tx	Reset	Master issues reset pulse.
Rx	Presence	DS18B20 responds with presence pulse.
Tx	CCh	Master issues Skip ROM command.
Tx	48h	Master issues Copy Scratchpad command.
Tx	DQ line held high by strong pullup	Master applies strong pullup to DQ for at least 10ms while copy operation is in progress.

Ordering Information

PART	TEMP RANGE	PIN-PACKAGE	TOP MARK
DS18B20	-55°C to +125°C	3 TO-92	18B20
DS18B20+	-55°C to +125°C	3 TO-92	18B20
DS18B20/T&R	-55°C to +125°C	3 TO-92 (2000 Piece)	18B20
DS18B20+T&R	-55°C to +125°C	3 TO-92 (2000 Piece)	18B20
DS18B20-SL/T&R	-55°C to +125°C	3 TO-92 (2000 Piece)*	18B20
DS18B20-SL+T&R	-55°C to +125°C	3 TO-92 (2000 Piece)*	18B20
DS18B20U	-55°C to +125°C	8 FSOP	18B20
DS18B20U+	-55°C to +125°C	8 FSOP	18B20
DS18B20U/T&R	-55°C to +125°C	8 FSOP (3000 Piece)	18B20
DS18B20U+T&R	-55°C to +125°C	8 FSOP (3000 Piece)	18B20
DS18B20Z	-55°C to +125°C	8 SO	DS18B20
DS18B20Z+	-55°C to +125°C	8 SO	DS18B20
DS18B20Z/T&R	-55°C to +125°C	8 SO (2500 Piece)	DS18B20
DS18B20Z+T&R	-55°C to +125°C	8 SO (2500 Piece)	DS18B20

+Denotes a lead-free package. A "+" will appear on the top mark of lead-free packages.

T&R = Tape and reel.

**TO-92 packages in tape and reel can be ordered with straight or formed leads. Choose "SL" for straight leads. Bulk TO-92 orders are straight leads only.*

Revision History

REVISION DATE	DESCRIPTION	PAGES CHANGED
030107	In the Absolute Maximum Ratings section, removed the reflow oven temperature value of +220°C. Reference to JEDEC specification for reflow remains.	19
101207	In the *Operation—Alarm Signaling* section, added “or equal to” in the description for a TH alarm condition	5
	In the *Memory* section, removed incorrect text describing memory.	7
	In the *Configuration Register* section, removed incorrect text describing configuration register.	8
042208	In the *Ordering Information* table, added TO-92 straight-lead packages and included a note that the TO-92 package in tape and reel can be ordered with either formed or straight leads.	2
1/15	Updated *Benefits and Features* section	1

Lampiran 7. *Datasheet* Sensor Cairan *Water Level*

Liquid Level Sensor User Manual

1. Features

Operating voltage	2.0V-5.0V
Output type	Analog output
Detectable depth	48mm
Dimensions	19.0mm*63.0mm
Fixing hole size	2.0mm

Operating principle:
This module is an application of the current amplification by a transistor. When the liquid level is high enough to conduct the current between the base and the positive power supply, a certain amount of current is generated between the base and the emitter. And in a mean while, an electric current is produced in a certain amplification factor between the collector and the emitter, and applied to the resistant in the emitter to produce a voltage. Then, this voltage will be collected by an AD converter.

2. Applications

This module can be applied to liquid level alarm system.

3. Interfaces

Pin No.	Symbol	Descriptions
1	AOUT	Analog output
2	GND	Power ground
3	VCC	Positive power supply (3.3V-5.0V)

4. How to use

We will illustrate the usage of the module with an example of liquid level detection by connecting a development board.

① Download the relative codes to the development board.

② Connect the development board to a PC via a serial wire and the module to the development board. Then, power up the development board and start the serial debugging software.
Here is the configuration of the connection between the module and the development board.

Port	STM32 MUC pin
AOUT	GPIOA.6
GND	GND
VCC	3.3V

Port	Arduino pin
AOUT	A0
GND	GND
VCC	5V

Here is the configuration of the serial port.

Baud rate	115200
Data bits	8
Stop bit	1
Parity bit	None

③ Put the module into the water, and the serial output is as followed:

Output on high level	Output on low level
High water level!	High water level!

④ Immerse the sensor into the water deeply. The table below shows the relationship between the output voltage from the AOUT pin and the liquid level.

Liquid level	Output voltage
0cm	0v
0.5cm	1.3v
1cm	1.53v
1.5cm	1.62v
2cm	1.69v
2.5cm	1.74v
3cm	1.77v
3.5cm	1.81v
4cm	1.84v
4.5cm	1.86v
4.8cm	1.88v

Lampiran 8. *Datasheet* RTC DS3231

Rev 4; 10/06

DALLAS SEMICONDUCTOR MAXIM

Extremely Accurate I²C-Integrated RTC/TCXO/Crystal

DS3231

General Description

The DS3231 is a low-cost, extremely accurate I²C real-time clock (RTC) with an integrated temperature-compensated crystal oscillator (TCXO) and crystal. The device incorporates a battery input, and maintains accurate timekeeping when main power to the device is interrupted. The integration of the crystal resonator enhances the long-term accuracy of the device as well as reduces the piece-part count in a manufacturing line. The DS3231 is available in commercial and industrial temperature ranges, and is offered in a 16-pin, 300-mil SO package.

The RTC maintains seconds, minutes, hours, day, date, month, and year information. The date at the end of the month is automatically adjusted for months with fewer than 31 days, including corrections for leap year. The clock operates in either the 24-hour or 12-hour format with an AM/PM indicator. Two programmable time-of-day alarms and a programmable square-wave output are provided. Address and data are transferred serially through an I²C bidirectional bus.

A precision temperature-compensated voltage reference and comparator circuit monitors the status of V_{CC} to detect power failures, to provide a reset output, and to automatically switch to the backup supply when necessary. Additionally, the RST pin is monitored as a pushbutton input for generating a reset externally.

Applications

Servers
Telematics
Utility Power Meters
GPS

Pin Configuration appears at end of data sheet.

Features

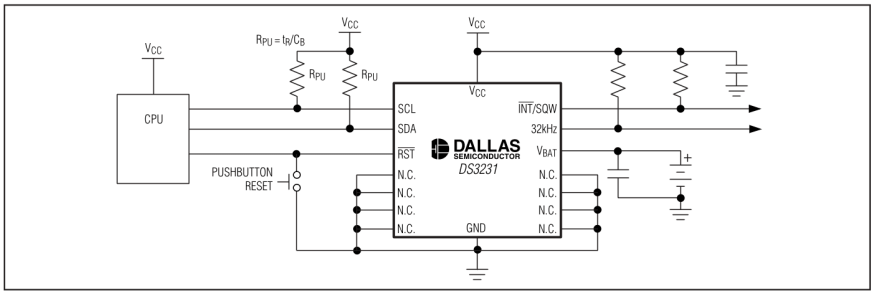
- **Accuracy ±2ppm from 0°C to +40°C**
- **Accuracy ±3.5ppm from -40°C to +85°C**
- **Battery Backup Input for Continuous Timekeeping**
- **Operating Temperature Ranges**
  Commercial: 0°C to +70°C
  Industrial: -40°C to +85°C
- **Low-Power Consumption**
- **Real-Time Clock Counts Seconds, Minutes, Hours, Day, Date, Month, and Year with Leap Year Compensation Valid Up to 2100**
- **Two Time-of-Day Alarms**
- **Programmable Square-Wave Output**
- **Fast (400kHz) I²C Interface**
- **3.3V Operation**
- **Digital Temp Sensor Output: ±3°C Accuracy**
- **Register for Aging Trim**
- **RST Output/Pushbutton Reset Debounce Input**
- **Underwriters Laboratory (UL) Recognized**

Ordering Information

PART	TEMP RANGE	PIN-PACKAGE	TOP MARK
DS3231S	0°C to +70°C	16 SO	DS3231
DS3231SN	-40°C to +85°C	16 SO	DS3231N
DS3231S#	0°C to +70°C	16 SO	DS3231S
DS3231SN#	-40°C to +85°C	16 SO	DS3231SN

 # Denotes a RoHS-compliant device that may include lead that is exempt under RoHS requirements. The lead finish is JESD97 category e3, and is compatible with both lead-based and lead-free soldering processes. A "#" anywhere on the top mark denotes a RoHS-compliant device.

Typical Operating Circuit



For pricing, delivery, and ordering information, please contact Maxim/Dallas Direct! at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

ABSOLUTE MAXIMUM RATINGS

Voltage Range on V_{CC}, V_{BAT}, 32kHz, SCL, SDA, $\overline{RST}$, $\overline{INT}$/SQW Relative to Ground.....-0.3V to +6.0V
Operating Temperature Range (noncondensing) .....-40°C to +85°C
Junction Temperature.....+125°C
Storage Temperature Range .....-40°C to +85°C
Lead Temperature (Soldering, 10s).....+260°C/10s
Soldering Temperature.....See the *Handling, PC Board Layout, and Assembly* section.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

RECOMMENDED DC OPERATING CONDITIONS

(T_A = T_{MIN} to T_{MAX}, unless otherwise noted.) (Notes 1, 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Supply Voltage	V_{CC}		2.3	3.3	5.5	V
	V_{BAT}		2.3	3.0	5.5	V
Logic 1 Input SDA, SCL	V_{IH}		0.7 x V_{CC}		V_{CC} + 0.3	V
Logic 0 Input SDA, SCL	V_{IL}		-0.3		+0.3 x V_{CC}	V
Pullup Voltage (SDA, SCL, 32kHz, $\overline{INT}$/SQW)	V_{PU}	V_{CC} = 0V			5.5V	V

ELECTRICAL CHARACTERISTICS

(V_{CC} = 2.3V to 5.5V, V_{CC} = Active Supply (see Table 1), T_A = T_{MIN} to T_{MAX}, unless otherwise noted.) (Typical values are at V_{CC} = 3.3V, V_{BAT} = 3.0V, and T_A = +25°C, unless otherwise noted.) (Notes 1, 2)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Active Supply Current	I_{CCA}	(Notes 3, 4)	V_{CC} = 3.63V			200	µA
			V_{CC} = 5.5V			300	
Standby Supply Current	I_{CCS}	I²C bus inactive, 32kHz output on, SQW output off (Note 4)	V_{CC} = 3.63V			110	µA
			V_{CC} = 5.5V			170	
Temperature Conversion Current	$I_{CCSCONV}$	I²C bus inactive, 32kHz output on, SQW output off	V_{CC} = 3.63V			575	µA
			V_{CC} = 5.5V			650	
Power-Fail Voltage	V_{PF}			2.45	2.575	2.70	V
Logic 0 Output, 32kHz, $\overline{INT}$/SQW, SDA	V_{OL}	I_{OL} = 3mA				0.4	V
Logic 0 Output, $\overline{RST}$	V_{OL}	I_{OL} = 1mA				0.4	V
Output Leakage Current 32kHz, $\overline{INT}$/SQW, SDA	I_{LO}	Output high impedance		-1	0	+1	µA
Input Leakage SCL	I_{LI}			-1		+1	µA
$\overline{RST}$ Pin I/O Leakage	I_{OL}	$\overline{RST}$ high impedance (Note 5)		-200		+10	µA
V_{BAT} Leakage Current (V_{CC} Active)	I_{BATLKG}				25	100	nA

ELECTRICAL CHARACTERISTICS (continued)

(V_{CC} = 2.3V to 5.5V, V_{CC} = Active Supply (see Table 1), T_A = T_{MIN} to T_{MAX}, unless otherwise noted.) (Typical values are at V_{CC} = 3.3V, V_{BAT} = 3.0V, and T_A = +25°C, unless otherwise noted.) (Notes 1, 2)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Output Frequency	f_{OUT}	V_{CC} = 3.3V or V_{BAT} = 3.3V			32.768		kHz
Frequency Stability vs. Temperature (Commercial)	$\Delta f/f_{OUT}$	V_{CC} = 3.3V or V_{BAT} = 3.3V, aging offset = 00h	0°C to +40°C			±2	ppm
			>40°C to +70°C			±3.5	
Frequency Stability vs. Temperature (Industrial)	$\Delta f/f_{OUT}$	V_{CC} = 3.3V or V_{BAT} = 3.3V, aging offset = 00h	-40°C to <0°C			±3.5	ppm
			0°C to +40°C			±2	
			>40°C to +85°C			±3.5	
Frequency Stability vs. Voltage	$\Delta f/V$				1		ppm/V
Trim Register Frequency Sensitivity per LSB	$\Delta f/LSB$	Specified at:	-40°C		0.7		ppm
			+25°C		0.1		
			+70°C		0.4		
			+85°C		0.8		
Temperature Accuracy	Temp	V_{CC} = 3.3V or V_{BAT} = 3.3V		-3		+3	°C
Crystal Aging	$\Delta f/f_0$	After reflow, not production tested	First year		±1.0		ppm
			0–10 years		±5.0		

ELECTRICAL CHARACTERISTICS

(**V_{CC} = 0V, V_{BAT} = 2.3V to 5.5V**, T_A = T_{MIN} to T_{MAX}, unless otherw.ise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Active Battery Current	I_{BATA}	$\overline{EOSC}$ = 0, BBSQW = 0, SCL = 400kHz (Note 4)	V_{BAT} = 3.63V			70	µA
			V_{BAT} = 5.5V			150	
Timekeeping Battery Current	I_{BATT}	$\overline{EOSC}$ = 0, BBSQW = 0, EN32kHz = 1, SCL = SDA = 0V or SCL = SDA = V_{BAT} (Note 4)	V_{BAT} = 3.63V		0.84	3.0	µA
			V_{BAT} = 5.5V		1.0	3.5	
Temperature Conversion Current	I_{BATTC}	$\overline{EOSC}$ = 0, BBSQW = 0, SCL = SDA = 0V or SCL = SDA = V_{BAT}	V_{BAT} = 3.63V			575	µA
			V_{BAT} = 5.5V			650	
Data-Retention Current	I_{BATTDR}	$\overline{EOSC}$ = 1, SCL = SDA = 0V, +25°C				100	nA

AC ELECTRICAL CHARACTERISTICS

(V_{CC} = $V_{CC(MIN)}$ to $V_{CC(MAX)}$ or V_{BAT} = $V_{BAT(MIN)}$ to $V_{BAT(MAX)}$, V_{BAT} > V_{CC}, T_A = T_{MIN} to T_{MAX}, unless otherwise noted.) (Note 1)

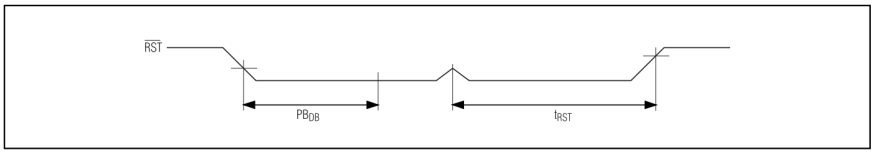
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
SCL Clock Frequency	f_{SCL}	Fast mode	100		400	kHz
		Standard mode	0		100	
Bus Free Time Between STOP and START Conditions	t_{BUF}	Fast mode	1.3			µs
		Standard mode	4.7			
Hold Time (Repeated) START Condition (Note 6)	$t_{HD:STA}$	Fast mode	0.6			µs
		Standard mode	4.0			
Low Period of SCL Clock	t_{LOW}	Fast mode	1.3			µs
		Standard mode	4.7			
High Period of SCL Clock	t_{HIGH}	Fast mode	0.6			µs
		Standard mode	4.0			
Data Hold Time (Notes 7, 8)	$t_{HD:DAT}$	Fast mode	0		0.9	µs
		Standard mode	0		0.9	
Data Setup Time (Note 9)	$t_{SU:DAT}$	Fast mode	100			ns
		Standard mode	250			
Start Setup Time	$t_{SU:STA}$	Fast mode	0.6			µs
		Standard mode	4.7			
Rise Time of Both SDA and SCL Signals (Note 10)	t_R	Fast mode	20 + 0.1C_B		300	ns
		Standard mode			1000	
Fall Time of Both SDA and SCL Signals (Note 10)	t_F	Fast mode	20 + 0.1C_B		300	ns
		Standard mode			300	
Setup Time for STOP Condition	$t_{SU:STO}$	Fast mode	0.6			µs
		Standard mode	4.7			
Capacitive Load for Each Bus Line (Note 10)	C_B				400	pF
Capacitance for SDA, SCL	$C_{I/O}$			10		pF
Pulse Width of Spikes That Must Be Suppressed by the Input Filter	t_{SP}			30		ns
Pushbutton Debounce	PB_{DB}			250		ms
Reset Active Time	t_{RST}			250		ms
Oscillator Stop Flag (OSF) Delay	t_{OSF}	(Note 11)		100		ms
Temperature Conversion Time	t_{CONV}			125	200	ms

POWER-SWITCH CHARACTERISTICS

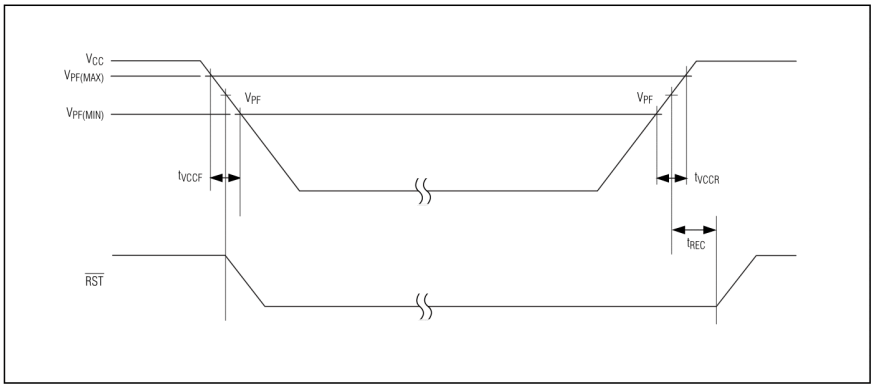
(T_A = T_{MIN} to T_{MAX})

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
V_{CC} Fall Time; $V_{PF(MAX)}$ to $V_{PF(MIN)}$	t_{VCCF}		300			µs
V_{CC} Rise Time; $V_{PF(MIN)}$ to $V_{PF(MAX)}$	t_{VCCR}		0			µs
Recovery at Power-Up	t_{REC}	(Note 12)		250	300	ms

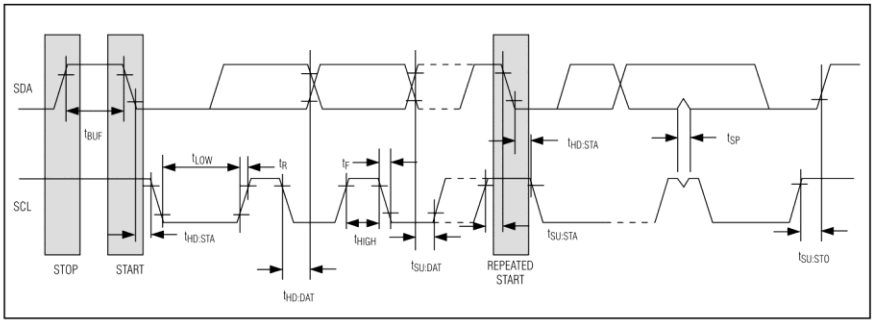
Pushbutton Reset Timing



Power-Switch Timing



Data Transfer on I²C Serial Bus

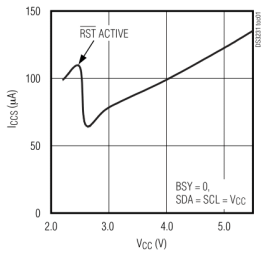


Note 1: Limits at -40°C are guaranteed by design and not production tested.
Note 2: All voltages are referenced to ground.
Note 3: I_{CCA}—SCL clocking at max frequency = 400kHz.
Note 4: Current is the averaged input current, which includes the temperature conversion current.
Note 5: The $\overline{RST}$ pin has an internal 50kΩ (nominal) pullup resistor to V_{CC}.
Note 6: After this period, the first clock pulse is generated.
Note 7: A device must internally provide a hold time of at least 300ns for the SDA signal (referred to the $V_{IH(MIN)}$ of the SCL signal) to bridge the undefined region of the falling edge of SCL.
Note 8: The maximum $t_{HD:DAT}$ needs only to be met if the device does not stretch the low period (t_{LOW}) of the SCL signal.
Note 9: A fast-mode device can be used in a standard-mode system, but the requirement $t_{SU:DAT} \geq 250ns$ must then be met. This is automatically the case if the device does not stretch the low period of the SCL signal. If such a device does stretch the low period of the SCL signal, it must output the next data bit to the SDA line $t_{R(MAX)} + t_{SU:DAT} = 1000 + 250 = 1250ns$ before the SCL line is released.
Note 10: C_B—total capacitance of one bus line in pF.
Note 11: The parameter t_{OSF} is the period of time the oscillator must be stopped for the OSF flag to be set over the voltage range of $0.0V \leq V_{CC} \leq V_{CC(MAX)}$ and $2.3V \leq V_{BAT} \leq 3.4V$.
Note 12: This delay applies only if the oscillator is enabled and running. If the $\overline{EOSC}$ bit is a 1, t_{REC} is bypassed and $\overline{RST}$ immediately goes high.

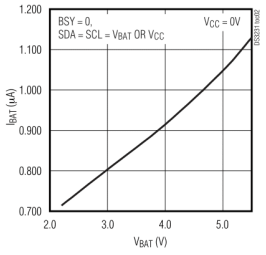
Typical Operating Characteristics

(V_{CC} = +3.3V, T_A = +25°C, unless otherwise noted.)

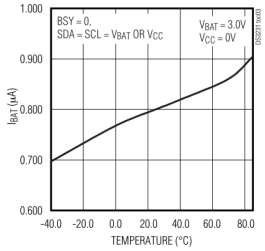
STANDBY SUPPLY CURRENT vs. SUPPLY VOLTAGE



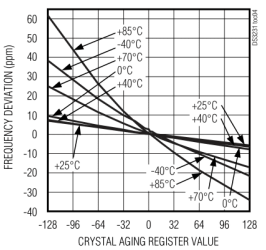
SUPPLY CURRENT vs. SUPPLY VOLTAGE



SUPPLY CURRENT vs. TEMPERATURE

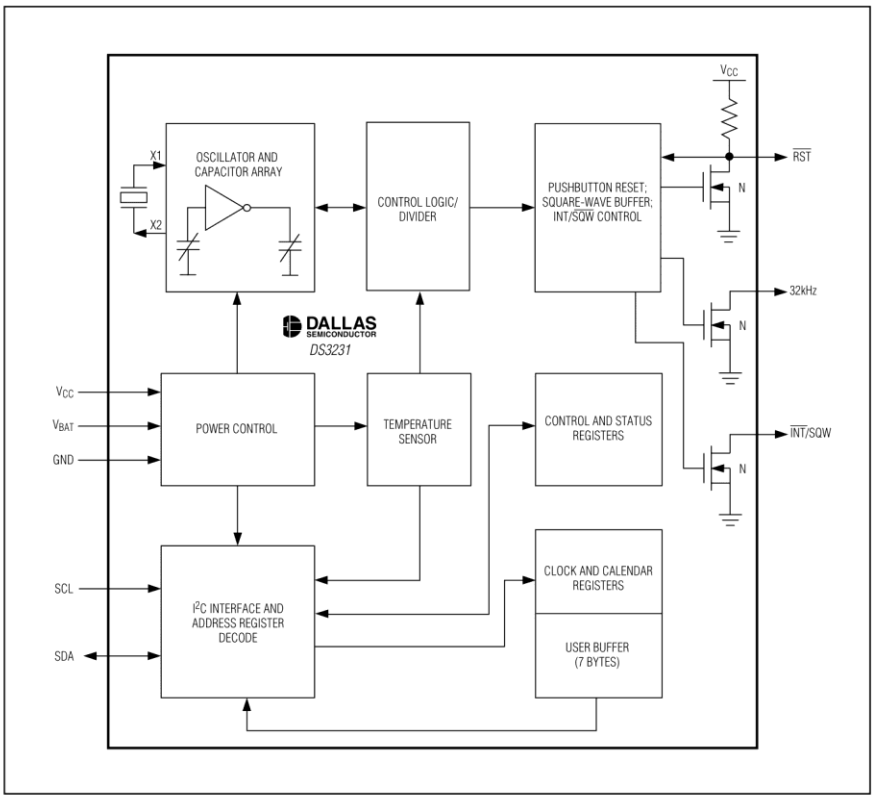


FREQUENCY DEVIATION vs. TEMPERATURE vs. AGING VALUE



Extremely Accurate I²C-Integrated RTC/TCXO/Crystal

Block Diagram



Pin Description

PIN	NAME	FUNCTION
1	32kHz	32kHz Output. This open-drain pin requires an external pullup resistor. When enabled, the output operates on either power supply. It may be left open if not used.
2	V_{CC}	DC Power Pin for Primary Power Supply. This pin should be decoupled using a 0.1µF to 1.0µF capacitor. If not used, connect to ground.
3	$\overline{INT}$/SQW	Active-Low Interrupt or Square-Wave Output. This open-drain pin requires an external pullup resistor connected to a supply at 5.5V or less. It may be left open if not used. This multifunction pin is determined by the state of the INTCN bit in the Control Register (0Eh). When INTCN is set to logic 0, this pin outputs a square wave and its frequency is determined by RS2 and RS1 bits. When INTCN is set to logic 1, then a match between the timekeeping registers and either of the alarm registers activates the $\overline{INT}$/SQW pin (if the alarm is enabled). Because the INTCN bit is set to logic 1 when power is first applied, the pin defaults to an interrupt output with alarms disabled.
4	$\overline{RST}$	Active-Low Reset. This pin is an open-drain input/output. It indicates the status of V_{CC} relative to the V_{PF} specification. As V_{CC} falls below V_{PF}, the $\overline{RST}$ pin is driven low. When V_{CC} exceeds V_{PF}, for t_{RST}, the $\overline{RST}$ pin is pulled high by the internal pullup resistor. The active-low, open-drain output is combined with a debounced pushbutton input function. This pin can be activated by a pushbutton reset request. It has an internal 50kΩ nominal value pullup resistor to V_{CC}. No external pullup resistors should be connected. If the oscillator is disabled, t_{REC} is bypassed and $\overline{RST}$ immediately goes high.
5–12	N.C.	No Connection. Must be connected to ground.
13	GND	Ground
14	V_{BAT}	Backup Power-Supply Input. This pin should be decoupled using a 0.1µF to 1.0µF low-leakage capacitor. If the I²C interface is inactive whenever the device is powered by the V_{BAT} input, the decoupling capacitor is not required. If V_{BAT} is not used, connect to ground. UL recognized to ensure against reverse charging when used with a lithium battery. Go to www.maxim-ic.com/qa/info/ul.
15	SDA	Serial Data Input/Output. This pin is the data input/output for the I²C serial interface. This open-drain pin requires an external pullup resistor.
16	SCL	Serial Clock Input. This pin is the clock input for the I²C serial interface and is used to synchronize data movement on the serial interface.

Detailed Description

The DS3231 is a serial RTC driven by a temperature-compensated 32kHz crystal oscillator. The TCXO provides a stable and accurate reference clock, and maintains the RTC to within ±2 minutes per year accuracy from -40°C to +85°C. The TCXO frequency output is available at the 32kHz pin. The RTC is a low-power clock/calendar with two programmable time-of-day alarms and a programmable square-wave output. The $\overline{INT}$/SQW provides either an interrupt signal due to alarm conditions or a square-wave output. The clock/calendar provides seconds, minutes, hours, day, date, month, and year information. The date at the end of the month is automatically adjusted for months with fewer than 31 days, including corrections for leap year. The clock operates in either the 24-hour or 12-hour format with an $\overline{AM}$/PM indicator. The internal registers are accessible though an I²C bus interface.

A temperature-compensated voltage reference and comparator circuit monitors the level of V_{CC} to detect power failures and to automatically switch to the back-up supply when necessary. The $\overline{RST}$ pin provides an external pushbutton function and acts as an indicator of a power-fail event.

Extremely Accurate I²C-Integrated RTC/TCXO/Crystal

Operation

The block diagram shows the main elements of the DS3231. The eight blocks can be grouped into four functional groups: TCXO, power control, pushbutton function, and RTC. Their operations are described separately in the following sections.

32kHz TCXO

The temperature sensor, oscillator, and control logic form the TCXO. The controller reads the output of the on-chip temperature sensor and uses a lookup table to determine the capacitance required, adds the aging correction in AGE register, and then sets the capacitance selection registers. New values, including changes to the AGE register, are loaded only when a change in the temperature value occurs, or when a user-initiated temperature conversion is completed. The temperature is read on initial application of V_{CC} and once every 64 seconds afterwards.

Power Control

This function is provided by a temperature-compensated voltage reference and a comparator circuit that monitors the V_{CC} level. When V_{CC} is greater than V_{PF}, the part is powered by V_{CC}. When V_{CC} is less than V_{PF} but greater than V_{BAT}, the DS3231 is powered by V_{CC}. If V_{CC} is less than V_{PF} and is less than V_{BAT}, the device is powered by V_{BAT}. See Table 1.

Table 1. Power Control

SUPPLY CONDITION	ACTIVE SUPPLY
$V_{CC} < V_{PF}$, $V_{CC} < V_{BAT}$	V_{BAT}
$V_{CC} < V_{PF}$, $V_{CC} > V_{BAT}$	V_{CC}
$V_{CC} > V_{PF}$, $V_{CC} < V_{BAT}$	V_{CC}
$V_{CC} > V_{PF}$, $V_{CC} > V_{BAT}$	V_{CC}

To preserve the battery, the first time V_{BAT} is applied to the device, the oscillator will not start up until V_{CC} exceeds V_{PF}, or until a valid I²C address is written to the part. Typical oscillator startup time is less than one second. Approximately 2 seconds after V_{CC} is applied, or a valid I²C address is written, the device makes a temperature measurement and applies the calculated correction to the oscillator. Once the oscillator is running, it continues to run as long as a valid power source is available (V_{CC} or V_{BAT}), and the device continues to measure the temperature and correct the oscillator frequency every 64 seconds.

Pushbutton Reset Function

The DS3231 provides for a pushbutton switch to be connected to the $\overline{RST}$ output pin. When the DS3231 is not in a reset cycle, it continuously monitors the $\overline{RST}$ signal for a low going edge. If an edge transition is detected, the DS3231 debounces the switch by pulling the $\overline{RST}$ low. After the internal timer has expired (PB_{DB}), the DS3231 continues to monitor the $\overline{RST}$ line. If the line is still low, the DS3231 continuously monitors the line looking for a rising edge. Upon detecting release, the DS3231 forces the $\overline{RST}$ pin low and holds it low for t_{RST}.

The same pin, $\overline{RST}$, is used to indicate a power-fail condition. When V_{CC} is lower than V_{PF}, an internal power-fail signal is generated, which forces the $\overline{RST}$ pin low. When V_{CC} returns to a level above V_{PF}, the $\overline{RST}$ pin is held low for approximately 250ms (t_{REC}) to allow the power supply to stabilize. If the oscillator is not running (see the *Power Control* section) when V_{CC} is applied, t_{REC} is bypassed and $\overline{RST}$ immediately goes high.

Real-Time Clock

With the clock source from the TCXO, the RTC provides seconds, minutes, hours, day, date, month, and year information. The date at the end of the month is automatically adjusted for months with fewer than 31 days, including corrections for leap year. The clock operates in either the 24-hour or 12-hour format with an $\overline{AM}$/PM indicator.

The clock provides two programmable time-of-day alarms and a programmable square-wave output. The $\overline{INT}$/SQW pin either generates an interrupt due to alarm condition or outputs a square-wave signal and the selection is controlled by the bit INTCN.

Address Map

Figure 1 shows the address map for the DS3231 timekeeping registers. During a multibyte access, when the address pointer reaches the end of the register space (12h), it wraps around to location 00h. On an I²C START or address pointer incrementing to location 00h, the current time is transferred to a second set of registers. The time information is read from these secondary registers, while the clock may continue to run. This eliminates the need to reread the registers in case the main registers update during a read.

I²C Interface

The I²C interface is accessible whenever either V_{CC} or V_{BAT} is at a valid level. If a microcontroller connected to the DS3231 resets because of a loss of V_{CC} or other event, it is possible that the microcontroller and DS3231 I²C communications could become unsynchronized, e.g., the microcontroller resets while reading data from the DS3231. When the microcontroller resets, the

Figure 1. Timekeeing Registers

ADDRESS	BIT 7 MSB	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0 LSB	FUNCTION	RANGE
00H	0	10 Seconds			Seconds				Seconds	00–59
01H	0	10 Minutes			Minutes				Minutes	00–59
02H	0	12/$\overline{24}$	$\overline{AM}$/PM 10 Hour	10 Hour	Hour				Hours	1–12 + $\overline{AM}$/PM 00–23
03H	0	0	0	0	0	Day			Day	1–7
04H	0	0	10 Date		Date				Date	00–31
05H	Century	0	0	10 Month	Month				Month/ Century	01–12 + Century
06H	10 Year				Year				Year	00–99
07H	A1M1	10 Seconds			Seconds				Alarm 1 Seconds	00–59
08H	A1M2	10 Minutes			Minutes				Alarm 1 Minutes	00–59
09H	A1M3	12/$\overline{24}$	$\overline{AM}$/PM 10 Hour	10 Hour	Hour				Alarm 1 Hours	1–12 + $\overline{AM}$/PM 00–23
0AH	A1M4	DY/$\overline{DT}$	10 Date		Day				Alarm 1 Day	1–7
					Date				Alarm 1 Date	1–31
0BH	A2M2	10 Minutes			Minutes				Alarm 2 Minutes	00–59
0CH	A2M3	12/$\overline{24}$	$\overline{AM}$/PM 10 Hour	10 Hour	Hour				Alarm 2 Hours	1–12 + $\overline{AM}$/PM 00–23
0DH	A2M4	DY/$\overline{DT}$	10 Date		Day				Alarm 2 Day	1–7
					Date				Alarm 2 Date	1–31
0EH	$\overline{EOSC}$	BBSQW	CONV	RS2	RS1	INTCN	A2IE	A1IE	Control	—
0FH	OSF	0	0	0	EN32kHz	BSY	A2F	A1F	Control/Status	—
10H	SIGN	DATA	DATA	DATA	DATA	DATA	DATA	DATA	Aging Offset	—
11H	SIGN	DATA	DATA	DATA	DATA	DATA	DATA	DATA	MSB of Temp	—
12H	DATA	DATA	0	0	0	0	0	0	LSB of Temp	—

Note: *Unless otherwise specified, the registers' state is not defined when power is first applied.*

DS3231 I²C interface may be placed into a known state by toggling SCL until SDA is observed to be at a high level. At that point the microcontroller should pull SDA low while SCL is high, generating a START condition.

Clock and Calendar

The time and calendar information is obtained by reading the appropriate register bytes. Figure 1 illustrates the RTC registers. The time and calendar data are set or initialized by writing the appropriate register bytes. The contents of the time and calendar registers are in the binary-coded decimal (BCD) format. The DS3231 can be run in either 12-hour or 24-hour mode. Bit 6 of the hours register is defined as the 12- or 24-hour mode select bit. When high, the 12-hour mode is selected. In the 12-hour mode, bit 5 is the $\overline{AM}$/PM bit with logic-high being PM. In the 24-hour mode, bit 5 is the second 10-hour bit (20–23 hours). The century bit (bit 7 of the month register) is toggled when the years register overflows from 99 to 00.

The day-of-week register increments at midnight. Values that correspond to the day of week are user-defined but must be sequential (i.e., if 1 equals Sunday, then 2 equals Monday, and so on). Illogical time and date entries result in undefined operation.

When reading or writing the time and date registers, secondary (user) buffers are used to prevent errors when the internal registers update. When reading the time and date registers, the user buffers are synchronized to the internal registers on any START and when the register pointer rolls over to zero. The time information is read from these secondary registers, while the clock continues to run. This eliminates the need to reread the registers in case the main registers update during a read.

The countdown chain is reset whenever the seconds register is written. Write transfers occur on the acknowledge from the DS3231. Once the countdown chain is reset, to avoid rollover issues the remaining time and date registers must be written within 1 second. The 1Hz square-wave output, if enabled, transitions high 500ms after the seconds data transfer, provided the oscillator is already running.

Alarms

The DS3231 contains two time-of-day/date alarms. Alarm 1 can be set by writing to registers 07h to 0Ah. Alarm 2 can be set by writing to registers 0Bh to 0Dh. The alarms can be programmed (by the alarm enable and INTCN bits of the control register) to activate the $\overline{INT}$/SQW output on an alarm match condition. Bit 7 of each of the time-of-day/date alarm registers are mask bits (Table 2). When all the mask bits for each alarm are logic 0, an alarm only occurs when the values in the timekeeping registers match the corresponding values stored in the time-of-day/date alarm registers. The alarms can also be programmed to repeat every second, minute, hour, day, or date. Table 2 shows the possible settings. Configurations not listed in the table will result in illogical operation.

The DY/$\overline{DT}$ bits (bit 6 of the alarm day/date registers) control whether the alarm value stored in bits 0 to 5 of that register reflects the day of the week or the date of the month. If DY/$\overline{DT}$ is written to logic 0, the alarm will be the result of a match with date of the month. If DY/$\overline{DT}$ is written to logic 1, the alarm will be the result of a match with day of the week.

When the RTC register values match alarm register settings, the corresponding Alarm Flag 'A1F' or 'A2F' bit is set to logic 1. If the corresponding Alarm Interrupt Enable 'A1IE' or 'A2IE' is also set to logic 1 and the INTCN bit is set to logic 1, the alarm condition will activate the $\overline{INT}$/SQW signal. The match is tested on the once-per-second update of the time and date registers.

Table 2. Alarm Mask Bits

DY/$\overline{DT}$	ALARM 1 REGISTER MASK BITS (BIT 7)				ALARM RATE
	A1M4	A1M3	A1M2	A1M1	
X	1	1	1	1	Alarm once per second
X	1	1	1	0	Alarm when seconds match
X	1	1	0	0	Alarm when minutes and seconds match
X	1	0	0	0	Alarm when hours, minutes, and seconds match
0	0	0	0	0	Alarm when date, hours, minutes, and seconds match
1	0	0	0	0	Alarm when day, hours, minutes, and seconds match

DY/$\overline{DT}$	ALARM 2 REGISTER MASK BITS (BIT 7)			ALARM RATE
	A2M4	A2M3	A2M2	
X	1	1	1	Alarm once per minute (00 seconds of every minute)
X	1	1	0	Alarm when minutes match
X	1	0	0	Alarm when hours and minutes match
0	0	0	0	Alarm when date, hours, and minutes match
1	0	0	0	Alarm when day, hours, and minutes match

Control Register (0Eh)

BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
$\overline{EOSC}$	BBSQW	CONV	RS2	RS1	INTCN	A2IE	A1IE

Special-Purpose Registers

The DS3231 has two additional registers (control and status) that control the real-time clock, alarms, and square-wave output.

Control Register (0Eh)

Bit 7: Enable Oscillator ($\overline{EOSC}$). When set to logic 0, the oscillator is started. When set to logic 1, the oscillator is stopped when the DS3231 switches to V_{BAT}. This bit is clear (logic 0) when power is first applied. When the DS3231 is powered by V_{CC}, the oscillator is always on regardless of the status of the $\overline{EOSC}$ bit.

Bit 6: Battery-Backed Square-Wave Enable (BBSQW). When set to logic 1 and the DS3231 is being powered by the V_{BAT} pin, this bit enables the square-wave or interrupt output when V_{CC} is absent. When BBSQW is logic 0, the $\overline{INT}$/SQW pin goes high impedance when V_{CC} falls below the power-fail trip point. This bit is disabled (logic 0) when power is first applied.

Bit 5: Convert Temperature (CONV). Setting this bit to 1 forces the temperature sensor to convert the temperature into digital code and execute the TCXO algorithm to update the capacitance array to the oscillator. This can only happen when a conversion is not already in progress. The user should check the status bit BSY before forcing the controller to start a new TCXO execution. A user-initiated temperature conversion does not affect the internal 64-second update cycle.

A user-initiated temperature conversion does not affect the BSY bit for approximately 2ms. The CONV bit remains at a 1 from the time it is written until the conversion is finished, at which time both CONV and BSY go to 0. The CONV bit should be used when monitoring the status of a user-initiated conversion.

Bits 4 and 3: Rate Select (RS2 and RS1). These bits control the frequency of the square-wave output when the square wave has been enabled. The following table shows the square-wave frequencies that can be selected with the RS bits. These bits are both set to logic 1 (8.192kHz) when power is first applied.

SQUARE-WAVE OUTPUT FREQUENCY

RS2	RS1	SQUARE-WAVE OUTPUT FREQUENCY
0	0	1Hz
0	1	1.024kHz
1	0	4.096kHz
1	1	8.192kHz

Bit 2: Interrupt Control (INTCN). This bit controls the $\overline{INT}$/SQW signal. When the INTCN bit is set to logic 0, a square wave is output on the $\overline{INT}$/SQW pin. When the INTCN bit is set to logic 1, then a match between the timekeeping registers and either of the alarm registers activates the $\overline{INT}$/SQW output (if the alarm is also enabled). The corresponding alarm flag is always set regardless of the state of the INTCN bit. The INTCN bit is set to logic 1 when power is first applied.

Bit 1: Alarm 2 Interrupt Enable (A2IE). When set to logic 1, this bit permits the alarm 2 flag (A2F) bit in the status register to assert $\overline{INT}$/SQW (when INTCN = 1). When the A2IE bit is set to logic 0 or INTCN is set to logic 0, the A2F bit does not initiate an interrupt signal. The A2IE bit is disabled (logic 0) when power is first applied.

Bit 0: Alarm 1 Interrupt Enable (A1IE). When set to logic 1, this bit permits the alarm 1 flag (A1F) bit in the status register to assert $\overline{INT}$/SQW (when INTCN = 1). When the A1IE bit is set to logic 0 or INTCN is set to logic 0, the A1F bit does not initiate the $\overline{INT}$/SQW signal. The A1IE bit is disabled (logic 0) when power is first applied.

Status Register (0Fh)

BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
OSF	0	0	0	EN32kHz	BSY	A2F	A1F

Status Register (0Fh)

Bit 7: Oscillator Stop Flag (OSF). A logic 1 in this bit indicates that the oscillator either is stopped or was stopped for some period and may be used to judge the validity of the timekeeping data. This bit is set to logic 1 any time that the oscillator stops. The following are examples of conditions that can cause the OSF bit to be set:

1) The first time power is applied.
2) The voltages present on both V_{CC} and V_{BAT} are insufficient to support oscillation.
3) The $\overline{EOSC}$ bit is turned off in battery-backed mode.
4) External influences on the crystal (i.e., noise, leakage, etc.).

This bit remains at logic 1 until written to logic 0.

Bit 3: Enable 32kHz Output (EN32kHz). This bit controls the status of the 32kHz pin. When set to logic 1, the 32kHz pin is enabled and outputs a 32.768kHz square-wave signal. When set to logic 0, the 32kHz pin goes to a high-impedance state. The initial power-up state of this bit is logic 1, and a 32.768kHz square-wave signal appears at the 32kHz pin after a power source is applied to the DS3231 (if the oscillator is running).

Bit 2: Busy (BSY). This bit indicates the device is busy executing TCXO functions. It goes to logic 1 when the conversion signal to the temperature sensor is asserted and then is cleared when the device is in the 1-minute idle state.

Bit 1: Alarm 2 Flag (A2F). A logic 1 in the alarm 2 flag bit indicates that the time matched the alarm 2 registers. If the A2IE bit is logic 1 and the INTCN bit is set to logic 1, the $\overline{INT}$/SQW pin is also asserted. A2F is cleared when written to logic 0. This bit can only be written to logic 0. Attempting to write to logic 1 leaves the value unchanged.

Bit 0: Alarm 1 Flag (A1F). A logic 1 in the alarm 1 flag bit indicates that the time matched the alarm 1 registers. If the A1IE bit is logic 1 and the INTCN bit is set to logic 1, the $\overline{INT}$/SQW pin is also asserted. A1F is cleared when written to logic 0. This bit can only be written to logic 0. Attempting to write to logic 1 leaves the value unchanged.

Aging Offset

The crystal aging offset register provides an 8-bit code to add to the codes in the capacitance array registers. The code is encoded in two's complement. One LSB represents one small capacitor to be switched in or out of the capacitance array at the crystal pins. The offset register is added to the capacitance array register under the following conditions: during a normal temperature conversion, if the temperature changes from the previous conversion, or during a manual user conversion (setting the CONV bit). To see the effects of the aging register on the 32kHz output frequency immediately, a manual conversion should be started after each aging register change.

Positive aging values add capacitance to the array, slowing the oscillator frequency. Negative values remove capacitance from the array, increasing the oscillator frequency.

The change in ppm per LSB is different at different temperatures. The frequency vs. temperature curve is shifted by the values used in this register. At +25°C, one LSB typically provides about 0.1ppm change in frequency.

Aging Offset (10h)

BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
Sign	Data	Data	Data	Data	Data	Data	Data

Temperature Register (Upper Byte) (11h)

BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
Sign	Data	Data	Data	Data	Data	Data	Data

Temperature Register (Lower Byte) (12h)

BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
Data	Data	0	0	0	0	0	0

Temperature Registers (11h–12h)

Temperature is represented as a 10-bit code with a resolution of +0.25°C and is accessible at location 11h and 12h. The temperature is encoded in two's complement format. The upper 8 bits are at location 11h and the lower 2 bits are in the upper nibble at location 12h. Upon power reset, the registers are set to a default temperature of 0°C and the controller starts a temperature conversion. New temperature readings are stored in this register.

I²C Serial Data Bus

The DS3231 supports a bidirectional I²C bus and data transmission protocol. A device that sends data onto the bus is defined as a transmitter and a device receiving data is defined as a receiver. The device that controls the message is called a master. The devices that are controlled by the master are slaves. The bus must be controlled by a master device that generates the serial clock (SCL), controls the bus access, and generates the START and STOP conditions. The DS3231 operates as a slave on the I²C bus. Connections to the bus are made through the SCL input and open-drain SDA I/O lines. Within the bus specifications, a standard mode (100kHz maximum clock rate) and a fast mode (400kHz maximum clock rate) are defined. The DS3231 works in both modes.

The following bus protocol has been defined (Figure 2):

- Data transfer may be initiated only when the bus is not busy.
- During data transfer, the data line must remain stable whenever the clock line is high. Changes in the data line while the clock line is high are interpreted as control signals.

Accordingly, the following bus conditions have been defined:

Bus not busy: Both data and clock lines remain high.

Start data transfer: A change in the state of the data line from high to low, while the clock line is high, defines a START condition.

Stop data transfer: A change in the state of the data line from low to high, while the clock line is high, defines a STOP condition.

Data valid: The state of the data line represents valid data when, after a START condition, the data line is stable for the duration of the high period of the clock signal. The data on the line must be changed during the low period of the clock signal. There is one clock pulse per bit of data.

Each data transfer is initiated with a START condition and terminated with a STOP condition. The number of data bytes transferred between the START and the STOP conditions is not limited, and is determined by the master device. The information is transferred byte-wise and each receiver acknowledges with a ninth bit.

Acknowledge: Each receiving device, when addressed, is obliged to generate an acknowledge after the reception of each byte. The master device must generate an extra clock pulse, which is associated with this acknowledge bit.

A device that acknowledges must pull down the SDA line during the acknowledge clock pulse in such a way that the SDA line is stable low during the high period of the acknowledge-related clock pulse. Of course, setup and hold times must be taken into account. A master must signal an end of data to the slave by not generating an acknowledge bit on the last byte that has been clocked out of the slave. In this case, the slave must leave the data line high to enable the master to generate the STOP condition.

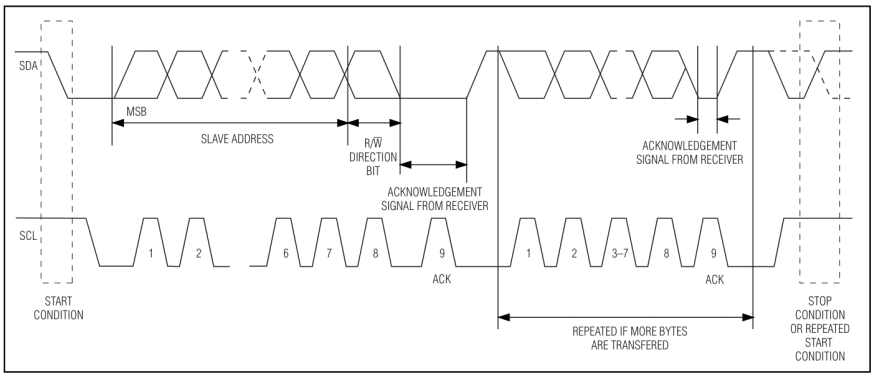


Figure 2. I²C Data Transfer Overview

Figures 3 and 4 detail how data transfer is accomplished on the I²C bus. Depending upon the state of the R/$\overline{W}$ bit, two types of data transfer are possible:

Data transfer from a master transmitter to a slave receiver. The first byte transmitted by the master is the slave address. Next follows a number of data bytes. The slave returns an acknowledge bit after each received byte. Data is transferred with the most significant bit (MSB) first.

Data transfer from a slave transmitter to a master receiver. The first byte (the slave address) is transmitted by the master. The slave then returns an acknowledge bit. Next follows a number of data bytes transmitted by the slave to the master. The master returns an acknowledge bit after all received bytes other than the last byte. At the end of the last received byte, a not acknowledge is returned.

The master device generates all the serial clock pulses and the START and STOP conditions. A transfer is ended with a STOP condition or with a repeated START condition. Since a repeated START condition is also the beginning of the next serial transfer, the bus will not be released. Data is transferred with the most significant bit (MSB) first.

The DS3231 can operate in the following two modes:

Slave receiver mode (DS3231 write mode): Serial data and clock are received through SDA and SCL. After each byte is received, an acknowledge bit is transmitted. START and STOP conditions are recognized as the beginning and end of a serial transfer.

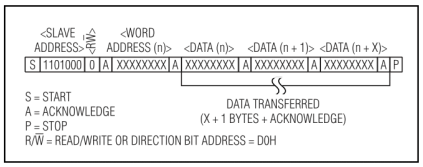


Figure 3. Slave Receiver Mode (Write Mode)

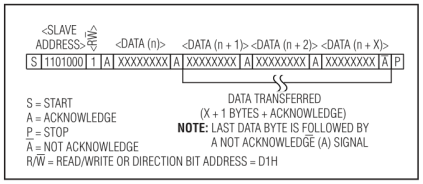


Figure 4. Slave Transmitter Mode (Read Mode)

Address recognition is performed by hardware after reception of the slave address and direction bit. The slave address byte is the first byte received after the master generates the START condition. The slave address byte contains the 7-bit DS3231 address, which is 1101000, followed by the direction bit (R/$\overline{W}$), which is 0 for a write. After receiving and decoding the slave address byte, the DS3231 outputs an

acknowledge on SDA. After the DS3231 acknowledges the slave address + write bit, the master transmits a word address to the DS3231. This sets the register pointer on the DS3231, with the DS3231 acknowledging the transfer. The master may then transmit zero or more bytes of data, with the DS3231 acknowledging each byte received. The register pointer increments after each data byte is transferred. The master generates a STOP condition to terminate the data write.

Slave transmitter mode (DS3231 read mode): The first byte is received and handled as in the slave receiver mode. However, in this mode, the direction bit indicates that the transfer direction is reversed. Serial data is transmitted on SDA by the DS3231 while the serial clock is input on SCL. START and STOP conditions are recognized as the beginning and end of a serial transfer. Address recognition is performed by hardware after reception of the slave address and direction bit. The slave address byte is the first byte received after the master generates a START condition. The slave address byte contains the 7-bit DS3231 address, which is 1101000, followed by the direction bit (R/$\overline{W}$), which is 1 for a read. After receiving and decoding the slave address byte, the DS3231 outputs an acknowledge on SDA. The DS3231 then begins to transmit data starting with the register address pointed to by the register pointer. If the register pointer is not written to before the initiation of a read mode, the first address that is read is the last one stored in the register pointer. The DS3231 must receive a not acknowledge to end a read.

Handling, PC Board Layout, and Assembly

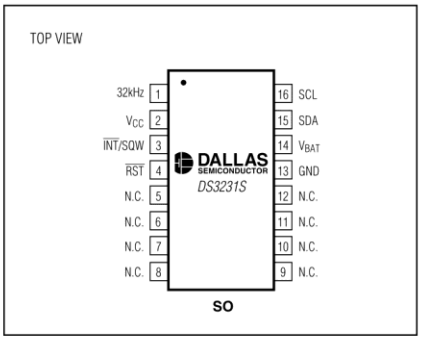
The DS3231 package contains a quartz tuning-fork crystal. Pick-and-place equipment can be used, but precautions should be taken to ensure that excessive shocks are avoided. Ultrasonic cleaning should be avoided to prevent damage to the crystal.

Avoid running signal traces under the package, unless a ground plane is placed between the package and the signal line. All N.C. (no connect) pins must be connected to ground.

Moisture-sensitive packages are shipped from the factory dry packed. Handling instructions listed on the package label must be followed to prevent damage during reflow. See IPC/JEDEC J-STD-020 standard for moisture-sensitive device (MSD) classifications and reflow profiles. Exposure to reflow is limited to 2 times maximum.

Extremely Accurate I²C-Integrated RTC/TCXO/Crystal

Pin Configuration



Chip Information

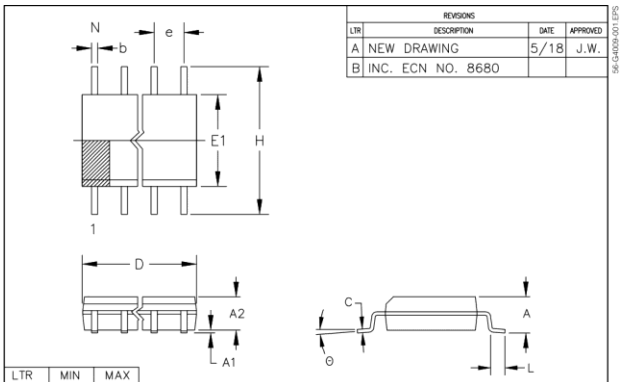
TRANSISTOR COUNT: 33,000
SUBSTRATE CONNECTED TO GROUND
PROCESS: CMOS

Thermal Information

Theta-JA: +73°C/W
Theta-JC: +23°C/W

Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/DallasPackInfo**).



REVISIONS			
LTR	DESCRIPTION	DATE	APPROVED
A	NEW DRAWING	5/18	J.W.
B	INC. ECN NO. 8680		

56-G4009-001.EPS

LTR		MIN	MAX
A	IN.	0.094	0.105
	MM	2.39	2.67
A1	IN.	0.004	0.012
	MM	0.102	0.30
A2	IN.	0.089	0.095
	MM	2.26	2.41
b	IN.	0.013	0.020
	MM	0.33	0.51
C	IN.	0.009	0.013
	MM	0.229	0.33
D	IN.	———	
	MM	———	
e	IN.	.050 BSC	
	MM	1.27 BSC	
E1	IN.	0.290	0.300
	MM	7.37	7.62
H	IN.	0.398	0.416
	MM	10.11	10.57
L	IN.	0.016	0.040
	MM	0.40	1.02
Θ		0°	8°

D	16 PIN MIN	16 PIN MAX	18 PIN MIN	18 PIN MAX	20 PIN MIN	20 PIN MAX	24 PIN MIN	24 PIN MAX	28 PIN MIN	28 PIN MAX
IN.	0.398	0.412	0.448	0.462	0.498	0.511	0.598	0.612	0.698	0.712
MM	10.11	10.46	11.38	11.73	12.65	12.99	15.19	15.54	17.73	18.08

THE CHAMFER ON THE BODY IS OPTIONAL.
IF IT IS NOT PRESENT, A TERMINAL 1 IDENTIFIER
MUST BE POSITIONED SO THAT 1/2 OR MORE OF
IT'S AREA IS CONTAINED IN THE HATCHED ZONE.

SIGNATURE		DATE
DOC. CONTROL:	J.WILKINS	5/94
ENGR. MGR:	B.W.MCARTY	5/94
MFG. ENGR:	C.M.SELLS	5/94
CHECKED BY:	C.M.SELLS	5/94
DRAWN BY:	M.W.C.	5/94
DO NOT SCALE DWG.		

DALLAS SEMICONDUCTOR MAXIM

TITLE: PACKAGE OUTLINE .300" SOIC 16,18,20,24&28 LD.

SIZE	FSCM NO	PART NO.	REV
A		56-G4009-001	B

SCALE N/A — SHEET 1 OF 1

Extremely Accurate I²C-Integrated RTC/TCXO/Crystal

Revision History

Rev 0; 1/05:	Initial data sheet release.
Rev 1; 2/05:	(pages 1, 3) Changed Digital Temp Sensor Output from ±2°C to ±3°C (page 1) Updated *Typical Operating Circuit* (pages 2, 3, 4) Changed T_A = -40°C to +85°C to T_A = T_{MIN} to T_{MAX}. (page 8) Updated *Block Diagram.*
Rev 2; 6/05:	(page 1) Added "UL Recognized" to *Features*; added lead-free packages and removed S from top mark info in *Ordering Information* table; added ground connections to the N.C. pin in the *Typical Operating Circuit.* (page 2) Added "noncondensing" to operating temperature range; changed V_{PF} MIN from 2.35V to 2.45V. (page 3) Added aging offset specification. (page 7) Relabeled TOC4. (page 8) Added arrow showing input on X1 in the *Block Diagram.* (page 9) Updated pin descriptions for V_{CC} and V_{BAT}. (page 10) Added the *I²C Interface* section. (page 11) *Figure 1*: Added sign bit to aging and temperature registers; added MSB and LSB. (page 13) Corrected title for rate select bits frequency table. (page 14) Added note that frequency stability over temperature spec is with aging offset register = 00h; changed bit 7 from Data to Sign (Crystal Aging Offset Register). (page 15) Changed bit 7 from Data to Sign (Temperature Register); correct pin definitions in *I²C Serial Data Bus* section. (page 17) Modified the *Handing, PC Board Layout, and Assembly* section to refer to J-STD-020 for reflow profiles for lead-free and leaded packages.
Rev 3; 11/05:	(page 1) Changed lead-free packages to RoHS-compliant packages.
Rev 4; 10/06:	(page 1) Changed $\overline{RST}$ and UL bullets in *Features.* (pages 2, 3) Changed EC condition "V_{CC} > V_{BAT}" to "V_{CC} = Active Supply (see Table 1)." (page 6) Modified Note 12 to correct t_{REC} operation. (page 7) Added various conditions text to TOCs 1, 2, and 3. (page 9) Added text to pin descriptions for 32kHz, V_{CC}, and $\overline{RST}$. (page 10) Table 1: Changed column heading "Powered By" to "Active Supply"; changed "applied" to "exceeds V_{PF}" in the *Power Control* section. (page 13) Indicated BBSQW applies to both SQW and interrupts; simplified temp convert description (bit 5); added "output" to $\overline{INT}$/SQW (bit 2). (page 14) Changed the *Crystal Aging* section to the *Aging Offset* section; changed "this bit indicates" to "this bit controls" for the enable 32kHz output bit.

Lampiran 9. *Datasheet* Relay

SONGLE RELAY

松乐继电器 ® SONGLE RELAY	RELAY ISO9002	SRD

1. MAIN FEATURES

- ☐ Switching capacity available by 10A in spite of small size design for highdensity P.C. board mounting technique.
- ☐ UL,CUL,TUV recognized.
- ☐ Selection of plastic material for high temperature and better chemical solution performance.
- ☐ Sealed types available.
- ☐ Simple relay magnetic circuit to meet low cost of mass production.

2. APPLICATIONS

☐ Domestic appliance, office machine, audio, equipment, automobile, etc.
(Remote control TV receiver, monitor display, audio equipment high rushing current use application.)

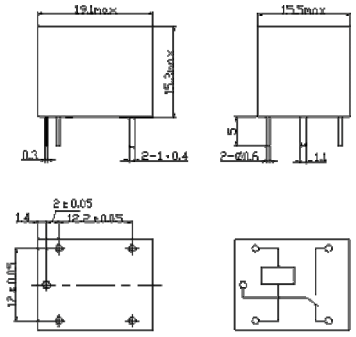
3. ORDERING INFORMATION

SRD	XX VDC	S	L	C
Model of relay	Nominal coil voltage	Structure	Coil	Contact form
SRD	03|05|06|09|12|24|48VDC	S:Sealed type	L:0.36W	A:1 form A
				B:1 form B
		F:Flux free type	D:0.45W	C:1 form C

4. RATING

CCC	FILE NUMBER:CQC03001003729	7A/240VDC
CCC	FILE NUMBER:CQC03001003731	10A/250VDC
UL /CUL	FILE NUMBER: E167996	10A/125VAC 28VDC
TUV	FILE NUMBER: R50056114	10A/250VAC 30VDC

5. DIMENSION(unit:mm) DRILLING(unit:mm) WIRING DIAGRAM



6. COIL DATA CHART (AT20 ° C)

Coil Sensitivity	Coil Voltage Code	Nominal Voltage (VDC)	Nominal Current (mA)	Coil Resistance (Ω) ☐ 10%	Power Consumption (W)	Pull-In Voltage (VDC)	Drop-Out Voltage (VDC)	Max-Allowable Voltage (VDC)
SRD (High Sensitivity)	03	03	120	25	abt. 0.36W	75%Max.	10% Min.	120%
	05	05	71.4	70				
	06	06	60	100				
	09	09	40	225				
	12	12	30	400				
	24	24	15	1600				
	48	48	7.5	6400				
SRD (Standard)	03	03	150	20	abt. 0.45W	75% Max.	10% Min.	110%
	05	05	89.3	55				
	06	06	75	80				
	09	09	50	180				
	12	12	37.5	320				
	24	24	18.7	1280				
	48	48	10	4500	abt. 0.51W			

7. CONTACT RATING

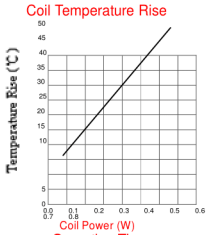
Item \ Type	FORM C	FORM A
Contact Capacity	7A 30VDC	10A 30VDC
Resistive Load (cosΦ=1)	10A 125VAC	10A 240VAC
Inductive Load (cosΦ=0.4 L/R=7msec)	10A 250VAC	5A 120VAC 5A 28VDC
	3A 120VAC 3A 28VDC	
Max. Allowable Voltage	250VAC/110VDC	250VAC/110VDC
Max. Allowable Power Force	800VAC/240W	1200VA/300W
Contact Material	AgCdO	AgCdO

8. PERFORMANCE (at initial value)

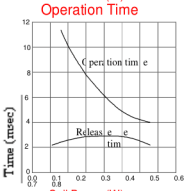
Item \ Type	SRD
Contact Resistance	100mΩ Max.
Operation Time	10msec Max.
Release Time	5msec Max.
Dielectric Strength	
Between coil & contact	1500VAC 50/60HZ (1 minute)
Between contacts	1000VAC 50/60HZ (1 minute)
Insulation Resistance	100 MΩ Min. (500VDC)
Max. ON/OFF Switching	
Mechanically	300 operation/min
Electrically	30 operation/min
Ambient Temperature	-25 ☐C to +70 C
Operating Humidity	45 to 85% RH
Vibration	
Endurance	10 to 55Hz Double Amplitude 1.5mm
Error Operation	10 to 55Hz Double Amplitude 1.5mm
Shock	
Endurance	100G Min.
Error Operation	10G Min.
Life Expectancy	
Mechanically	10^7 operations. Min. (no load)
Electrically	10^5 operations. Min. (at rated coil voltage)
Weight	abt. 10grs.

9.REFERENCE DATA

Coil Temperature Rise

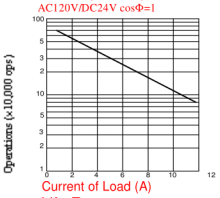


Operation Time

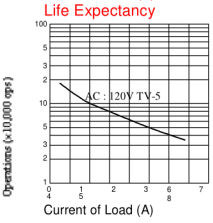


Life Expectancy

AC120V/DC24V cosΦ=1



Life Expectancy

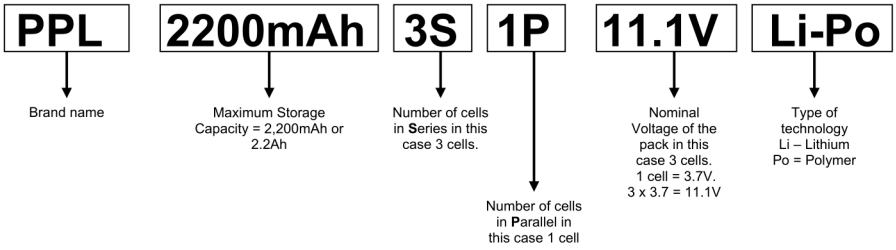


Lampiran 10. *Datasheet* Bateray Lippo

What The Numbers Mean with Regards to LiPo cells

This is just a brief explanation as to what the numbers mean on Lithium Polymer cells

Example: 2,200mAh 3S1P 11.1V Li-Po



PPL - Brand Name/Part Number
Not much I can say about this except it's a Brand Name/Part Number.

2,200mAh - Maximum Storage Capacity
The amount of energy a battery can store is measured in milli Amp Hours or shortened to "mAh"
In this instance this battery could supply 2,200mA for 1 hour. 2,200mAh is the same as 2.2Ah.
This figure of 2,200mAh is important as we use it to work out the charge current and the maximum current we can safely draw from this size of battery.

3S – Number of cells in Series
This is also very important as it determines the voltage of the battery. The nominal voltage of a single LiPo cell is 3.70V. Therefore 3 cells in Series is equal to 3 x 3.70V = 11.1V. More cells in series equals higher voltage. Voltage is important in electric flight as brushless motors have a RPM per volt figure. The higher the voltage, the higher the RPM which means more power. The down side of more voltage is that more cells are required therefore more weight. Most ESC's (Electronic Speed Controllers) can only be used on 2S or 3S battery packs. Some ESC's will work on 4S but then the BEC (Battery Eliminator Circuit) is no longer usable and a separate battery will have to be used to power the receiver and servos.
ESC's that are designed to work on 5S – 15S will not have any BEC. See below for a more detailed description of what a BEC does.

October 2006 Rev3.

1P – Number of cells in Parallel
For us in the UK this figure is not important as batteries are referred to the maximum TOTAL storage capacity of the WHOLE pack.
In USA some manufactures refer to the storage capacity per CELL and not as the whole pack.
Example: UK = 5S2P 5,000mAh, Some USA manufactures might call this identical pack a 5S2P 2,500mAh.
They are identical packs with the same voltage and storage capacity, just with different markings, so check and double check.

11.1V – Nominal Voltage of the battery pack
The nominal voltage of 1 LiPo cell is 3.70V
The maximum voltage of 1 LiPo cell is 4.20V (absolute maximum is 4.25V)
The minimum voltage of 1 LiPo Cell is 3.30V - no load (absolute minimum is 3.00V per cell – no load)
Battery packs are always referenced to the nominal voltage. In this particular example this battery pack has 3 cells in Series therefore the nominal voltage is 3 x 3.7V = 11.1V

Li-Po
Li-Po is indicating that this battery is a Lithium Polymer battery

20C Continuous
This is referring to the maximum continuous current that can be drawn from this battery safely without **immediately** destroying the battery pack.
C is the maximum storage capacity of the battery in this case 2,200mAh or 2.2Ah. As this is a 20C pack therefore the maximum continuous current is….
20 times the maximum storage capacity (20 x 2,200 = 44,000mAh or 44Ah).
If every discharge is done at 44Amps then this battery will only last 20-50 cycles.
A good maximum current to aim for is 60% of the maximum continuous rating in this example 60% of 44A is 26.4A. This will greatly extend the life of your expensive LiPo's.

30C Sustained
This is referring to the maximum current that can be drawn from this battery safely without immediately destroying the battery pack for a maximum period of 30 seconds in one discharge cycle.

40C Peak or Burst
This is referring to the maximum current that can be drawn from this battery safely without immediately destroying the battery pack for a maximum period of 10 seconds in one discharge cycle.

BEC
BEC is short for **B**attery **E**liminator **C**ircuit.
The BEC part of an ESC or Electronic Speed Controller is completely separate from the circuitry which controls the speed of your electric motor.
Contrary to popular belief it does **NOT** cut power to the motor when the battery voltage drops below a set level. Other circuitry within your ESC controls this function.
The BEC's only job is to supply the receiver and servos with power that it converts down from the battery that supplies your motor, eliminating the need for a separate battery to power your receiver and servos.
Hence the name, Battery Eliminator Circuit.
Your ESC may or may not have a BEC built in. It's best to check before hand to make sure and also check the maximum number of servos it can supply to ensure you are not going to blow the BEC which would cause a loss of power to your receiver and servos which in turn would cause an expensive crash. If you don't want to trust your expensive model to a BEC then fit a separate receiver battery.

October 2006 Rev3.

Charging Current
Current LiPo technology does not allow for charging currents to exceed 1C. C = Capacity of battery.
In this example the battery's capacity is 2,200mAh or 2.2Ah.
Therefore 1C = 1 x 2,200mAh = 2,200mAh or 2.2Ah.
To extend the life of your battery only charge at 0.8C. Therefore 0.8 x 2,200mAh = 1,760mA or 1.76A.

Some manufactures are claiming that you can charge their cells at up to 2.5C.
Yes, you can charge them at 2.5C safely….. BUT…… you will reduce the number of cycles you get out of them.

If you only charge your cells to 95% of their capacity i.e. 4.15V per cell (12.45V for a 3S pack) instead of the 4.2V per cell (12.6V for a 3S pack) not only will this will extend the life of your cells but it will also cut down your charge time by about 15-20 minutes.

George Worley

October 2006 Rev3.